QPro Virtex-E 1.8V QML High-Reliability FPGAs

DS098-1 (v1.1) July 29, 2004

Advance Product Specification

Features

- Certified to MIL-PRF-38535 (Qualified Manufacturer Listing)
- Guaranteed over the full military temperature range (–55°C to +125°C)
- Ceramic and Plastic Packages
- Fast, High-Density 1.8V FPGA Family
  - Densities from 600K to 2M system gates
  - 130 MHz internal performance (four LUT levels)
  - Designed for low-power operation
  - PCI compliant 3.3V, 32-bit, 33 MHz
- Highly Flexible SelectIO™+ Technology
  - Supports 20 high-performance interface standards
  - Up to 804 singled-ended I/Os or 344 differential I/O pairs for an aggregate bandwidth of > 100 Gb/s
- Differential Signalling Support
  - LVDS (622 Mb/s), BLVDS (Bus LVDS), LVPECL
  - Differential I/O signals can be input, output, or I/O
  - Compatible with standard differential devices
  - LVPECL and LVDS clock inputs for 300+ MHz clocks
- Proprietary High-Performance SelectLink Technology
  - Double Data Rate (DDR) to Virtex™-E link
  - Web-based HDL generation methodology
- Sophisticated SelectRAM+™ Memory Hierarchy
  - 600 Kb of internal configurable distributed RAM
  - Up to 640 Kb of synchronous internal block RAM
  - Dual port block RAM capability
  - Memory bandwidth up to 1.66 Tb/s (equivalent bandwidth of over 100 RAMBUS channels)
  - Designed for high-performance Interfaces to External Memories
  - 200 MHz ZBT* SRAMs
  - 200 Mb/s DDR SDRAMs
  - Supported by free Synthesizable reference design
- High-Performance Built-In Clock Management Circuitry
  - Eight fully digital Delay-Locked Loops (DLLs)
  - Digitally-Synthesized 50% duty cycle for Double Data Rate (DDR) Applications
  - Clock Multiply and Divide
  - Zero-delay conversion of high-speed LVPECL/LVDS clocks to any I/O standard
- Flexible Architecture Balances Speed and Density
  - Dedicated carry logic for high-speed arithmetic
  - Dedicated multiplier support
  - Cascade chain for wide-input function
  - Abundant registers/latches with clock enable, and dual synchronous/asynchronous set and reset
  - Internal 3-state bussing
  - IEEE 1149.1 boundary-scan logic
  - Die-temperature sensor diode
- Supported by Xilinx Foundation™ and Alliance Series™ Development Systems
  - Further compile time reduction of 50%
  - Internet Team Design (ITD) tool ideal for million-plus gate density designs
  - Wide selection of PC and workstation platforms
- SRAM-Based In-System Configuration
  - Unlimited reprogrammability
- Advanced Packaging Options
  - 1.0 mm BGA
  - 1.27 mm BGA
- 0.18 µm 6-Layer Metal Process
- 100% Factory Tested
- 100% Factory Tested

* ZBT is a trademark of Integrated Device Technology, Inc.

Table 1: **Virtex-E Field-Programmable Gate Array Family Members**

Device	System Gates	Logic Gates	CLB Array	Logic Cells	Differential I/O Pairs	User I/O	Block RAM Bits	Distributed RAM Bits
XQV600E	985,882	186,624	48 x 72	15,552	247	316	294,912	221,184
XQV1000E	1,569,178	331,776	64 x 96	27,648	281	404	393,216	393,216
XQV2000E	2,541,952	518,400	80 x 120	43,200	344	804	655,360	614,400

Virtex-E Compared to Virtex Devices

The Virtex-E family offers up to 43,200 logic cells in devices up to 30% faster than the Virtex family.

I/O performance is increased to 622 Mb/s using Source Synchronous data transmission architectures and synchronous system performance up to 240 MHz using singled-ended SelectIO technology. Additional I/O standards are supported, notably LVPECL, LVDS, and BLVDS, which use two pins per signal. Almost all signal pins can be used for these new standards.

Virtex-E devices have up to 640 Kb of faster (250 MHz) block SelectRAM, but the individual RAMs are the same size and structure as in the Virtex family. They also have eight DLLs instead of the four in Virtex devices. Each individual DLL is slightly improved with easier clock mirroring and 4x frequency multiplication.

V_{CCINT}, the supply voltage for the internal logic and memory, is 1.8V, instead of 2.5V for Virtex devices. Advanced processing and 0.18 µm design rules have resulted in smaller dice, faster speed, and lower power consumption.

I/O pins are 3V tolerant, and can be 5V tolerant with an external 100Ω resistor. PCI 5V is not supported. With the addition of appropriate external resistors, any pin can tolerate any voltage desired.

Banking rules are different. With Virtex devices, all input buffers are powered by V_{CCINT}. With Virtex-E devices, the LVTTL, LVCMOS2, and PCI input buffers are powered by the I/O supply voltage V_{CCO}.

The Virtex-E family is not bitstream-compatible with the Virtex family, but Virtex designs can be compiled into equivalent Virtex-E devices.

The same device in the same package for the Virtex-E and Virtex families are pin-compatible with some minor exceptions. See the data sheet pinout section for details.

General Description

The Virtex-E FPGA family delivers high-performance, high-capacity programmable logic solutions. Dramatic increases in silicon efficiency result from optimizing the new architecture for place-and-route efficiency and exploiting an aggressive 6-layer metal 0.18 µm CMOS process. These advances make Virtex-E FPGAs powerful and flexible alternatives to mask-programmed gate arrays. The QPro Virtex-E family includes the three members in Table 1.

Building on experience gained from Virtex FPGAs, the Virtex-E family is an evolutionary step forward in programmable logic design. Combining a wide variety of programmable system features, a rich hierarchy of fast, flexible interconnect resources, and advanced process technology, the Virtex-E family delivers a high-speed and high-capacity programmable logic solution that enhances design flexibility while reducing time-to-market.

Virtex-E Architecture

Virtex-E devices feature a flexible, regular architecture that comprises an array of configurable logic blocks (CLBs) surrounded by programmable input/output blocks (IOBs), all interconnected by a rich hierarchy of fast, versatile routing resources. The abundance of routing resources permits the Virtex-E family to accommodate even the largest and most complex designs.

Virtex-E FPGAs are SRAM-based, and are customized by loading configuration data into internal memory cells. Configuration data can be read from an external SPROM (master serial mode), or can be written into the FPGA (SelectMAP™, slave serial, and JTAG modes).

The standard Xilinx Foundation Series and Alliance Series Development systems deliver complete design support for Virtex-E, covering every aspect from behavioral and schematic entry, through simulation, automatic design translation and implementation, to the creation and downloading of a configuration bit stream.

Higher Performance

Virtex-E devices provide better performance than previous generations of FPGAs. Designs can achieve synchronous system clock rates up to 240 MHz including I/O or 622 Mb/s using Source Synchronous data transmission architechtures. Virtex-E I/Os comply fully with 3.3V PCI specifications, and interfaces can be implemented that operate at 33 MHz or 66 MHz.

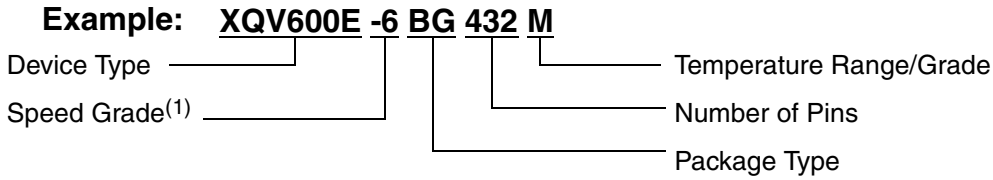
While performance is design-dependent, many designs operate internally at speeds in excess of 133 MHz and can achieve over 311 MHz.

Virtex-E Device/Package Combinations and Maximum I/O

Table 2: **Maximum User I/O by Device/Package (Excluding Dedicated Clock Pins)**

	XQV600E	XQV1000E	XQV2000E
BG432	316	-	-
BG560	-	404	404
CG560	-	404	-
FG1156	-	-	804

Virtex-E Ordering Information



Device Ordering Options

Device Type
XQV600E
XQV1000E
XQV2000E

Package	
BG432	432-ball Plastic BGA Package
BG560	560-ball Plastic BGA Package
FG1156	1156-ball Plastic Fine Pitch BGA Package
CG560	560-column Ceramic Column Grid Package

Grade		Temperature
M	Military Ceramic	T_C = –55°C to +125°C
N	Military Plastic	T_J = –55°C to +125°C

Notes:
1. -6 only supported speed grade.

Valid Ordering Combinations

M Grade
XQV1000E-6CG560M

N Grade
XQV600E-6BG432N
XQV1000E-6BG560N
XQV2000E-6BG560N
XQV2000E-6FG1156N

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
05/19/03	1.0	Initial Xilinx release.
07/29/04	1.1	• Device/Package Availability and Ordering Information tables on page 3: Removed references to devices in CB228 and HQ240 packages (not offered). • Device Ordering Options table on page 3: Removed Footnote (2) referring to Class Q order codes (not offered). • Table 1: Corrected number of available User I/Os to conform to numbers in Table 2.

Architectural Description

Virtex-E Array

The Virtex™-E user-programmable gate array, shown in Figure 1, comprises two major configurable elements: configurable logic blocks (CLBs) and input/output blocks (IOBs).

- CLBs provide the functional elements for constructing logic
- IOBs provide the interface between the package pins and the CLBs

CLBs interconnect through a general routing matrix (GRM). The GRM comprises an array of routing switches located at the intersections of horizontal and vertical routing channels. Each CLB nests into a VersaBlock that also provides local routing resources to connect the CLB to the GRM.

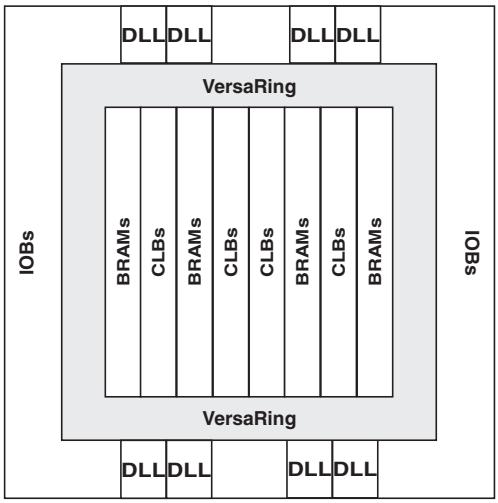


Figure 1: **Virtex-E Architecture Overview**

The VersaRing™ I/O interface provides additional routing resources around the periphery of the device. This routing improves I/O routability and facilitates pin locking.

The Virtex-E architecture also includes the following circuits that connect to the GRM.

- Dedicated block memories of 4096 bits each
- Clock DLLs for clock-distribution delay compensation and clock domain control
- 3-State buffers (BUFTs) associated with each CLB that drive dedicated segmentable horizontal routing resources

Values stored in static memory cells control the configurable logic elements and interconnect resources. These values load into the memory cells on power-up, and can reload if necessary to change the function of the device.

Input/Output Block

The Virtex-E IOB, Figure 2, features SelectIO™+ inputs and outputs that support a wide variety of I/O signalling standards, see Table 1.

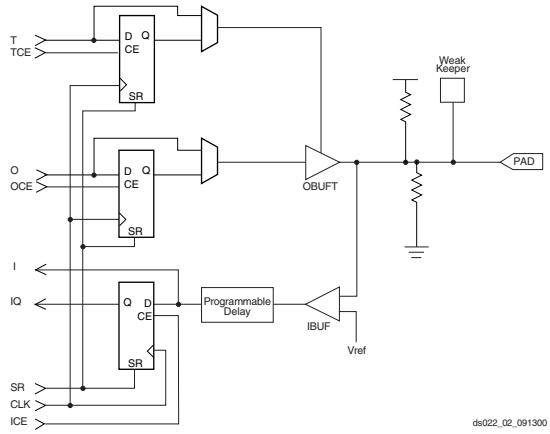


Figure 2: **Virtex-E Input/Output Block (IOB)**

The three IOB storage elements function either as edge-triggered D-type flip-flops or as level-sensitive latches. Each IOB has a clock signal (CLK) shared by the three flip-flops and independent clock enable signals for each flip-flop.

In addition to the CLK and CE control signals, the three flip-flops share a Set/Reset (SR). For each flip-flop, this signal can be independently configured as a synchronous Set, a synchronous Reset, an asynchronous Preset, or an asynchronous Clear.

The output buffer and all of the IOB control signals have independent polarity controls.

All pads are protected against damage from electrostatic discharge (ESD) and from over-voltage transients. After configuration, clamping diodes are connected to V_{CCO} with the exception of LVCMOS18, LVCMOS25, GTL, GTL+, LVDS, and LVPECL.

Table 1: **Supported I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTL	3.3	3.3	N/A	N/A
LVCMOS2	2.5	2.5	N/A	N/A
LVCMOS18	1.8	1.8	N/A	N/A
SSTL3 I & II	3.3	N/A	1.50	1.50
SSTL2 I & II	2.5	N/A	1.25	1.25
GTL	N/A	N/A	0.80	1.20
GTL+	N/A	N/A	1.0	1.50
HSTL I	1.5	N/A	0.75	0.75
HSTL III & IV	1.5	N/A	0.90	1.50
CTT	3.3	N/A	1.50	1.50
AGP-2X	3.3	N/A	1.32	N/A
PCI33_3	3.3	3.3	N/A	N/A
PCI66_3	3.3	3.3	N/A	N/A
BLVDS & LVDS	2.5	N/A	N/A	N/A
LVPECL	3.3	N/A	N/A	N/A

Optional pull-up, pull-down and weak-keeper circuits are attached to each pad. Prior to configuration all outputs not involved in configuration are forced into their high-impedance state. The pull-down resistors and the weak-keeper circuits are inactive, but I/Os can optionally be pulled up.

The activation of pull-up resistors prior to configuration is controlled on a global basis by the configuration mode pins. If the pull-up resistors are not activated, all the pins are in a high-impedance state. Consequently, external pull-up or pull-down resistors must be provided on pins required to be at a well-defined logic level prior to configuration.

All Virtex-E IOBs support IEEE 1149.1-compatible boundary scan testing.

Input Path

The Virtex-E IOB input path routes the input signal directly to internal logic and/ or through an optional input flip-flop.

An optional delay element at the D-input of this flip-flop eliminates pad-to-pad hold time. The delay is matched to the internal clock-distribution delay of the FPGA, and when used, assures that the pad-to-pad hold time is zero.

Each input buffer can be configured to conform to any of the low-voltage signalling standards supported. In some of these standards the input buffer utilizes a user-supplied threshold voltage, V_{REF}. The need to supply V_{REF} imposes constraints on which standards can be used in close proximity to each other. See "I/O Banking" on page 2.

There are optional pull-up and pull-down resistors at each user I/O input for use after configuration. Their value is in the range 50-100 kΩ.

Output Path

The output path includes a 3-state output buffer that drives the output signal onto the pad. The output signal can be routed to the buffer directly from the internal logic or through an optional IOB output flip-flop.

The 3-state control of the output can also be routed directly from the internal logic or through a flip-flip that provides synchronous enable and disable.

Each output driver can be individually programmed for a wide range of low-voltage signalling standards. Each output buffer can source up to 24 mA and sink up to 48 mA. Drive strength and slew rate controls minimize bus transients.

In most signalling standards, the output High voltage depends on an externally supplied V_{CCO} voltage. The need to supply V_{CCO} imposes constraints on which standards can be used in close proximity to each other. See "I/O Banking" on page 2.

An optional weak-keeper circuit is connected to each output. When selected, the circuit monitors the voltage on the pad and weakly drives the pin High or Low to match the input signal. If the pin is connected to a multiple-source signal, the weak keeper holds the signal in its last state if all drivers are disabled. Maintaining a valid logic level in this way eliminates bus chatter.

Since the weak-keeper circuit uses the IOB input buffer to monitor the input level, an appropriate V_{REF} voltage must be provided if the signalling standard requires one. The provision of this voltage must comply with the I/O banking rules.

I/O Banking

Some of the I/O standards described above require V_{CCO} and/or V_{REF} voltages. These voltages are externally supplied and connected to device pins that serve groups of IOBs, called banks. Consequently, restrictions exist about which I/O standards can be combined within a given bank.

Eight I/O banks result from separating each edge of the FPGA into two banks, as shown in Figure 3. Each bank has multiple V_{CCO} pins, all of which must be connected to the same voltage. This voltage is determined by the output standards in use.

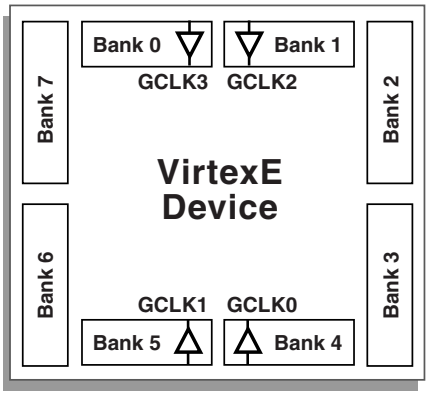


Figure 3: **Virtex-E I/O Banks**

Within a bank, output standards can be mixed only if they use the same V_{CCO}. Compatible standards are shown in Table 2. GTL and GTL+ appear under all voltages because their open-drain outputs do not depend on V_{CCO}.

Table 2: **Compatible Output Standards**

V_{CCO}	Compatible Standards
3.3V	PCI, LVTTL, SSTL3 I, SSTL3 II, CTT, AGP, GTL, GTL+, LVPECL
2.5V	SSTL2 I, SSTL2 II, LVCMOS2, GTL, GTL+, BLVDS, LVDS
1.8V	LVCMOS18, GTL, GTL+
1.5V	HSTL I, HSTL III, HSTL IV, GTL, GTL+

Some input standards require a user-supplied threshold voltage, V_{REF}. In this case, certain user-I/O pins are automatically configured as inputs for the V_{REF} voltage. Approximately one in six of the I/O pins in the bank assume this role.

The V_{REF} pins within a bank are interconnected internally and consequently only one V_{REF} voltage can be used within each bank. All V_{REF} pins in the bank, however, must be connected to the external voltage source for correct operation.

Within a bank, inputs that require V_{REF} can be mixed with those that do not. However, only one V_{REF} voltage can be used within a bank.

In Virtex-E, input buffers with LVTTL, LVCMOS2, LVCMOS18, PCI33_3, PCI66_3 standards are supplied by V_{CCO} rather than V_{CCINT}. For these standards, only input and output buffers that have the same V_{CCO} can be mixed together.

The V_{CCO} and V_{REF} pins for each bank appear in the device pin-out tables and diagrams. The diagrams also show the bank affiliation of each I/O.

Within a given package, the number of V_{REF} and V_{CCO} pins can vary depending on the size of device. In larger devices, more I/O pins convert to V_{REF} pins. Since these are always a super set of the V_{REF} pins used for smaller devices, it is possible to design a PCB that permits migration to a larger device if necessary. All the V_{REF} pins for the largest device anticipated must be connected to the V_{REF} voltage, and not used for I/O.

In smaller devices, some V_{CCO} pins used in larger devices do not connect within the package. These unconnected pins can be left unconnected externally, or can be connected to the V_{CCO} voltage to permit migration to a larger device if necessary.

Configurable Logic Blocks

The basic building block of the Virtex-E CLB is the logic cell (LC). An LC includes a 4-input function generator, carry logic, and a storage element. The output from the function generator in each LC drives both the CLB output and the D input of the flip-flop. Each Virtex-E CLB contains four LCs, organized in two similar slices, as shown in Figure 4. Figure 5 shows a more detailed view of a single slice.

In addition to the four basic LCs, the Virtex-E CLB contains logic that combines function generators to provide functions of five or six inputs. Consequently, when estimating the number of system gates provided by a given device, each CLB counts as 4.5 LCs.

Look-Up Tables

Virtex-E function generators are implemented as 4-input look-up tables (LUTs). In addition to operating as a function generator, each LUT can provide a 16 x 1-bit synchronous RAM. Furthermore, the two LUTs within a slice can be combined to create a 16 x 2-bit or 32 x 1-bit synchronous RAM, or a 16 x 1-bit dual-port synchronous RAM.

The Virtex-E LUT can also provide a 16-bit shift register that is ideal for capturing high-speed or burst-mode data. This mode can also be used to store data in applications such as Digital Signal Processing.

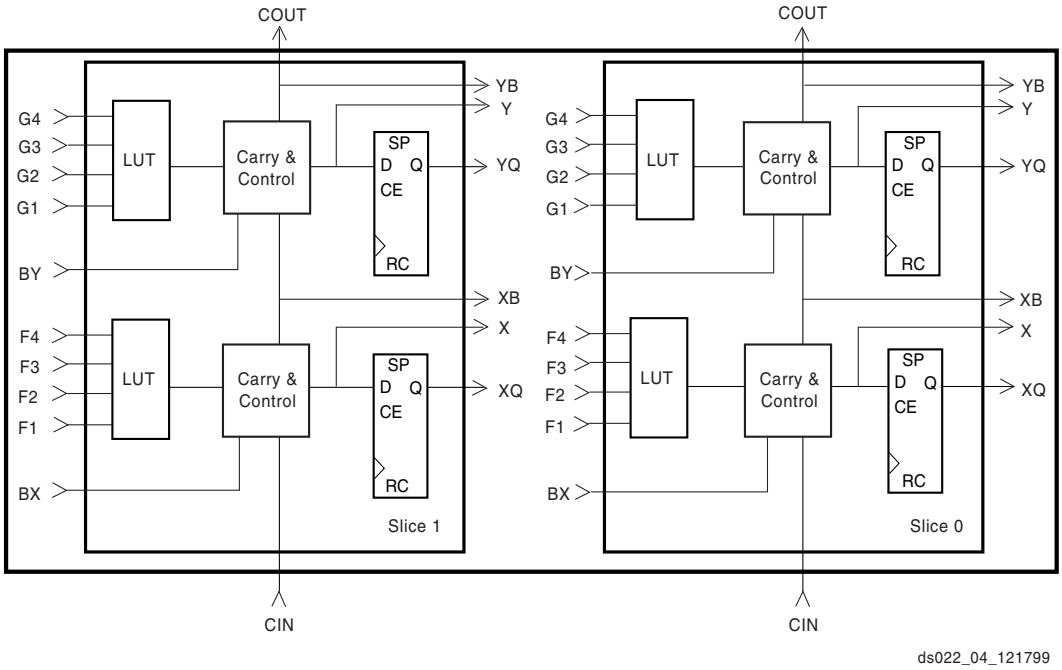


Figure 4: **2-Slice Virtex-E CLB**

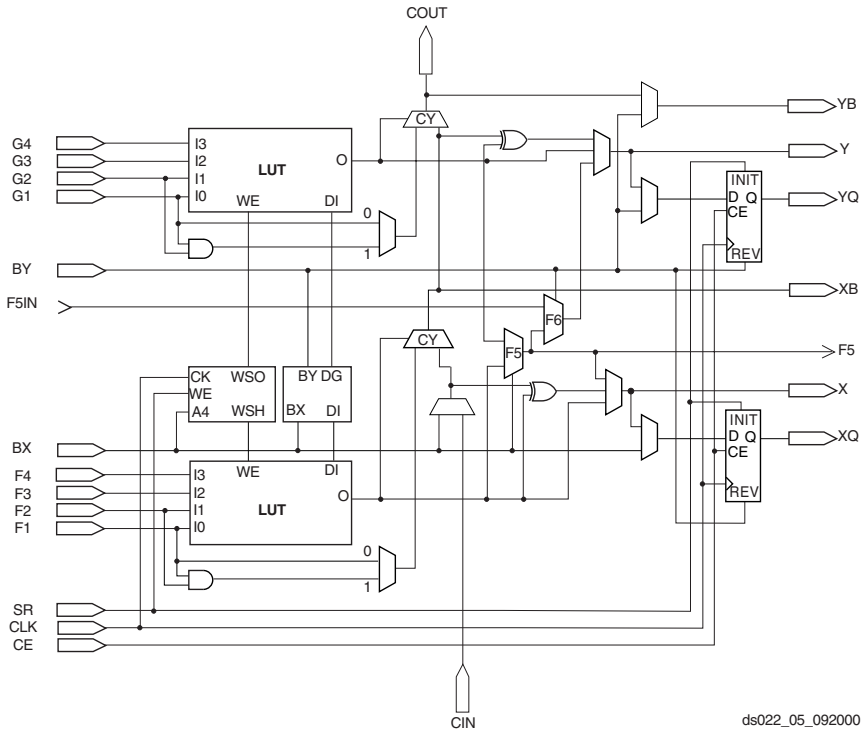


Figure 5: **Detailed View of Virtex-E Slice**

Storage Elements

The storage elements in the Virtex-E slice can be configured either as edge-triggered D-type flip-flops or as level-sensitive latches. The D inputs can be driven either by the function generators within the slice or directly from slice inputs, bypassing the function generators.

In addition to Clock and Clock Enable signals, each Slice has synchronous set and reset signals (SR and BY). SR

forces a storage element into the initialization state specified for it in the configuration. BY forces it into the opposite state. Alternatively, these signals can be configured to operate asynchronously. All of the control signals are independently invertible, and are shared by the two flip-flops within the slice.

Additional Logic

The F5 multiplexer in each slice combines the function generator outputs. This combination provides either a function generator that can implement any 5-input function, a 4:1 multiplexer, or selected functions of up to nine inputs.

Similarly, the F6 multiplexer combines the outputs of all four function generators in the CLB by selecting one of the F5-multiplexer outputs. This permits the implementation of any 6-input function, an 8:1 multiplexer, or selected functions of up to 19 inputs.

Each CLB has four direct feedthrough paths, two per slice. These paths provide extra data input lines or additional local routing that does not consume logic resources.

Arithmetic Logic

Dedicated carry logic provides fast arithmetic carry capability for high-speed arithmetic functions. The Virtex-E CLB supports two separate carry chains, one per Slice. The height of the carry chains is two bits per CLB.

The arithmetic logic includes an XOR gate that allows a 2-bit full adder to be implemented within a slice. In addition, a dedicated AND gate improves the efficiency of multiplier implementation. The dedicated carry path can also be used to cascade function generators for implementing wide logic functions.

BUFTs

Each Virtex-E CLB contains two 3-state drivers (BUFTs) that can drive on-chip busses. See "Dedicated Routing" on page 6. Each Virtex-E BUFT has an independent 3-state control pin and an independent input pin.

Block SelectRAM

Virtex-E FPGAs incorporate large block SelectRAM memories. These complement the Distributed SelectRAM memories that provide shallow RAM structures implemented in CLBs.

Block SelectRAM memory blocks are organized in columns, starting at the left (column 0) and right outside edges and inserted every 12 CLB columns (see notes for smaller devices). Each memory block is four CLBs high, and each memory column extends the full height of the chip, immediately adjacent (to the right, except for column 0) of the CLB column locations indicated in Table 3.

Table 3: **CLB/Block RAM Column Locations**

XQ Device	Column Number										
	0	12	24	36	48	60	72	84	96	108	120
V600E	√	√	√		√	√	√				
V1000E	√	√	√				√	√	√		
V2000E	√	√	√	√				√	√	√	√

Table 4 shows the amount of block SelectRAM memory that is available in each Virtex-E device.

Table 4: **Virtex-E Block SelectRAM Amounts**

Virtex-E Device	# of Blocks	Block SelectRAM Bits
XQV600E	72	294,912
XQV1000E	96	393,216
XQV2000E	160	655,360

As illustrated in Figure 6, each block SelectRAM cell is a fully synchronous dual-ported (True Dual Port) 4096-bit RAM with independent control signals for each port. The data widths of the two ports can be configured independently, providing built-in bus-width conversion.

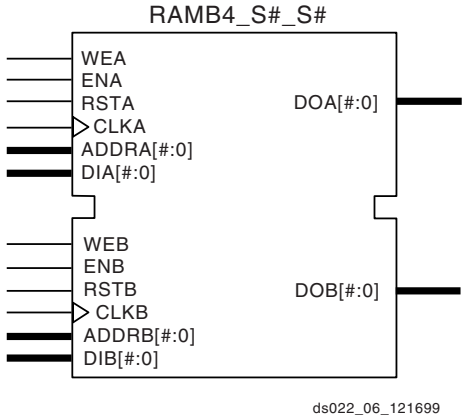


Figure 6: **Dual-Port Block SelectRAM**

Table 5 shows the depth and width aspect ratios for the block SelectRAM. The Virtex-E block SelectRAM also includes dedicated routing to provide an efficient interface with both CLBs and other block SelectRAMs. Refer to **XAPP130** for block SelectRAM timing waveforms.

Table 5: **Block SelectRAM Port Aspect Ratios**

Width	Depth	ADDR Bus	Data Bus
1	4096	ADDR<11:0>	DATA<0>
2	2048	ADDR<10:0>	DATA<1:0>

Table 5: **Block SelectRAM Port Aspect Ratios**

Width	Depth	ADDR Bus	Data Bus
4	1024	ADDR<9:0>	DATA<3:0>
8	512	ADDR<8:0>	DATA<7:0>
16	256	ADDR<7:0>	DATA<15:0>

Programmable Routing Matrix

It is the longest delay path that limits the speed of any worst-case design. Consequently, the Virtex-E routing architecture and its place-and-route software were defined in a joint optimization process. This joint optimization minimizes long-path delays, and consequently, yields the best system performance.

The joint optimization also reduces design compilation times because the architecture is software-friendly. Design cycles are correspondingly reduced due to shorter design iteration times.

Local Routing

The VersaBlock provides local routing resources (see Figure 7), providing three types of connections:

- Interconnections among the LUTs, flip-flops, and GRM
- Internal CLB feedback paths that provide high-speed connections to LUTs within the same CLB, chaining them together with minimal routing delay
- Direct paths that provide high-speed connections between horizontally adjacent CLBs, eliminating the delay of the GRM.

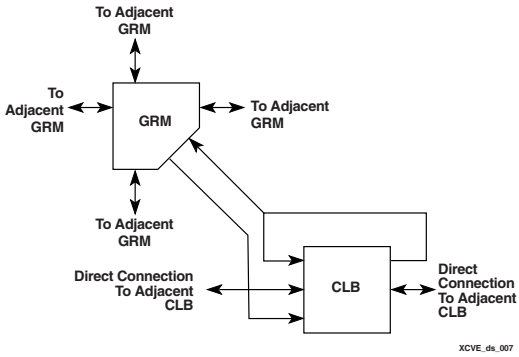


Figure 7: **Virtex-E Local Routing**

General Purpose Routing

Most Virtex-E signals are routed on the general purpose routing, and consequently, the majority of interconnect resources are associated with this level of the routing hierarchy. General-purpose routing resources are located in horizontal and vertical routing channels associated with the CLB rows and columns and are as follows:

- Adjacent to each CLB is a General Routing Matrix (GRM). The GRM is the switch matrix through which horizontal and vertical routing resources connect, and is also the means by which the CLB gains access to the general purpose routing.
- 24 single-length lines route GRM signals to adjacent GRMs in each of the four directions.
- 72 buffered Hex lines route GRM signals to another GRMs six-blocks away in each one of the four directions. Organized in a staggered pattern, Hex lines are driven only at their endpoints. Hex-line signals can be accessed either at the endpoints or at the midpoint (three blocks from the source). One third of the Hex lines are bidirectional, while the remaining ones are uni-directional.
- 12 Longlines are buffered, bidirectional wires that distribute signals across the device quickly and efficiently. Vertical Longlines span the full height of the device, and horizontal ones span the full width of the device.

I/O Routing

Virtex-E devices have additional routing resources around their periphery that form an interface between the CLB array and the IOBs. This additional routing, called the VersaRing, facilitates pin-swapping and pin-locking, such that logic redesigns can adapt to existing PCB layouts. Time-to-market is reduced, since PCBs and other system components can be manufactured while the logic design is still in progress.

Dedicated Routing

Some classes of signal require dedicated routing resources to maximize performance. In the Virtex-E architecture, dedicated routing resources are provided for two classes of signal.

- Horizontal routing resources are provided for on-chip 3-state busses. Four partitionable bus lines are provided per CLB row, permitting multiple busses within a row, as shown in Figure 8.
- Two dedicated nets per CLB propagate carry signals vertically to the adjacent CLB.Global Clock Distribution Network
- DLL Location

Clock Routing

Clock Routing resources distribute clocks and other signals with very high fanout throughout the device. Virtex-E devices include two tiers of clock routing resources referred to as global and local clock routing resources.

- The global routing resources are four dedicated global nets with dedicated input pins that are designed to distribute high-fanout clock signals with minimal skew. Each global clock net can drive all CLB, IOB, and block RAM clock pins. The global nets can be driven only by global buffers. There are four global buffers, one for each global net.
- The local clock routing resources consist of 24 backbone lines, 12 across the top of the chip and 12 across bottom. From these lines, up to 12 unique signals per column can be distributed via the 12 longlines in the column. These local resources are more flexible than the global resources since they are not restricted to routing only to clock pins.

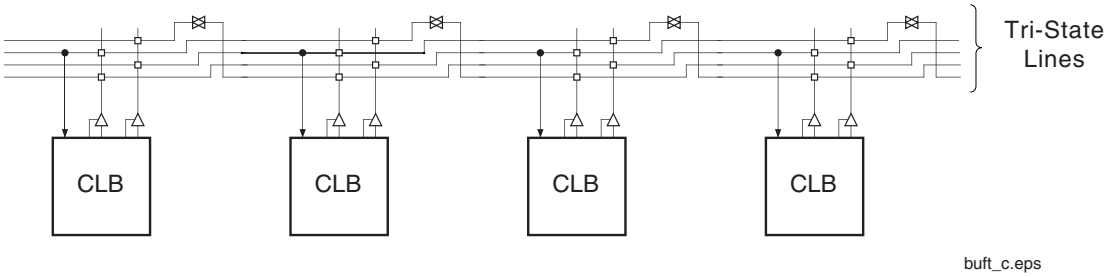


Figure 8: **BUFT Connections to Dedicated Horizontal Bus LInes**

Global Clock Distribution

Virtex-E provides high-speed, low-skew clock distribution through the global routing resources described above. A typical clock distribution net is shown in Figure 9.

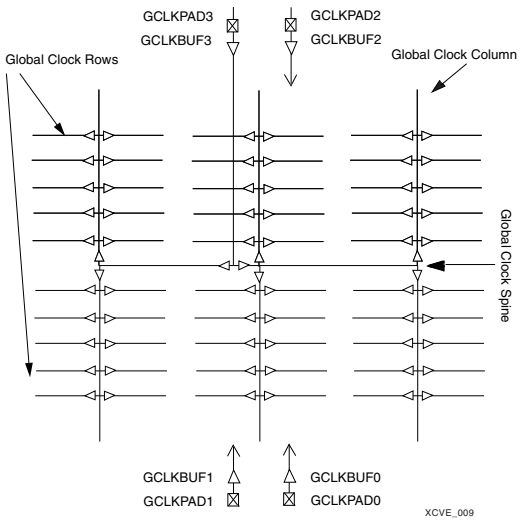


Figure 9: **Global Clock Distribution Network**

Four global buffers are provided, two at the top center of the device and two at the bottom center. These drive the four global nets that in turn drive any clock pin.

Four dedicated clock pads are provided, one adjacent to each of the global buffers. The input to the global buffer is selected either from these pads or from signals in the general purpose routing.

Digital Delay-Locked Loops

There are eight DLLs (Delay-Locked Loops) per device, with four located at the top and four at the bottom, Figure 10. The DLLs can be used to eliminate skew between the clock input pad and the internal clock input pins throughout the device. Each DLL can drive two global clock networks.The DLL monitors the input clock and the distributed clock, and automatically adjusts a clock delay element. Additional delay is introduced such that clock edges arrive at internal flip-flops synchronized with clock edges arriving at the input.

In addition to eliminating clock-distribution delay, the DLL provides advanced control of multiple clock domains. The DLL provides four quadrature phases of the source clock, and can double the clock or divide the clock by 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

The DLL also operates as a clock mirror. By driving the output from a DLL off-chip and then back on again, the DLL can be used to de-skew a board level clock among multiple devices.

To guarantee that the system clock is operating correctly prior to the FPGA starting up after configuration, the DLL can delay the completion of the configuration process until after it has achieved lock. For more information about DLL functionality, see the Design Consideration section of the data sheet.

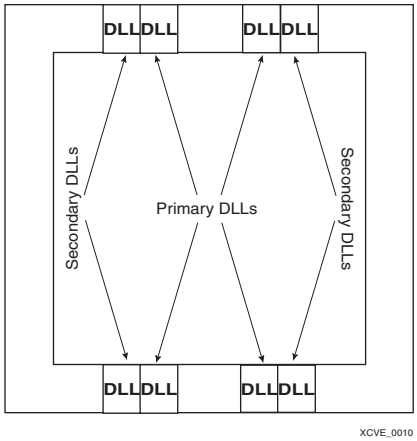


Figure 10: **DLL Locations**

Boundary Scan

Virtex-E devices support all the mandatory boundary-scan instructions specified in the IEEE standard 1149.1. A Test Access Port (TAP) and registers are provided that implement the EXTEST, INTEST, SAMPLE/PRELOAD, BYPASS, IDCODE, USERCODE, and HIGHZ instructions. The TAP also supports two internal scan chains and configuration/readback of the device.

The JTAG input pins (TDI, TMS, TCK) do not have a V_{CCO} requirement and operate with either 2.5V or 3.3V input signalling levels. The output pin (TDO) is sourced from the V_{CCO} in bank 2, and for proper operation of LVTTL 3.3V levels, the bank should be supplied with 3.3V.

Boundary-scan operation is independent of individual IOB configurations, and unaffected by package type. All IOBs, including un-bonded ones, are treated as independent 3-state bidirectional pins in a single scan chain. Retention of the bidirectional test capability after configuration facilitates the testing of external interconnections.

Table 6 lists the boundary-scan instructions supported in Virtex-E FPGAs. Internal signals can be captured during EXTEST by connecting them to un-bonded or unused IOBs. They can also be connected to the unused outputs of IOBs defined as unidirectional input pins.

Before the device is configured, all instructions except USER1 and USER2 are available. After configuration, all instructions are available. During configuration, it is recommended that those operations using the boundary-scan register (SAMPLE/PRELOAD, INTEST, EXTEST) not be performed.

In addition to the test instructions outlined above, the boundary-scan circuitry can be used to configure the FPGA, and also to read back the configuration data.

Figure 11 is a diagram of the Virtex-E Series boundary scan logic. It includes three bits of Data Register per IOB, the IEEE 1149.1 Test Access Port controller, and the Instruction Register with decodes.

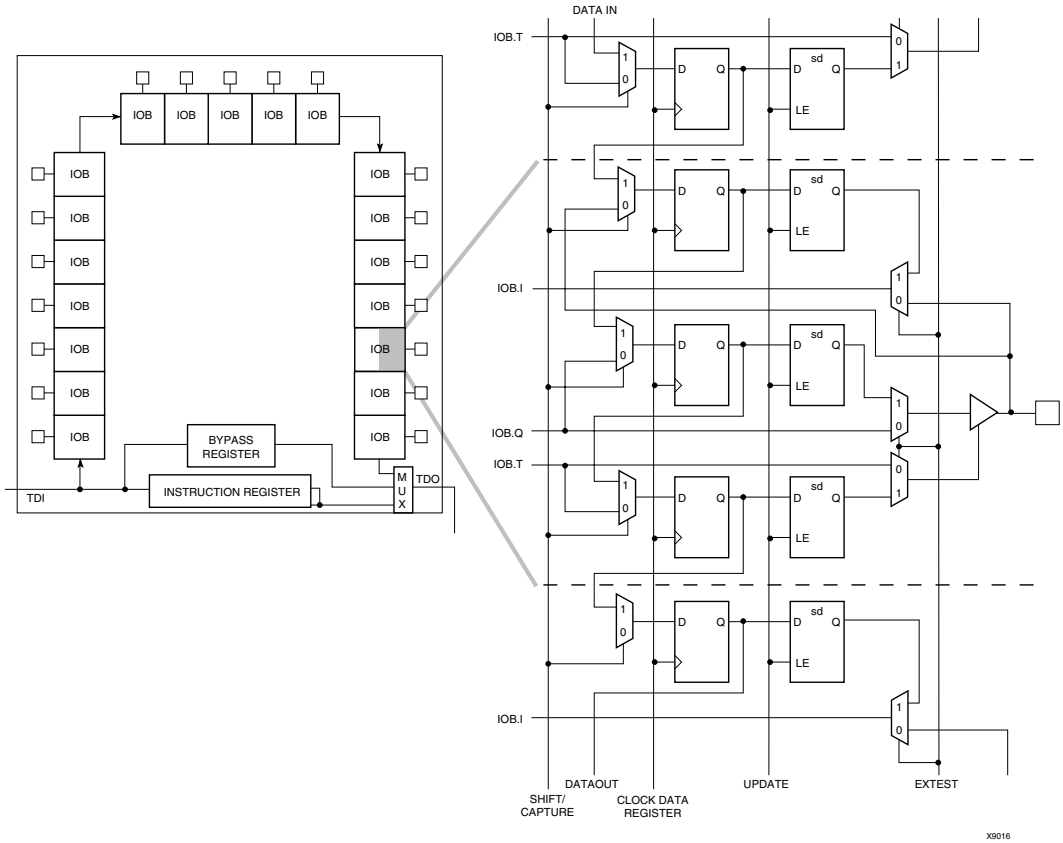


Figure 11: **Virtex-E Family Boundary Scan Logic**

Instruction Set

The Virtex-E Series boundary scan instruction set also includes instructions to configure the device and read back configuration data (CFG_IN, CFG_OUT, and JSTART). The complete instruction set is coded as shown in Table 6..

Table 6: **Boundary Scan Instructions**

Boundary-Scan Command	Binary Code(4:0)	Description
EXTEST	00000	Enables boundary-scan EXTEST operation
SAMPLE/ PRELOAD	00001	Enables boundary-scan SAMPLE/PRELOAD operation
USER1	00010	Access user-defined register 1
USER2	00011	Access user-defined register 2
CFG_OUT	00100	Access the configuration bus for read operations.
CFG_IN	00101	Access the configuration bus for write operations.
INTEST	00111	Enables boundary-scan INTEST operation
USERCODE	01000	Enables shifting out USER code
IDCODE	01001	Enables shifting out of ID Code
HIGHZ	01010	3-states output pins while enabling the Bypass Register
JSTART	01100	Clock the start-up sequence when StartupClk is TCK
BYPASS	11111	Enables BYPASS
RESERVED	All other codes	Xilinx reserved instructions

Data Registers

The primary data register is the boundary scan register. For each IOB pin in the FPGA, bonded or not, it includes three bits for In, Out, and 3-State Control. Non-IOB pins have appropriate partial bit population if input-only or output-only.

Each EXTEST CAPTURED-OR state captures all In, Out, and 3-state pins.

The other standard data register is the single flip-flop BYPASS register. It synchronizes data being passed through the FPGA to the next downstream boundary scan device.

The FPGA supports up to two additional internal scan chains that can be specified using the BSCAN macro. The macro provides two user pins (SEL1 and SEL2) which are decodes of the USER1 and USER2 instructions respectively. For these instructions, two corresponding pins (T DO1 and TDO2) allow user scan data to be shifted out of TDO.

Likewise, there are individual clock pins (DRCK1 and DRCK2) for each user register. There is a common input pin (TDI) and shared output pins that represent the state of the TAP controller (RESET, SHIFT, and UPDATE).

Bit Sequence

The order within each IOB is: In, Out, 3-State. The input-only pins contribute only the In bit to the boundary scan I/O data register, while the output-only pins contributes all three bits.

From a cavity-up view of the chip (as shown in EPIC), starting in the upper right chip corner, the boundary scan data-register bits are ordered as shown in Figure 12.

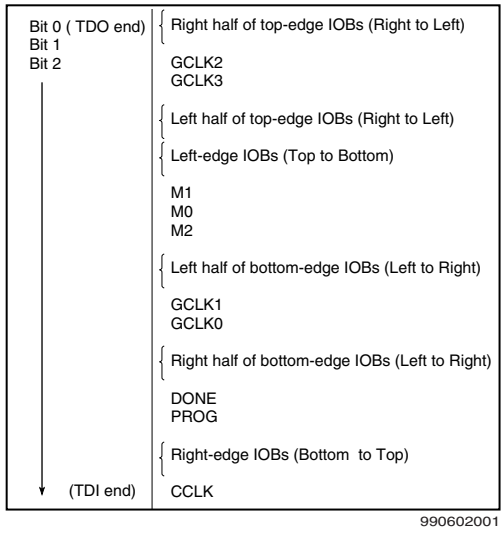


Figure 12: **Boundary Scan Bit Sequence**

BSDL (Boundary Scan Description Language) files for Virtex-E Series devices are available on the Xilinx web site in the File Download area.

Identification Registers

The IDCODE register is supported. By using the IDCODE, the device connected to the JTAG port can be determined.

The IDCODE register has the following binary format:

```
vvvv:ffff:fffa:aaaa:aaaa:cccc:cccc:ccc1
```

where

- v = the die version number
- f = the family code (05 for Virtex-E family)
- a = the number of CLB rows (ranges from 48 for XQV600E to 80 for XQV2000E)
- c = the company code (49h for Xilinx)

The USERCODE register is supported. By using the USERCODE, a user-programmable identification code can be loaded and shifted out for examination. The identification code (see Table 7) is embedded in the bitstream during bitstream generation and is valid only after configuration.

Table 7: **IDCODEs Assigned to Virtex-E FPGAs**

FPGA	IDCODE
XCV600E	v0A30093h
XCV1000E	v0A40093h
XCV2000E	v0A50093h

Note:
Attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Including Boundary Scan in a Design

Since the boundary scan pins are dedicated, no special element needs to be added to the design unless an internal data register (USER1 or USER2) is desired.

If an internal data register is used, insert the boundary scan symbol and connect the necessary pins as appropriate.

Development System

Virtex-E FPGAs are supported by the Xilinx Foundation and Alliance Series CAE tools. The basic methodology for Virtex-E design consists of three interrelated steps: design entry, implementation, and verification. Industry-standard tools are used for design entry and simulation (for example, Synopsys FPGA Express), while Xilinx provides proprietary architecture-specific tools for implementation.

The Xilinx development system is integrated under the Xilinx Design Manager (XDM™) software, providing designers with a common user interface regardless of their choice of entry and verification tools. The XDM software simplifies the selection of implementation options with pull-down menus and on-line help.

Application programs ranging from schematic capture to Placement and Routing (PAR) can be accessed through the XDM software. The program command sequence is generated prior to execution, and stored for documentation.

Several advanced software features facilitate Virtex-E design. RPMs, for example, are schematic-based macros with relative location constraints to guide their placement. They help ensure optimal implementation of common functions.

For HDL design entry, the Xilinx FPGA Foundation development system provides interfaces to the following synthesis design environments.

- Synopsys (FPGA Compiler, FPGA Express)
- Exemplar (Spectrum)
- Synplicity (Synplify)

For schematic design entry, the Xilinx FPGA Foundation and Alliance development system provides interfaces to the following schematic-capture design environments.

- Mentor Graphics V8 (Design Architect, QuickSim II)
- Viewlogic Systems (Viewdraw)

Third-party vendors support many other environments.

A standard interface-file specification, Electronic Design Interchange Format (EDIF), simplifies file transfers into and out of the development system.

Virtex-E FPGAs are supported by a unified library of standard functions. This library contains over 400 primitives and macros, ranging from 2-input AND gates to 16-bit accumulators, and includes arithmetic functions, comparators, counters, data registers, decoders, encoders, I/O functions, latches, Boolean functions, multiplexers, shift registers, and barrel shifters.

The "soft macro" portion of the library contains detailed descriptions of common logic functions, but does not contain any partitioning or placement information. The performance of these macros depends, therefore, on the partitioning and placement obtained during implementation.

RPMs, on the other hand, do contain predetermined partitioning and placement information that permits optimal implementation of these functions. Users can create their own library of soft macros or RPMs based on the macros and primitives in the standard library.

The design environment supports hierarchical design entry, with high-level schematics that comprise major functional blocks, while lower-level schematics define the logic in these blocks. These hierarchical design elements are automatically combined by the implementation tools. Different design entry tools can be combined within a hierarchical design, thus allowing the most convenient entry method to be used for each portion of the design.

Design Implementation

The place-and-route tools (PAR) automatically provide the implementation flow described in this section. The partitioner takes the EDIF net list for the design and maps the logic into the architectural resources of the FPGA (CLBs and IOBs, for example). The placer then determines the best locations for these blocks based on their interconnections and the desired performance. Finally, the router interconnects the blocks.

The PAR algorithms support fully automatic implementation of most designs. For demanding applications, however, the user can exercise various degrees of control over the process. User partitioning, placement, and routing information is optionally specified during the design-entry process. The implementation of highly structured designs can benefit greatly from basic floor planning.

The implementation software incorporates Timing Wizard® timing-driven placement and routing. Designers specify timing requirements along entire paths during design entry. The timing path analysis routines in PAR then recognize these user-specified requirements and accommodate them.

Timing requirements are entered on a schematic in a form directly relating to the system requirements, such as the targeted clock frequency, or the maximum allowable delay between two registers. In this way, the overall performance of the system along entire signal paths is automatically tailored to user-generated specifications. Specific timing information for individual nets is unnecessary.

Design Verification

In addition to conventional software simulation, FPGA users can use in-circuit debugging techniques. Because Xilinx devices are infinitely reprogrammable, designs can be verified in real time without the need for extensive sets of software simulation vectors.

The development system supports both software simulation and in-circuit debugging techniques. For simulation, the system extracts the post-layout timing information from the design database, and back-annotates this information into the net list for use by the simulator. Alternatively, the user can verify timing-critical portions of the design using the TRCE® static timing analyzer.

For in-circuit debugging, an optional download and readback cable is available. This cable connects the FPGA in the target system to a PC or workstation. After downloading the design into the FPGA, the designer can single-step the logic, readback the contents of the flip-flops, and so observe the internal logic state. Simple modifications can be downloaded into the system in a matter of minutes.

Configuration

Virtex-E devices are configured by loading configuration data into the internal configuration memory. Note that attempting to load an incorrect bitstream causes configuration to fail and can damage the device.

Some of the pins used for configuration are dedicated pins, while others can be re-used as general purpose inputs and outputs once configuration is complete.

The following are dedicated pins:

- Mode pins (M2, M1, M0)
- Configuration clock pin (CCLK)
- $\overline{\text{PROGRAM}}$ pin
- DONE pin
- Boundary-scan pins (TDI, TDO, TMS, TCK)

Depending on the configuration mode chosen, CCLK can be an output generated by the FPGA, or can be generated externally and provided to the FPGA as an input. The $\overline{\text{PROGRAM}}$ pin must be pulled High prior to reconfiguration.

Note that some configuration pins can act as outputs. For correct operation, these pins require a V_{CCO} of 3.3 V or 2.5 V. At 3.3 V the pins operate as LVTTL, and at 2.5 V they operate as LVCMOS. All affected pins fall in banks 2 or 3. The configuration pins needed for SelectMap (CS, Write) are located in bank 1.

Configuration Modes

Virtex-E supports the following four configuration modes.

- Slave-serial mode
- Master-serial mode
- SelectMAP mode
- Boundary-scan mode (JTAG)

The Configuration mode pins (M2, M1, M0) select among these configuration modes with the option in each case of having the IOB pins either pulled up or left floating prior to configuration. The selection codes are listed in Table 8.

Table 8: **Configuration Codes**

Configuration Mode	M2	M1	M0	CCLK Direction	Data Width	Serial D_{out}	Configuration Pull-ups
Master-serial mode	0	0	0	Out	1	Yes	No
Boundary-scan mode	1	0	1	N/A	1	No	No
SelectMAP mode	1	1	0	In	8	No	No
Slave-serial mode	1	1	1	In	1	Yes	No
Master-serial mode	1	0	0	Out	1	Yes	Yes
Boundary-scan mode	0	0	1	N/A	1	No	Yes
SelectMAP mode	0	1	0	In	8	No	Yes
Slave-serial mode	0	1	1	In	1	Yes	Yes

Configuration through the boundary-scan port is always available, independent of the mode selection. Selecting the boundary-scan mode simply turns off the other modes. The three mode pins have internal pull-up resistors, and default to a logic High if left unconnected. However, it is recommended to drive the configuration mode pins externally.

Table 9 lists the total number of bits required to configure each device.

Table 9: **Virtex-E Bitstream Lengths**

Device	# of Configuration Bits
XQV600E	3,961,632
XQV1000E	6,587,520
XQV2000E	10,159,648

Slave-Serial Mode

In slave-serial mode, the FPGA receives configuration data in bit-serial form from a serial PROM or other source of serial configuration data. The serial bitstream must be set up at the DIN input pin a short time before each rising edge of an externally generated CCLK.

For more detailed information on serial PROMs, see the PROM data sheet at **http://www.xilinx.com/bvdocs/publications/ds082.pdf**.

Multiple FPGAs can be daisy-chained for configuration from a single source. After a particular FPGA has been configured, the data for the next device is routed to the DOUT pin. The data on the DOUT pin changes on the rising edge of CCLK.

The change of DOUT on the rising edge of CCLK differs from previous families, but does not cause a problem for mixed configuration chains. This change was made to improve serial configuration rates for Virtex and Virtex-E only chains.

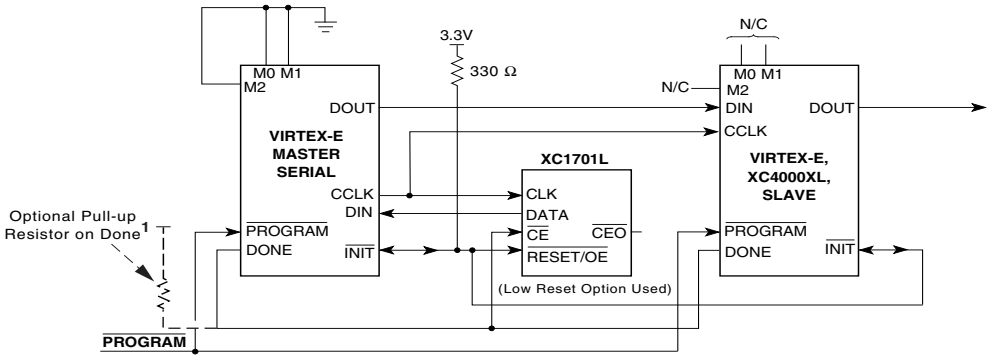
Figure 13 shows a full master/slave system. A Virtex-E device in slave-serial mode should be connected as shown in the right-most device.

Slave-serial mode is selected by applying <111> or <011> to the mode pins (M2, M1, M0). A weak pull-up on the mode pins makes slave serial the default mode if the pins are left unconnected. However, it is recommended to drive the configuration mode pins externally. Figure 14 shows slave-serial mode programming switching characteristics.

Table 10 provides more detail about the characteristics shown in Figure 14. Configuration must be delayed until the $\overline{\text{INIT}}$ pins of all daisy-chained FPGAs are High.

Table 10: **Master/Slave Serial Mode Programming Switching**

Description		Figure References	Symbol	Values		Units
				min	max	
CCLK	DIN setup/hold, slave mode	1/2	T_{DCC} / T_{CCD}	5.0 / 0.0	-	ns
	DIN setup/hold, master mode	1/2	T_{DSCK} / T_{CKDS}	5.0 / 0.0	-	ns
	DOUT	3	T_{CCO}		12.0	ns
	High time	4	T_{CCH}	5.0	-	ns
	Low time	5	T_{CCL}	5.0	-	ns
	Maximum Frequency	-	F_{CC}	-	66	MHz
	Frequency Tolerance, master mode with respect to nominal	-	-	–30	+45	%



Note 1: If none of the Virtex FPGAs have been selected to drive DONE, an external pull-up resistor of 330 Ω should be added to the common DONE line. (For Spartan-XL devices, add a 4.7K Ω pull-up resistor.) This pull-up is not needed if the DriveDONE attribute is set. If used, DriveDONE should be selected only for the last device in the configuration chain.

XCVE_ds_013_050103

Figure 13: **Master/Slave Serial Mode Circuit Diagram**

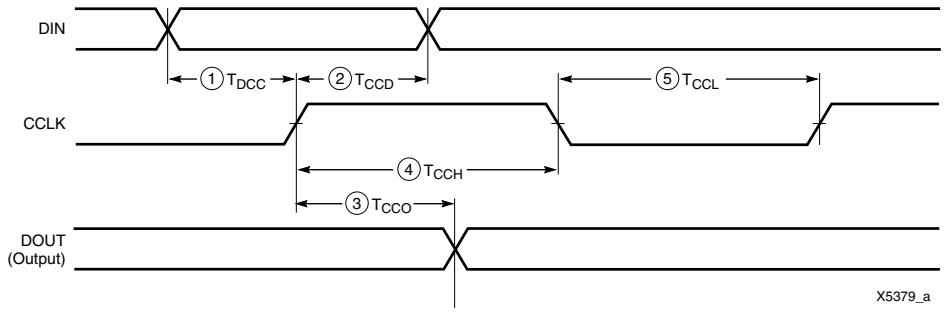


Figure 14: **Slave-Serial Mode Programming Switching Characteristics**

Master-Serial Mode

In master-serial mode, the CCLK output of the FPGA drives a Xilinx Serial PROM that feeds bit-serial data to the DIN input. The FPGA accepts this data on each rising CCLK edge. After the FPGA has been loaded, the data for the next device in a daisy-chain is presented on the DOUT pin after the rising CCLK edge.

The interface is identical to slave-serial except that an internal oscillator is used to generate the configuration clock (CCLK). A wide range of frequencies can be selected for CCLK, which always starts at a slow default frequency. Configuration bits then switch CCLK to a higher frequency for the remainder of the configuration. Switching to a lower frequency is prohibited.

The CCLK frequency is set using the ConfigRate option in the bitstream generation software. The maximum CCLK frequency that can be selected is 60 MHz. When selecting a CCLK frequency, ensure that the serial PROM and any daisy-chained FPGAs are fast enough to support the clock rate.

On power-up, the CCLK frequency is approximately 2.5 MHz. This frequency is used until the ConfigRate bits have been loaded when the frequency changes to the selected ConfigRate. Unless a different frequency is specified in the design, the default ConfigRate is 4 MHz.

In a full master/slave system (Figure 13), the left-most device operates in master-serial mode. The remaining devices operate in slave-serial mode. The SPROM $\overline{\text{RESET}}$ pin is driven by $\overline{\text{INIT}}$, and the $\overline{\text{CE}}$ input is driven by DONE. There is the potential for contention on the DONE pin, depending on the start-up sequence options chosen.

The sequence of operations necessary to configure a Virtex-E FPGA serially appears in Figure 15.

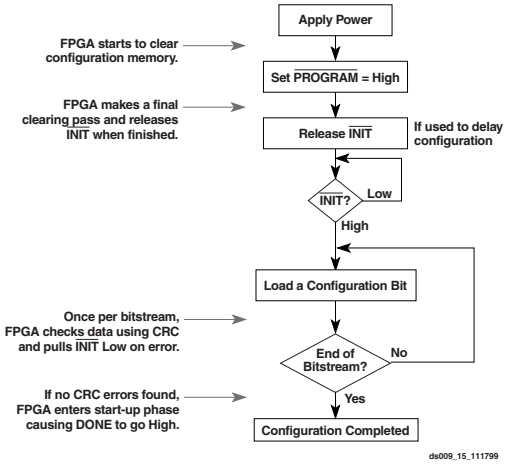


Figure 15: **Serial Configuration Flowchart**

Figure 16 shows the timing of master-serial configuration. Master-serial mode is selected by a <000> or <100> on the mode pins (M2, M1, M0). Table 10 shows the timing information for Figure 16.

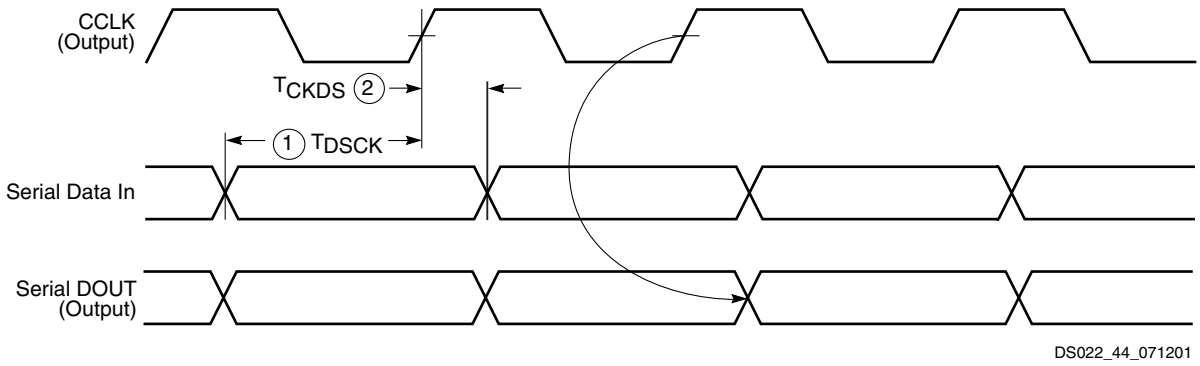


Figure 16: **Master-Serial Mode Programming Switching Characteristics**

At power-up, V_{CC} must rise from 1.0 V to V_{CC} Min in less than 50 ms, otherwise delay configuration by pulling PROGRAM Low until V_{CC} is valid.

SelectMAP Mode

The SelectMAP mode is the fastest configuration option. Byte-wide data is written into the FPGA with a BUSY flag controlling the flow of data.

An external data source provides a byte stream, CCLK, a Chip Select (CS) signal and a Write signal (WRITE). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low.

Data can also be read using the SelectMAP mode. If WRITE is not asserted, configuration data is read out of the FPGA as part of a readback operation.

After configuration, the pins of the SelectMAP port can be used as additional user I/O. Alternatively, the port can be retained to permit high-speed 8-bit readback.

Retention of the SelectMAP port is selectable on a design-by-design basis when the bitstream is generated. If retention is selected, PROHIBIT constraints are required to prevent the SelectMAP-port pins from being used as user I/O.

Multiple Virtex-E FPGAs can be configured using the SelectMAP mode, and be made to start-up simultaneously. To configure multiple devices in this way, wire the individual CCLK, Data, WRITE, and BUSY pins of all the devices in parallel. The individual devices are loaded separately by asserting the CS pin of each device in turn and writing the appropriate data. See Table 11 for SelectMAP Write Timing Characteristics.

Write

Write operations send packets of configuration data into the FPGA. The sequence of operations for a multi-cycle write operation is shown below. Note that a configuration packet can be split into many such sequences. The packet does

not have to complete within one assertion of $\overline{CS}$, illustrated in Figure 17.

1. Assert $\overline{WRITE}$ and $\overline{CS}$ Low. Note that when $\overline{CS}$ is asserted on successive CCLKs, $\overline{WRITE}$ must remain either asserted or de-asserted. Otherwise, an abort is initiated, as described below.
2. Drive data onto D[7:0]. Note that to avoid contention, the data source should not be enabled while $\overline{CS}$ is Low and $\overline{WRITE}$ is High. Similarly, while $\overline{WRITE}$ is High, no more that one $\overline{CS}$ should be asserted.
3. At the rising edge of CCLK: If BUSY is Low, the data is accepted on this clock. If BUSY is High (from a previous write), the data is not accepted. Acceptance instead occurs on the first clock after BUSY goes Low, and the data must be held until this has happened.
4. Repeat steps 2 and 3 until all the data has been sent.
5. De-assert $\overline{CS}$ and $\overline{WRITE}$.

Table 11: **SelectMAP Write Timing Characteristics**

	Description		Symbol		Units
CCLK	D_{0-7} Setup/Hold	1/2	T_{SMDCC}/T_{SMCCD}	5.0 / 1.7	ns, min
	$\overline{CS}$ Setup/Hold	3/4	T_{SMCSCC}/T_{SMCCCS}	7.0 / 1.7	ns, min
	$\overline{WRITE}$ Setup/Hold	5/6	T_{SMCCW}/T_{SMWCC}	7.0 / 1.7	ns, min
	BUSY Propagation Delay	7	T_{SMCKBY}	12.0	ns, max
	Maximum Frequency		F_{CC}	66	MHz, max
	Maximum Frequency with no handshake		F_{CCNH}	50	MHz, max

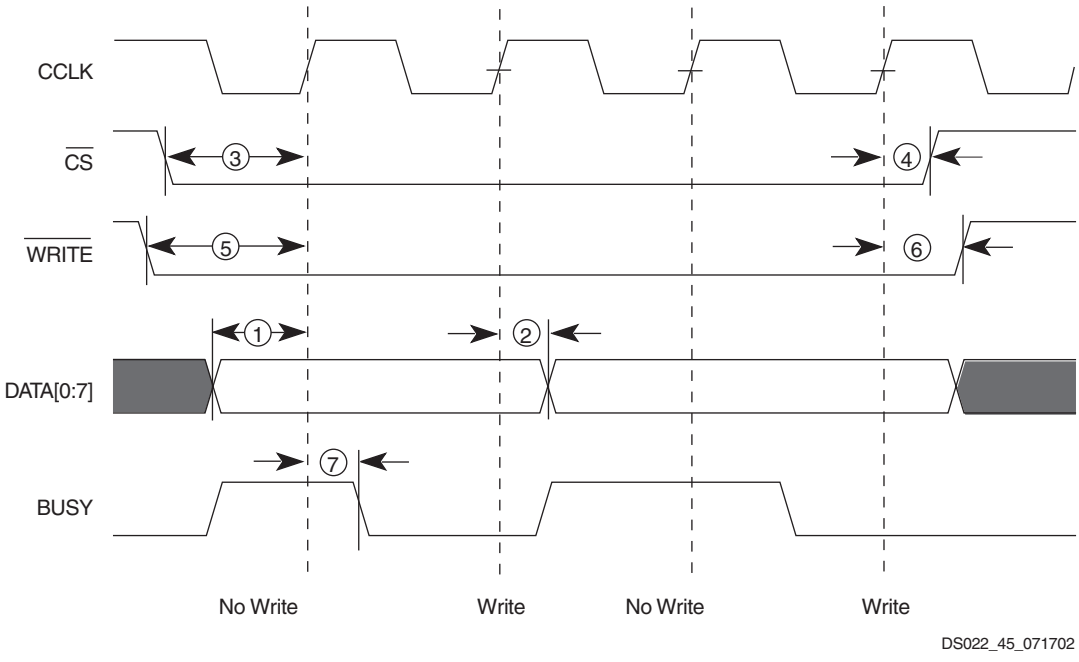


Figure 17: **Write Operations**

A flowchart for the write operation is shown in Figure 18. Note that if CCLK is slower than f_{CCNH}, the FPGA never asserts BUSY, In this case, the above handshake is unnecessary, and data can simply be entered into the FPGA every CCLK cycle.

Abort

During a given assertion of $\overline{CS}$, the user cannot switch from a write to a read, or vice-versa. This action causes the current packet command to be aborted. The device remains BUSY until the aborted operation has completed. Following an abort, data is assumed to be unaligned to word boundaries, and the FPGA requires a new synchronization word prior to accepting any new packets.

To initiate an abort during a write operation, de-assert $\overline{WRITE}$. At the rising edge of CCLK, an abort is initiated, as shown in Figure 19.

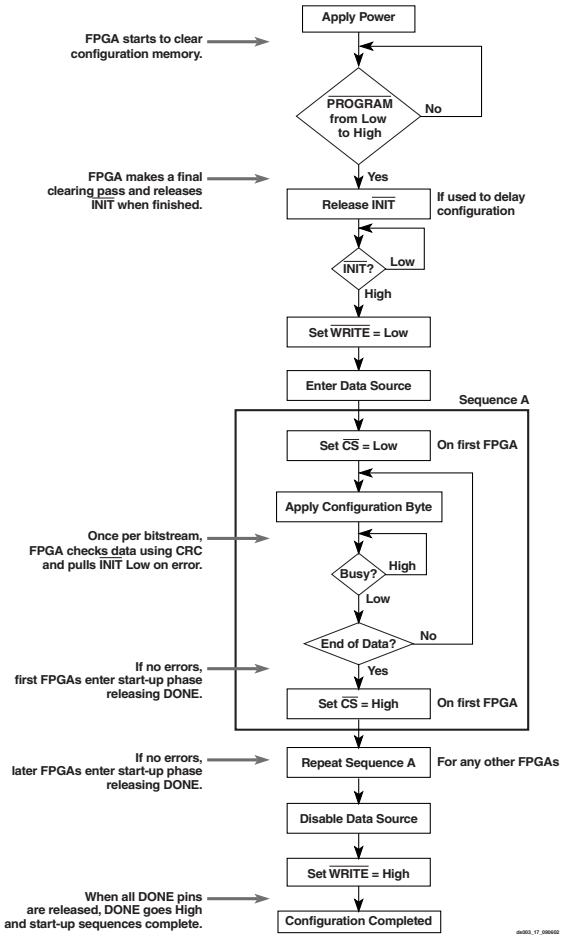


Figure 18: **SelectMAP Flowchart for Write Operations**

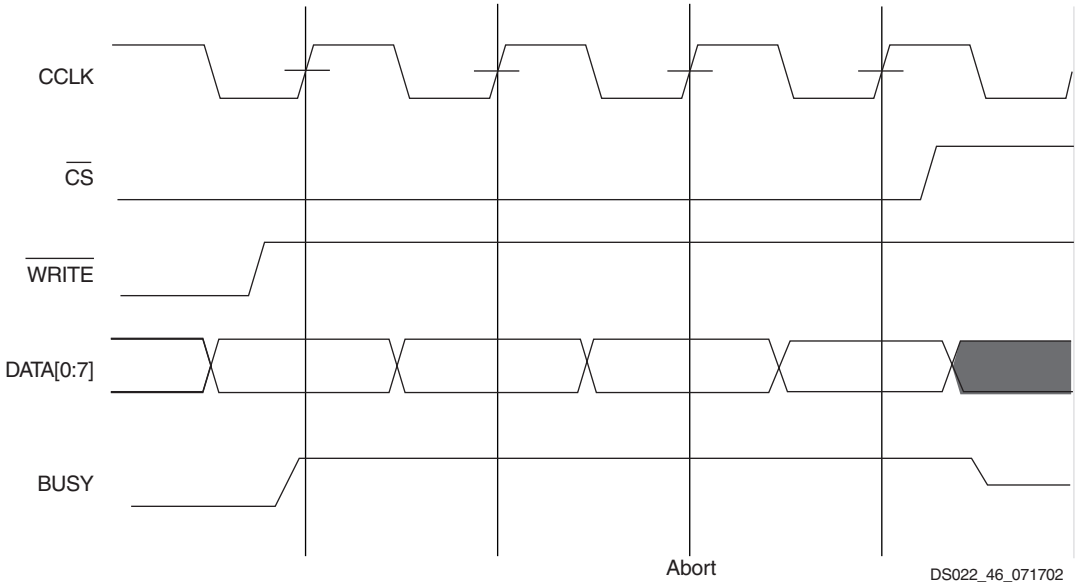


Figure 19: **SelectMAP Write Abort Waveforms**

Boundary-Scan Mode

In the boundary-scan mode, configuration is done through the IEEE 1149.1 Test Access Port. Note that the PROGRAM pin must be pulled High prior to reconfiguration. A Low on the PROGRAM pin resets the TAP controller and no JTAG operations can be performed.

Configuration through the TAP uses the CFG_IN instruction. This instruction allows data input on TDI to be converted into data packets for the internal configuration bus.

The following steps are required to configure the FPGA through the boundary-scan port (when using TCK as a start-up clock).

1. Load the CFG_IN instruction into the boundary-scan instruction register (IR).
2. Enter the Shift-DR (SDR) state.
3. Shift a configuration bitstream into TDI.
4. Return to Run-Test-Idle (RTI).
5. Load the JSTART instruction into IR.
6. Enter the SDR state.
7. Clock TCK through the startup sequence.
8. Return to RTI.

Configuration and readback via the TAP is always available. The boundary-scan mode is selected by a <101> or <001> on the mode pins (M2, M1, M0). For details on TAP characteristics, refer to **XAPP139**.

Configuration Sequence

The configuration of Virtex-E devices is a three-phase process. First, the configuration memory is cleared. Next, configuration data is loaded into the memory, and finally, the logic is activated by a start-up process.

Configuration is automatically initiated on power-up unless it is delayed by the user, as described below. The configuration process can also be initiated by asserting PROGRAM. The end of the memory-clearing phase is signalled by INIT going High, and the completion of the entire process is signalled by DONE going High.

The power-up timing of configuration signals is shown in Figure 20.

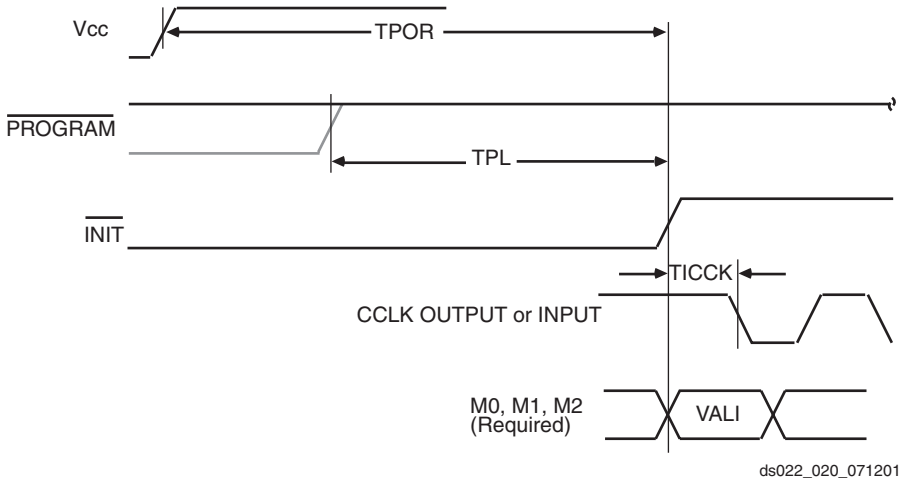


Figure 20: **Power-Up Timing Configuration Signals**

The corresponding timing characteristics are listed in Table 12.

Table 12: **Power-up Timing Characteristics**

Description	Figure Reference	Symbol	Value		Units
			min	max	
Power-on Reset[1]	20	T_{POR}	-	2.0	ms
Program Latency	20	T_{PL}	-	100.0	µs
CCLK (output) Delay	20	T_{ICCK}	0.5	4.0	µs
Program Pulse Width	-	$T_{PROGRAM}$	300	-	ns

Notes:
1. T_{POR} delay is the initialization time required after V_{CCINT} and V_{CCO} in Bank 2 reach the recommended operating voltage.

Delaying Configuration

$\overline{\text{INIT}}$ can be held Low using an open-drain driver. An open-drain is required since $\overline{\text{INIT}}$ is a bidirectional open-drain pin that is held Low by the FPGA while the configuration memory is being cleared. Extending the time that the pin is Low causes the configuration sequencer to wait. Thus, configuration is delayed by preventing entry into the phase where data is loaded.

Start-Up Sequence

The default Start-up sequence is that one CCLK cycle after DONE goes High, the global 3-state signal (GTS) is released. This permits device outputs to turn on as necessary.

One CCLK cycle later, the Global Set/Reset (GSR) and Global Write Enable (GWE) signals are released. This permits the internal storage elements to begin changing state in response to the logic and the user clock.

The relative timing of these events can be changed. In addition, the GTS, GSR, and GWE events can be made dependent on the DONE pins of multiple devices all going High, forcing the devices to start synchronously. The sequence can also be paused at any stage until lock has been achieved on any or all DLLs.

Readback

The configuration data stored in the Virtex-E configuration memory can be readback for verification. Along with the configuration data it is possible to readback the contents all flip-flops/latches, LUT RAMs, and block RAMs. This capability is used for real-time debugging. For more detailed information, see application note XAPP138 "Virtex FPGA Series Configuration and Readback".

Design Considerations

This section contains more detailed design information on the following features.

Using DLLs

The Virtex-E FPGA series provides up to eight fully digital dedicated on-chip Delay-Locked Loop (DLL) circuits which provide zero propagation delay, low clock skew between output clock signals distributed throughout the device, and advanced clock domain control. These dedicated DLLs can be used to implement several circuits which improve and simplify system level design.

Introduction

As FPGAs grow in size, quality on-chip clock distribution becomes increasingly important. Clock skew and clock delay impact device performance and the task of managing clock skew and clock delay with conventional clock trees becomes more difficult in large devices. The Virtex-E series of devices resolve this potential problem by providing up to eight fully digital dedicated on-chip DLL circuits, which provide zero propagation delay and low clock skew between output clock signals distributed throughout the device.

Each DLL can drive up to two global clock routing networks within the device. The global clock distribution network minimizes clock skews due to loading differences. By monitoring a sample of the DLL output clock, the DLL can compensate for the delay on the routing network, effectively eliminating the delay from the external input port to the individual clock loads within the device.

In addition to providing zero delay with respect to a user source clock, the DLL can provide multiple phases of the source clock. The DLL can also act as a clock doubler or it can divide the user source clock by up to 16.

Clock multiplication gives the designer a number of design alternatives. For instance, a 50 MHz source clock doubled by the DLL can drive an FPGA design operating at 100 MHz. This technique can simplify board design because the clock path on the board no longer distributes such a high-speed signal. A multiplied clock also provides designers the option of time-domain-multiplexing, using one circuit twice per clock cycle, consuming less area than two copies of the same circuit. Two DLLs in can be connected in series to increase the effective clock multiplication factor to four.

The DLL can also act as a clock mirror. By driving the DLL output off-chip and then back in again, the DLL can be used to de-skew a board level clock between multiple devices.

In order to guarantee the system clock establishes prior to the device "waking up," the DLL can delay the completion of the device configuration process until after the DLL achieves lock.

By taking advantage of the DLL to remove on-chip clock delay, the designer can greatly simplify and improve system level design involving high-fanout, high-performance clocks.

Library DLL Symbols

Figure 21 shows the simplified Xilinx library DLL macro symbol, BUFGDLL. This macro delivers a quick and efficient way to provide a system clock with zero propagation delay throughout the device. Figure 22 and Figure 23 show the two library DLL primitives. These symbols provide access to the complete set of DLL features when implementing more complex applications.

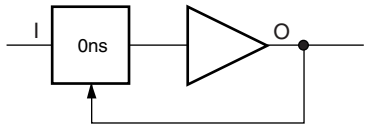


Figure 21: **Simplified DLL Macro Symbol BUFGDLL**

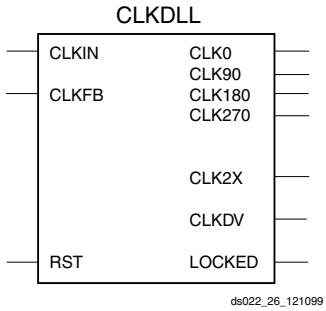


Figure 22: **Standard DLL Symbol CLKDLL**

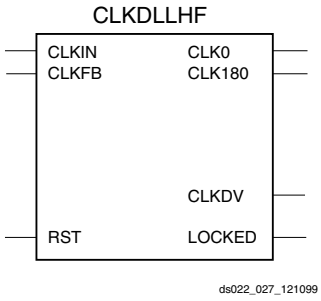


Figure 23: **High Frequency DLL Symbol CLKDLLHF**

BUFGDLL Pin Descriptions

Use the BUFGDLL macro as the simplest way to provide zero propagation delay for a high-fanout on-chip clock from an external input. This macro uses the IBUFG, CLKDLL and BUFG primitives to implement the most basic DLL application as shown in Figure 24.

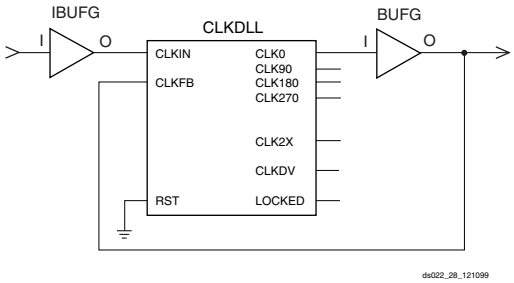


Figure 24: **BUFGDLL Schematic**

This symbol does not provide access to the advanced clock domain controls or to the clock multiplication or clock division features of the DLL. This symbol also does not provide access to the RST, or LOCKED pins of the DLL. For access to these features, a designer must use the library DLL primitives described in the following sections.

Source Clock Input — I

The I pin provides the user source clock, the clock signal on which the DLL operates, to the BUFGDLL. For the BUFGDLL macro the source clock frequency must fall in the low frequency range as specified in the data sheet. The BUFGDLL requires an external signal source clock. Therefore, only an external input port can source the signal that drives the BUFGDLL I pin.

Clock Output — O

The clock output pin O represents a delay-compensated version of the source clock (I) signal. This signal, sourced by a global clock buffer BUFG symbol, takes advantage of the dedicated global clock routing resources of the device.

The output clock has a 50-50 duty cycle unless you deactivate the duty cycle correction property.

CLKDLL Primitive Pin Descriptions

The library CLKDLL primitives provide access to the complete set of DLL features needed when implementing more complex applications with the DLL.

Source Clock Input — CLKIN

The CLKIN pin provides the user source clock (the clock signal on which the DLL operates) to the DLL. The CLKIN frequency must fall in the ranges specified in the data sheet. A global clock buffer (BUFG) driven from another CLKDLL, one of the global clock input buffers (IBUFG), or an IO_LVDS_DLL pin on the same edge of the device (top or bottom) must source this clock signal. There are four IO_LVDS_DLL input pins that can be used as inputs to the DLLs. This makes a total of eight usable input pins for DLLs in the Virtex-E family.

Feedback Clock Input — CLKFB

The DLL requires a reference or feedback signal to provide the delay-compensated output. Connect only the CLK0 or CLK2X DLL outputs to the feedback clock input (CLKFB) pin to provide the necessary feedback to the DLL. The feedback clock input can also be provided through one of the following pins.

IBUFG - Global Clock Input Pad

IO_LVDS_DLL - the pin adjacent to IBUF

If an IBUFG sources the CLKFB pin, the following special rules apply.

1. An external input port must source the signal that drives the IBUFG I pin.
2. The CLK2X output must feedback to the device if both the CLK0 and CLK2X outputs are driving off chip devices.
3. That signal must directly drive only OBUFs and nothing else.

These rules enable the software determine which DLL clock output sources the CLKFB pin.

Reset Input — RST

When the reset pin RST activates the LOCKED signal deactivates within four source clock cycles. The RST pin, active High, must either connect to a dynamic signal or tied to ground. As the DLL delay taps reset to zero, glitches can occur on the DLL clock output pins. Activation of the RST pin can also severely affect the duty cycle of the clock output pins. Furthermore, the DLL output clocks no longer deskew with respect to one another. For these reasons, rarely use the reset pin unless re-configuring the device or changing the input frequency.

2x Clock Output — CLK2X

The output pin CLK2X provides a frequency-doubled clock with an automatic 50/50 duty-cycle correction. Until the CLKDLL has achieved lock, the CLK2X output appears as a 1x version of the input clock with a 25/75 duty cycle. This behavior allows the DLL to lock on the correct edge with respect to source clock. This pin is not available on the CLKDLLHF primitive.

Clock Divide Output — CLKDV

The clock divide output pin CLKDV provides a lower frequency version of the source clock. The CLKDV_DIVIDE property controls CLKDV such that the source clock is divided by N where N is either 1.5, 2, 2.5, 3, 4, 5, 8, or 16.

This feature provides automatic duty cycle correction such that the CLKDV output pin always has a 50/50 duty cycle, with the exception of noninteger divides in HF mode, where the duty cycle is 1/3 for N=1.5 and 2/5 for N=2.5.

1x Clock Outputs — CLK[0|90|180|270]

The 1x clock output pin CLK0 represents a delay-compensated version of the source clock (CLKIN) signal. The CLKDLL primitive provides three phase-shifted versions of the CLK0 signal while CLKDLLHF provides only the 180 phase-shifted version. The relationship between phase shift and the corresponding period shift appears in Table 13.

Table 13: **Relationship of Phase-Shifted Output Clock to Period Shift**

Phase (degrees)	Period Shift (percent)
0	0%
90	25%
180	50%
270	75%

The timing diagrams in Figure 25 illustrate the DLL clock output characteristics.

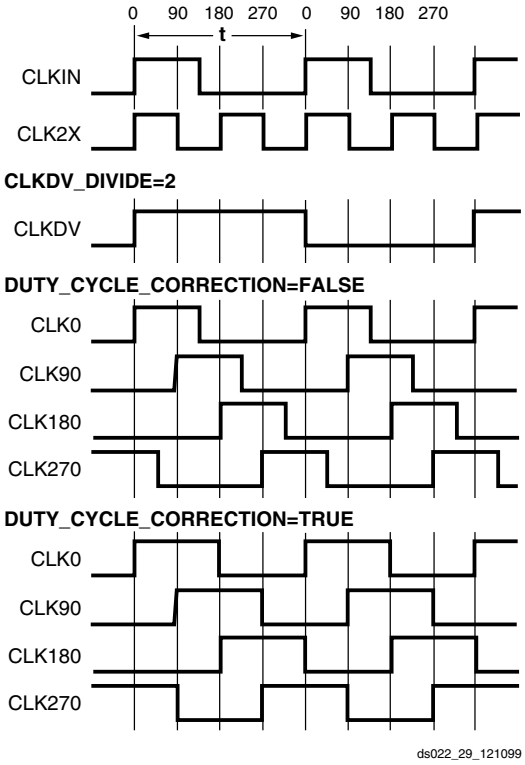


Figure 25: **DLL Output Characteristics**

The DLL provides duty cycle correction on all 1x clock outputs such that all 1x clock outputs by default have a 50/50 duty cycle. The DUTY_CYCLE_CORRECTION property (TRUE by default), controls this feature. In order to deactivate the DLL duty cycle correction, attach the DUTY_CYCLE_CORRECTION=FALSE property to the DLL symbol. When duty cycle correction deactivates, the output clock has the same duty cycle as the source clock.

The DLL clock outputs can drive an OBUF, a BUFG, or they can route directly to destination clock pins. The DLL clock outputs can only drive the BUFGs that reside on the same edge (top or bottom).

Locked Output — LOCKED

To achieve lock, the DLL might need to sample several thousand clock cycles. After the DLL achieves lock, the LOCKED signal activates. The DLL timing parameter section of the data sheet provides estimates for locking times.

To guarantee that the system clock is established prior to the device "waking up," the DLL can delay the completion of the device configuration process until after the DLL locks. The STARTUP_WAIT property activates this feature.

Until the LOCKED signal activates, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement. In particular the CLK2X output appears as a 1x clock with a 25/75 duty cycle.

DLL Properties

Properties provide access to some of the Virtex-E series DLL features, (for example, clock division and duty cycle correction).

Duty Cycle Correction Property

The 1x clock outputs, CLK0, CLK90, CLK180, and CLK270, use the duty-cycle corrected default, exhibiting a 50/50 duty cycle. The DUTY_CYCLE_CORRECTION property (by default TRUE) controls this feature. To deactivate the DLL duty-cycle correction for the 1x clock outputs, attach the DUTY_CYCLE_CORRECTION=FALSE property to the DLL symbol.

Clock Divide Property

The CLKDV_DIVIDE property specifies how the signal on the CLKDV pin is frequency divided with respect to the CLK0 pin. The values allowed for this property are 1.5, 2, 2.5, 3, 4, 5, 8, or 16; the default value is 2.

Startup Delay Property

This property, STARTUP_WAIT, takes on a value of TRUE or FALSE (the default value). When TRUE the device configuration DONE signal waits until the DLL locks before going to High.

Virtex-E DLL Location Constraints

As shown in Figure 26, there are four additional DLLs in the Virtex-E devices, for a total of eight per Virtex-E device. These DLLs are located in silicon, at the top and bottom of the two innermost block SelectRAM columns. The location constraint LOC, attached to the DLL symbol with the identifier DLL0S, DLL0P, DLL1S, DLL1P, DLL2S, DLL2P, DLL3S, or DLL3P, controls the DLL location.

The LOC property uses the following form:

LOC = DLL0P

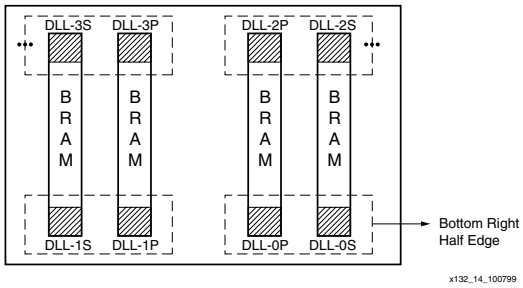


Figure 26: **Virtex Series DLLs**

Design Factors

Use the following design considerations to avoid pitfalls and improve success designing with Xilinx devices.

Input Clock

The output clock signal of a DLL, essentially a delayed version of the input clock signal, reflects any instability on the input clock in the output waveform. For this reason the quality of the DLL input clock relates directly to the quality of the output clock waveforms generated by the DLL. The DLL input clock requirements are specified in the data sheet.

In most systems a crystal oscillator generates the system clock. The DLL can be used with any commercially available quartz crystal oscillator. For example, most crystal oscillators produce an output waveform with a frequency tolerance of 100 PPM, meaning 0.01 percent change in the clock period. The DLL operates reliably on an input waveform with a frequency drift of up to 1 ns — orders of magnitude in excess of that needed to support any crystal oscillator in the industry. However, the cycle-to-cycle jitter must be kept to less than 300 ps in the low frequencies and 150 ps for the high frequencies.

Input Clock Changes

Changing the period of the input clock beyond the maximum drift amount requires a manual reset of the CLKDLL. Failure to reset the DLL produces an unreliable lock signal and output clock.

It is possible to stop the input clock with little impact to the DLL. Stopping the clock should be limited to less than 100 µs to keep device cooling to a minimum. The clock should be stopped during a Low phase, and when restored the full High period should be seen. During this time, LOCKED stays High and remains High when the clock is restored.

When the clock is stopped, one to four more clocks are still observed as the delay line is flushed. When the clock is restarted, the output clocks are not observed for one to four clocks as the delay line is filled. The most common case is two or three clocks.

In a similar manner, a phase shift of the input clock is also possible. The phase shift propagates to the output one to four clocks after the original shift, with no disruption to the CLKDLL control.

Output Clocks

As mentioned earlier in the DLL pin descriptions, some restrictions apply regarding the connectivity of the output pins. The DLL clock outputs can drive an OBUF, a global clock buffer BUFG, or they can route directly to destination clock pins. The only BUFGs that the DLL clock outputs can drive are the two on the same edge of the device (top or bottom). In addition, the CLK2X output of the secondary DLL can connect directly to the CLKIN of the primary DLL in the same quadrant.

Do not use the DLL output clock signals until after activation of the LOCKED signal. Prior to the activation of the LOCKED signal, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement.

Useful Application Examples

The Virtex-E DLL can be used in a variety of creative and useful applications. The following examples show some of the more common applications. The Verilog and VHDL example files are available at:

ftp://ftp.xilinx.com/pub/applications/xapp/xapp132.zip

Standard Usage

The circuit shown in Figure 27 resembles the BUFGDLL macro implemented to provide access to the RST and LOCKED pins of the CLKDLL.

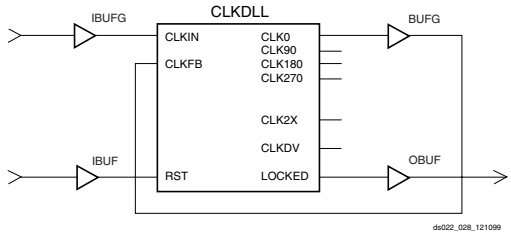


Figure 27: **Standard DLL Implementation**

Board Level De-skew of Multiple Non-Virtex-E Devices

The circuit shown in Figure 28 can be used to de-skew a system clock between a Virtex-E chip and other non-Virtex-E chips on the same board. This application is commonly used when the Virtex-E device is used in conjunction with other standard products such as SRAM or DRAM devices. While designing the board level route, ensure that the return net delay to the source equals the delay to the other chips involved.

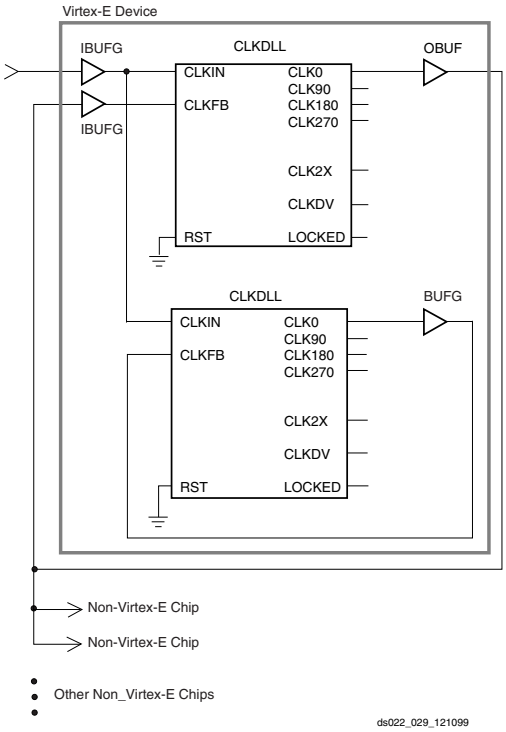


Figure 28: **DLL De-skew of Board Level Clock**

Board-level de-skew is not required for low-fanout clock networks. It is recommended for systems that have fanout limitations on the clock network, or if the clock distribution chip cannot handle the load.

Do not use the DLL output clock signals until after activation of the LOCKED signal. Prior to the activation of the LOCKED signal, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement.

The dll_mirror_1 files in the **xapp132.zip** file show the VHDL and Verilog implementation of this circuit.

De-Skew of Clock and Its 2x Multiple

The circuit shown in Figure 29 implements a 2x clock multiplier and also uses the CLK0 clock output with a zero ns skew between registers on the same chip. Alternatively, a clock divider circuit can be implemented using similar connections.

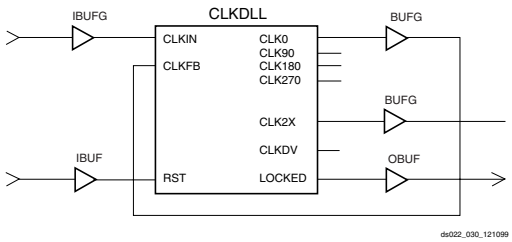


Figure 29: **DLL De-skew of Clock and 2x Multiple**

Because any single DLL can access only two BUFGs at most, any additional output clock signals must be routed from the DLL in this example on the high speed backbone routing.

The dll_2x files in the **xapp132.zip** file show the VHDL and Verilog implementation of this circuit.

Virtex-E 4x Clock

Two DLLs located in the same half-edge (top-left, top-right, bottom-right, bottom-left) can be connected together, without using a BUFG between the CLKDLLs, to generate a 4x clock as shown in Figure 30. Virtex-E devices, like the Virtex devices, have four clock networks that are available for internal de-skewing of the clock. Each of the eight DLLs have access to two of the four clock networks. Although all the DLLs can be used for internal de-skewing, the presence of two GCLKBUFs on the top and two on the bottom indicate that only two of the four DLLs on the top (and two of the four DLLs on the bottom) can be used for this purpose.

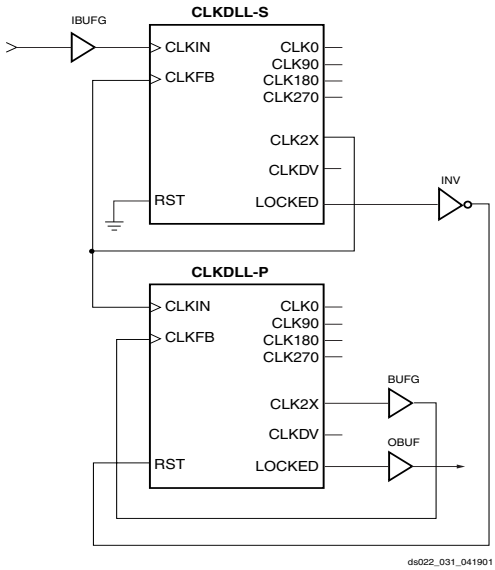


Figure 30: **DLL Generation of 4x Clock in Virtex-E Devices**

The dll_4xe files in the xapp132.zip file show the DLL implementation in Verilog for Virtex-E devices. These files can be found at:

ftp://ftp.xilinx.com/pub/applications/xapp/xapp132.zip

Using Block SelectRAM+ Features

The Virtex FPGA Series provides dedicated blocks of on-chip, true dual-read/write port synchronous RAM, with 4096 memory cells. Each port of the block SelectRAM+ memory can be independently configured as a read/write port, a read port, a write port, and can be configured to a specific data width. The block SelectRAM+ memory offers new capabilities allowing the FPGA designer to simplify designs.

Operating Modes

VIrtex-E block SelectRAM+ memory supports two operating modes:

- Read Through
- Write Back

Read Through (one clock edge)

The read address is registered on the read port clock edge and data appears on the output after the RAM access time. Some memories might place the latch/register at the outputs, depending on whether a faster clock-to-out versus set-up time is desired. This is generally considered to be an inferior solution, since it changes the read operation to an asynchronous function with the possibility of missing an address/control line transition during the generation of the read pulse clock.

Write Back (one clock edge)

The write address is registered on the write port clock edge and the data input is written to the memory and mirrored on the output.

Block SelectRAM+ Characteristics

- All inputs are registered with the port clock and have a set-up to clock timing specification.
- All outputs have a read through or write back function depending on the state of the port WE pin. The outputs relative to the port clock are available after the clock-to-out timing specification.
- The block SelectRAMs are true SRAM memories and do not have a combinatorial path from the address to the output. The LUT SelectRAM+ cells in the CLBs are still available with this function.
- The ports are completely independent from each other (*i.e.,* clocking, control, address, read/write function, and data width) without arbitration.
- A write operation requires only one clock edge.
- A read operation requires only one clock edge.

The output ports are latched with a self timed circuit to guarantee a glitch free read. The state of the output port does not change until the port executes another read or write operation.

Library Primitives

Figure 31 and Figure 32 show the two generic library block SelectRAM+ primitives. Table 14 describes all of the available primitives for synthesis and simulation.

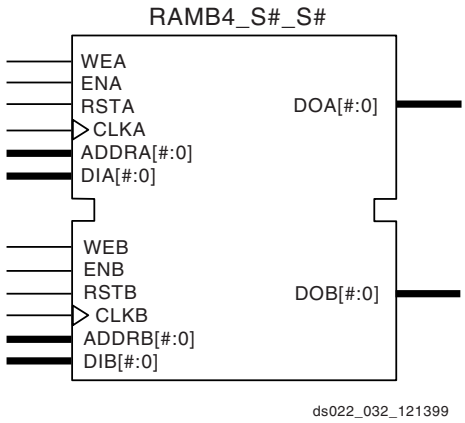


Figure 31: **Dual-Port Block SelectRAM+ Memory**

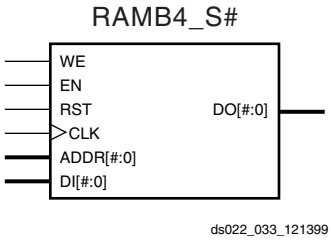


Figure 32: **Single-Port Block SelectRAM+ Memory**

Table 14: **Available Library Primitives**

Primitive	Port A Width	Port B Width
RAMB4_S1	1	N/A
RAMB4_S1_S1		1
RAMB4_S1_S2		2
RAMB4_S1_S4		4
RAMB4_S1_S8		8
RAMB4_S1_S16		16
RAMB4_S2	2	N/A
RAMB4_S2_S2		2
RAMB4_S2_S4		4
RAMB4_S2_S8		8
RAMB4_S2_S16		16
RAMB4_S4	4	N/A
RAMB4_S4_S4		4
RAMB4_S4_S8		8
RAMB4_S4_S16		16
RAMB4_S8	8	N/A
RAMB4_S8_S8		8
RAMB4_S8_S16		16
RAMB4_S16	16	N/A
RAMB4_S16_S16		16

Port Signals

Each block SelectRAM+ port operates independently of the others while accessing the same set of 4096 memory cells.

Table 15 describes the depth and width aspect ratios for the block SelectRAM+ memory.

Table 15: **Block SelectRAM+ Port Aspect Ratios**

Width	Depth	ADDR Bus	Data Bus
1	4096	ADDR<11:0>	DATA<0>
2	2048	ADDR<10:0>	DATA<1:0>
4	1024	ADDR<9:0>	DATA<3:0>
8	512	ADDR<8:0>	DATA<7:0>
16	256	ADDR<7:0>	DATA<15:0>

Clock—CLK[A/B]

Each port is fully synchronous with independent clock pins. All port input pins have setup time referenced to the port CLK pin. The data output bus has a clock-to-out time referenced to the CLK pin.

Enable—EN[A/B]

The enable pin affects the read, write and reset functionality of the port. Ports with an inactive enable pin keep the output pins in the previous state and do not write data to the memory cells.

Write Enable—WE[A/B]

Activating the write enable pin allows the port to write to the memory cells. When active, the contents of the data input bus are written to the RAM at the address pointed to by the address bus, and the new data also reflects on the data out bus. When inactive, a read operation occurs and the contents of the memory cells referenced by the address bus reflect on the data out bus.

Reset—RST[A/B]

The reset pin forces the data output bus latches to zero synchronously. This does not affect the memory cells of the RAM and does not disturb a write operation on the other port.

Address Bus—ADDR[A/B]<#:0>

The address bus selects the memory cells for read or write. The width of the port determines the required width of this bus as shown in Table 15.

Data In Bus—DI[A/B]<#:0>

The data in bus provides the new data value to be written into the RAM. This bus and the port have the same width, as shown in Table 15.

Data Output Bus—DO[A/B]<#:0>

The data out bus reflects the contents of the memory cells referenced by the address bus at the last active clock edge. During a write operation, the data out bus reflects the data in bus. The width of this bus equals the width of the port. The allowed widths appear in Table 15.

Inverting Control Pins

The four control pins (CLK, EN, WE and RST) for each port have independent inversion control as a configuration option.

Address Mapping

Each port accesses the same set of 4096 memory cells using an addressing scheme dependent on the width of the port.

The physical RAM location addressed for a particular width are described in the following formula (of interest only when the two ports use different aspect ratios).

$$Start = ((ADDR_{port} + 1) * Width_{port}) - 1$$

$$End = ADDR_{port} * Width_{port}$$

Table 16 shows low order address mapping for each port width.

Table 16: **Port Address Mapping**

Port Width	Port Addresses															
1	4095...	15	14	13	12	11	10	09	08	07	06	05	04	03	02	01	00
2	2047...	07		06		05		04		03		02		01		00	
4	1023...	03				02				01				00			
8	511...	01								00							
16	255...	00															

Creating Larger RAM Structures

The block SelectRAM+ columns have specialized routing to allow cascading blocks together with minimal routing delays. This achieves wider or deeper RAM structures with a smaller timing penalty than when using normal routing channels.

Location Constraints

Block SelectRAM+ instances can have LOC properties attached to them to constrain the placement. The block SelectRAM+ placement locations are separate from the CLB location naming convention, allowing the LOC properties to transfer easily from array to array.

The LOC properties use the following form.

LOC = RAMB4_R#C#

RAMB4_R0C0 is the upper left RAMB4 location on the device.

Conflict Resolution

The block SelectRAM+ memory is a true dual-read/write port RAM that allows simultaneous access of the same memory cell from both ports. When one port writes to a given memory cell, the other port must not address that memory cell (for a write or a read) within the clock-to-clock setup window. The following lists specifics of port and memory cell write conflict resolution.

- If both ports write to the same memory cell simultaneously, violating the clock-to-clock setup requirement, consider the data stored as invalid.
- If one port attempts a read of the same memory cell the other simultaneously writes, violating the clock-to-clock setup requirement, the following occurs.
  - The write succeeds
  - The data out on the writing port accurately reflects the data written.
  - The data out on the reading port is invalid.

Conflicts do not cause any physical damage.

Single Port Timing

Figure 33 shows a timing diagram for a single port of a block SelectRAM+ memory. The block SelectRAM+ AC switching characteristics are specified in the data sheet. The block SelectRAM+ memory is initially disabled.

At the first rising edge of the CLK pin, the ADDR, DI, EN, WE, and RST pins are sampled. The EN pin is High and the WE pin is Low indicating a read operation. The DO bus contains the contents of the memory location, 0x00, as indicated by the ADDR bus.

At the second rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN and WE pins are High indicating a write operation. The DO bus mirrors the DI bus. The DI bus is written to the memory location 0x0F.

At the third rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN pin is High and the WE pin is Low indicating a read operation. The DO bus contains the contents of the memory location 0x7E as indicated by the ADDR bus.

At the fourth rising edge of the CLK pin, the ADDR, DI, EN, WR, and RST pins are sampled again. The EN pin is Low indicating that the block SelectRAM+ memory is now disabled. The DO bus retains the last value.

Dual Port Timing

Figure 34 shows a timing diagram for a true dual-port read/write block SelectRAM+ memory. The clock on port A has a longer period than the clock on Port B. The timing parameter T_{BCCS}, (clock-to-clock set-up) is shown on this diagram. The parameter, T_{BCCS} is violated once in the diagram. All other timing parameters are identical to the single port version shown in Figure 33.

T_{BCCS} is only of importance when the address of both ports are the same and at least one port is performing a write operation. When the clock-to-clock set-up parameter is violated for a WRITE-WRITE condition, the contents of the memory at that location are invalid. When the clock-to-clock set-up parameter is violated for a WRITE-READ condition, the contents of the memory are correct, but the read port has invalid data.

At the first rising edge of the CLKA, memory location 0x00 is to be written with the value 0xAAAA and is mirrored on the DOA bus. The last operation of Port B was a read to the same memory location 0x00. The DOB bus of Port B does not change with the new value on Port A, and retains the last read value. A short time later, Port B executes another read to memory location 0x00, and the DOB bus now reflects the new memory value written by Port A.

At the second rising edge of CLKA, memory location 0x7E is written with the value 0x9999 and is mirrored on the DOA bus. Port B then executes a read operation to the same memory location without violating the T_{BCCS} parameter and the DOB reflects the new memory values written by Port A.

At the third rising edge of CLKA, the T_{BCCS} parameter is violated with two writes to memory location 0x0F. The DOA and DOB busses reflect the contents of the DIA and DIB busses, but the stored value at 0x0F is invalid.

At the fourth rising edge of CLKA, a read operation is performed at memory location 0x0F and invalid data is present on the DOA bus. Port B also executes a read operation to memory location 0x0F and also reads invalid data.

At the fifth rising edge of CLKA a read operation is performed that does not violate the T_{BCCS} parameter to the previous write of 0x7E by Port B. THe DOA bus reflects the recently written value by Port B.

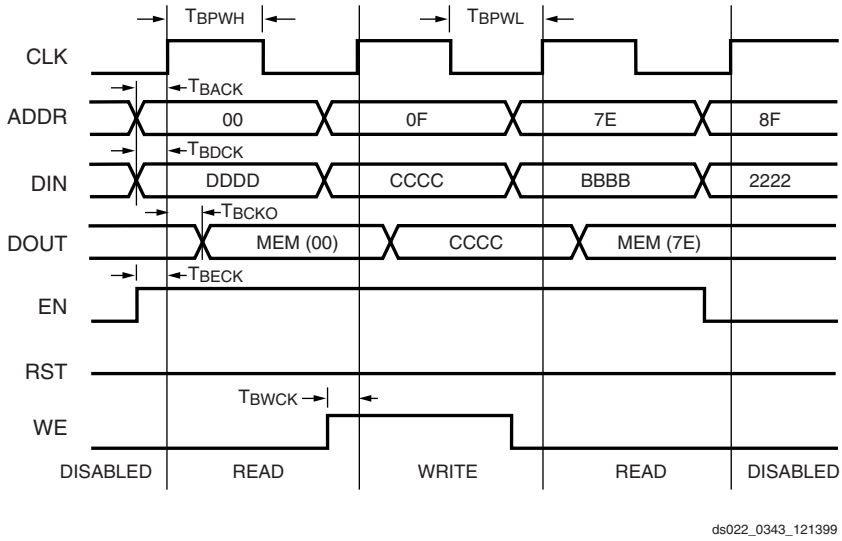


Figure 33: **Timing Diagram for Single Port Block SelectRAM+ Memory**

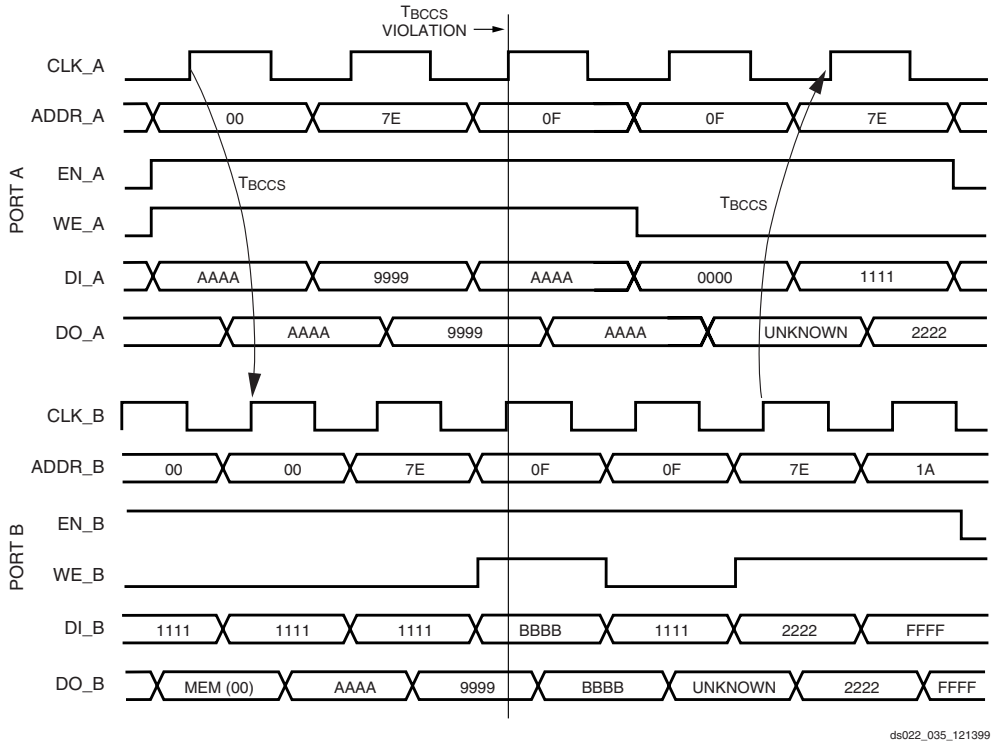


Figure 34: **Timing Diagram for a True Dual-port Read/Write Block SelectRAM+ Memory**

Initialization

The block SelectRAM+ memory can initialize during the device configuration sequence. The 16 initialization properties of 64 hex values each (a total of 4096 bits) set the initialization of each RAM. These properties appear in Table 17. Any initialization properties not explicitly set configure as zeros. Partial initialization strings pad with zeros. Initialization strings greater than 64 hex values generate an error. The RAMs can be simulated with the initialization values using generics in VHDL simulators and parameters in Verilog simulators.

Initialization in VHDL and Synopsys

The block SelectRAM+ structures can be initialized in VHDL for both simulation and synthesis for inclusion in the EDIF output file. The simulation of the VHDL code uses a generic to pass the initialization. Synopsys FPGA compiler does not presently support generics. The initialization values instead attach as attributes to the RAM by a built-in Synopsys dc_script. The translate_off statement stops synthesis translation of the generic statements. The following code illustrates a module that employs these techniques.

Table 17: **RAM Initialization Properties**

Property	Memory Cells
INIT_00	255 to 0
INIT_01	511 to 256
INIT_02	767 to 512
INIT_03	1023 to 768
INIT_04	1279 to 1024
INIT_05	1535 to 1280
INIT_06	1791 to 2047
INIT_07	2047 to 1792
INIT_08	2303 to 2048
INIT_09	2559 to 2304
INIT_0a	2815 to 2560
INIT_0b	3071 to 2816
INIT_0c	3327 to 3072
INIT_0d	3583 to 3328
INIT_0e	3839 to 3584
INIT_0f	4095 to 3840

Initialization in Verilog and Synopsys

The block SelectRAM+ structures can be initialized in Verilog for both simulation and synthesis for inclusion in the EDIF output file. The simulation of the Verilog code uses a defparam to pass the initialization. The Synopsys FPGA compiler does not presently support defparam. The initialization values instead attach as attributes to the RAM by a built-in Synopsys dc_script. The translate_off statement stops synthesis translation of the defparam statements. The following code illustrates a module that employs these techniques.

Design Examples

Creating a 32-bit Single-Port RAM

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single port, 128 deep by 32-bit wide RAM to be created using a single block SelectRAM+ cell as shown in Figure 35.

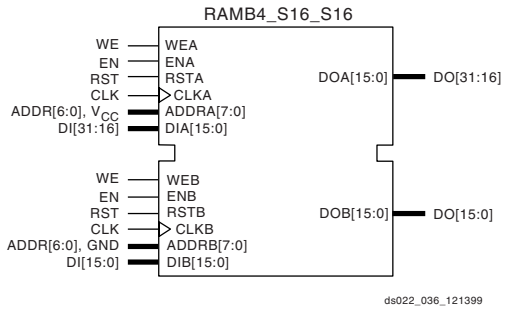


Figure 35: **Single Port 128 x 32 RAM**

Interleaving the memory space, setting the LSB of the address bus of Port A to 1 (V_{CC}), and the LSB of the address bus of Port B to 0 (GND), allows a 32-bit wide single port RAM to be created.

Creating Two Single-Port RAMs

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single RAM to be split into two single port memories of 2K bits each as shown in Figure 36.

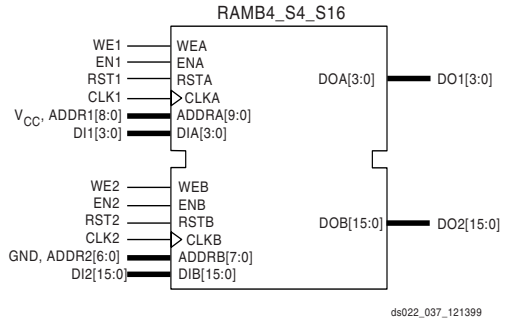


Figure 36: **512 x 4 RAM and 128 x 16 RAM**

In this example, a 512K x 4 RAM (Port A) and a 128 x 16 RAM (Port B) are created out of a single block SelectRAM+. The address space for the RAM is split by fixing the MSB of Port A to 1 (V_{CC}) for the upper 2K bits and the MSB of Port B to 0 (GND) for the lower 2K bits.

Block Memory Generation

The CoreGen program generates memory structures using the block SelectRAM+ features. This program outputs VHDL or Verilog simulation code templates and an EDIF file for inclusion in a design.

VHDL Initialization Example

```
library IEEE;
use IEEE.std_logic_1164.all;

entity MYMEM is
port (CLK, WE:in std_logic;
ADDR: in std_logic_vector(8 downto 0);
DIN: in std_logic_vector(7 downto 0);
DOUT: out std_logic_vector(7 downto 0));
end MYMEM;

architecture BEHAVE of MYMEM is
signal logic0, logic1: std_logic;

component RAMB4_S8
--synopsys translate_off
generic( INIT_00,INIT_01, INIT_02, INIT_03, INIT_04, INIT_05, INIT_06, INIT_07,
INIT_08, INIT_09, INIT_0a, INIT_0b, INIT_0c, INIT_0d, INIT_0e, INIT_0f : BIT_VECTOR(255
downto 0)
:= X"0000000000000000000000000000000000000000000000000000000000000000");
--synopsys translate_on
port (WE, EN, RST, CLK: in STD_LOGIC;
ADDR: in STD_LOGIC_VECTOR(8 downto 0);
DI: in STD_LOGIC_VECTOR(7 downto 0);
DO: out STD_LOGIC_VECTOR(7 downto 0));
end component;

--synopsys dc_script_begin
--set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
--set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
--synopsys dc_script_end

begin
logic0 <='0';
logic1 <='1';

ram0: RAMB4_S8
--synopsys translate_off
generic map (

INIT_00 => X"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF",
INIT_01 => X"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210")
--synopsys translate_on
port map (WE=>WE, EN=>logic1, RST=>logic0, CLK=>CLK,ADDR=>ADDR, DI=>DIN, DO=>DOUT);

end BEHAVE;
```

Verilog Initialization Example

```
module MYMEM (CLK, WE, ADDR, DIN, DOUT);
input CLK, WE;
input [8:0] ADDR;
input [7:0] DIN;
output [7:0] DOUT;

wire logic0, logic1;

//synopsys dc_script_begin
//set_attribute ram0 INIT_00
"0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF" -type string
//set_attribute ram0 INIT_01
"FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210" -type string
//synopsys dc_script_end

assign logic0 = 1'b0;
assign logic1 = 1'b1;

RAMB4_S8 ram0 (.WE(WE), .EN(logic1), .RST(logic0), .CLK(CLK), .ADDR(ADDR), .DI(DIN),
.DO(DOUT));
//synopsys translate_off
defparam ram0.INIT_00 =
256h'0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF0123456789ABCDEF;
defparam ram0.INIT_01 =
256h'FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210FEDCBA9876543210;
//synopsys translate_on
endmodule
```

Using SelectIO

The Virtex-E FPGA series includes a highly configurable, high-performance I/O resource, called SelectIO to provide support for a wide variety of I/O standards. The SelectIO resource is a robust set of features including programmable control of output drive strength, slew rate, and input delay and hold time. Taking advantage of the flexibility and SelectIO features and the design considerations described in this document can improve and simplify system level design.

Introduction

As FPGAs continue to grow in size and capacity, the larger and more complex systems designed for them demand an increased variety of I/O standards. Furthermore, as system clock speeds continue to increase, the need for high performance I/O becomes more important.

While chip-to-chip delays have an increasingly substantial impact on overall system speed, the task of achieving the desired system performance becomes more difficult with the proliferation of low-voltage I/O standards. SelectIO, the revolutionary input/output resources of Virtex-E devices, resolve this potential problem by providing a highly configurable, high-performance alternative to the I/O resources of more conventional programmable devices. Virtex-E SelectIO features combine the flexibility and time-to-market advantages of programmable logic with the high performance previously available only with ASICs and custom ICs.

Each SelectIO block can support up to 20 I/O standards. Supporting such a variety of I/O standards allows the support of a wide variety of applications, from general purpose standard applications to high-speed low-voltage memory busses.

SelectIO blocks also provide selectable output drive strengths and programmable slew rates for the LVTTL output buffers, as well as an optional, programmable weak pull-up, weak pull-down, or weak "keeper" circuit ideal for use in external bussing applications.

Each Input/Output Block (IOB) includes three registers, one each for the input, output, and 3-state signals within the IOB. These registers are optionally configurable as either a D-type flip-flop or as a level sensitive latch.

The input buffer has an optional delay element used to guarantee a zero hold time requirement for input signals registered within the IOB.

The Virtex-E SelectIO features also provide dedicated resources for input reference voltage (V_{REF}) and output source voltage (V_{CCO}), along with a convenient banking system that simplifies board design.

By taking advantage of the built-in features and wide variety of I/O standards supported by the SelectIO features, system-level design and board design can be greatly simplified and improved.

Fundamentals

Modern bus applications, pioneered by the largest and most influential companies in the digital electronics industry, are commonly introduced with a new I/O standard tailored specifically to the needs of that application. The bus I/O standards provide specifications to other vendors who create products designed to interface with these applications. Each standard often has its own specifications for current, voltage, I/O buffering, and termination techniques.

The ability to provide the flexibility and time-to-market advantages of programmable logic is increasingly dependent on the capability of the programmable logic device to support an ever increasing variety of I/O standards

The SelectIO resources feature highly configurable input and output buffers which provide support for a wide variety of I/O standards. As shown in Table 18, each buffer type can support a variety of voltage requirements.

Table 18: **Virtex-E Supported I/O Standards**

I/O Standard	Output V_{CCO}	Input V_{CCO}	Input V_{REF}	Board Termination Voltage (V_{TT})
LVTTL	3.3	3.3	N/A	N/A
LVCMOS2	2.5	2.5	N/A	N/A
LVCMOS18	1.8	1.8	N/A	N/A
SSTL3 I & II	3.3	N/A	1.50	1.50
SSTL2 I & II	2.5	N/A	1.25	1.25
GTL	N/A	N/A	0.80	1.20
GTL+	N/A	N/A	1.0	1.50
HSTL I	1.5	N/A	0.75	0.75
HSTL III & IV	1.5	N/A	0.90	1.50
CTT	3.3	N/A	1.50	1.50
AGP-2X	3.3	N/A	1.32	N/A
PCI33_3	3.3	3.3	N/A	N/A
PCI66_3	3.3	3.3	N/A	N/A
BLVDS & LVDS	2.5	N/A	N/A	N/A
LVPECL	3.3	N/A	N/A	N/A

Overview of Supported I/O Standards

This section provides a brief overview of the I/O standards supported by all Virtex-E devices.

While most I/O standards specify a range of allowed voltages, this document records typical voltage values only. Detailed information on each specification can be found on the Electronic Industry Alliance Jedec website at:

http://www.jedec.org

LVTTL — Low-Voltage TTL

The Low-Voltage TTL, or LVTTL standard is a general purpose EIA/JESDSA standard for 3.3V applications that uses an LVTTL input buffer and a Push-Pull output buffer. This standard requires a 3.3V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a termination voltage (V_{TT}).

LVCMOS2 — Low-Voltage CMOS for 2.5V

The Low-Voltage CMOS for 2.5V or lower, or LVCMOS2 standard is an extension of the LVCMOS standard (JESD 8-5) used for general purpose 2.5V applications. This standard requires a 2.5V output source voltage (V_{CCO}), but does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}).

LVCMOS18 — 1.8V Low Voltage CMOS

This standard is an extension of the LVCMOS standard. It is used in general purpose 1.8V applications. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required.

PCI — Peripheral Component Interface

The Peripheral Component Interface, or PCI standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses a LVTTL input buffer and a Push-Pull output buffer. This standard does not require the use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}), however, it does require a 3.3V output source voltage (V_{CCO}).

GTL — Gunning Transceiver Logic Terminated

The Gunning Transceiver Logic, or GTL standard is a high-speed bus standard (JESD 8.3) invented by Xerox. Xilinx has implemented the terminated variation for this standard. This standard requires a differential amplifier input buffer and a Open Drain output buffer.

GTL+ — Gunning Transceiver Logic Plus

The Gunning Transceiver Logic Plus, or GTL+ standard is a high-speed bus standard (JESD 8.3) first used by the Pentium Pro processor.

HSTL — High-Speed Transceiver Logic

The High-Speed Transceiver Logic, or HSTL standard is a general purpose high-speed, 1.5V bus standard sponsored by IBM (EIA/JESD 8-6). This standard has four variations or classes. SelectIO devices support Class I, III, and IV. This

standard requires a Differential Amplifier input buffer and a Push-Pull output buffer.

SSTL3 — Stub Series Terminated Logic for 3.3V

The Stub Series Terminated Logic for 3.3V, or SSTL3 standard is a general purpose 3.3V memory bus standard also sponsored by Hitachi and IBM (JESD 8-8). This standard has two classes, I and II. SelectIO devices support both classes for the SSTL3 standard. This standard requires a Differential Amplifier input buffer and an Push-Pull output buffer.

SSTL2 — Stub Series Terminated Logic for 2.5V

The Stub Series Terminated Logic for 2.5V, or SSTL2 standard is a general purpose 2.5V memory bus standard sponsored by Hitachi and IBM (JESD 8-9). This standard has two classes, I and II. SelectIO devices support both classes for the SSTL2 standard. This standard requires a Differential Amplifier input buffer and an Push-Pull output buffer.

CTT — Center Tap Terminated

The Center Tap Terminated, or CTT standard is a 3.3V memory bus standard sponsored by Fujitsu (JESD 8-4). This standard requires a Differential Amplifier input buffer and a Push-Pull output buffer.

AGP-2X — Advanced Graphics Port

The Intel AGP standard is a 3.3V Advanced Graphics Port-2X bus standard used with the Pentium II processor for graphics applications. This standard requires a Push-Pull output buffer and a Differential Amplifier input buffer.

LVDS — Low Voltage Differential Signal

LVDS is a differential I/O standard. It requires that one data bit is carried through two signal lines. As with all differential signaling standards, LVDS has an inherent noise immunity over single-ended I/O standards. The voltage swing between two signal lines is approximately 350 mV. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required. LVDS requires the use of two pins per input or output. LVDS requires external resistor termination.

BLVDS — Bus LVDS

This standard allows for bidirectional LVDS communication between two or more devices. The external resistor termination is different than the one for standard LVDS.

LVPECL — Low Voltage Positive Emitter Coupled Logic

LVPECL is another differential I/O standard. It requires two signal lines for transmitting one data bit. This standard specifies two pins per input or output. The voltage swing between these two signal lines is approximately 850 mV. The use of a reference voltage (V_{REF}) or a board termination voltage (V_{TT}) is not required. The LVPECL standard requires external resistor termination.

Library Symbols

The Xilinx library includes an extensive list of symbols designed to provide support for the variety of SelectIO features. Most of these symbols represent variations of the five generic SelectIO symbols.

- IBUF (input buffer)
- IBUFG (global clock input buffer)
- OBUF (output buffer)
- OBUFT (3-state output buffer)
- IOBUF (input/output buffer)

IBUF

Signals used as inputs to the Virtex-E device must source an input buffer (IBUF) via an external input port. The generic Virtex-E IBUF symbol appears in Figure 37. The extension

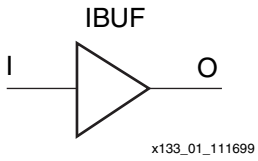


Figure 37: **Input Buffer (IBUF) Symbols**

to the base name defines which I/O standard the IBUF uses. The assumed standard is LVTTL when the generic IBUF has no specified extension.

The following list details the variations of the IBUF symbol:

- IBUF
- IBUF_LVCMOS2
- IBUF_PCI33_3
- IBUF_PCI66_3
- IBUF_GTL
- IBUF_GTLP
- IBUF_HSTL_I
- IBUF_HSTL_III
- IBUF_HSTL_IV
- IBUF_SSTL3_I
- IBUF_SSTL3_II
- IBUF_SSTL2_I
- IBUF_SSTL2_II
- IBUF_CTT
- IBUF_AGP
- IBUF_LVCMOS18
- IBUF_LVDS
- IBUF_LVPECL

When the IBUF symbol supports an I/O standard that requires a V_{REF}, the IBUF automatically configures as a differential amplifier input buffer. The V_{REF} voltage must be supplied on the V_{REF} pins. In the case of LVDS, LVPECL, and BLVDS, V_{REF} is not required.

The voltage reference signal is "banked" within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUF placement restrictions require that any differential amplifier input signals within a bank be of the same standard. How to specify a specific location for the IBUF via the LOC property is described below. Table 19 summarizes the Virtex-E input standards compatibility requirements.

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element by default activates to ensure a zero hold-time requirement. The NODELAY=TRUE property overrides this default.

When the IBUF does not drive a flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

Table 19: **Xilinx Input Standards Compatibility Requirements**

Rule 1	Standards with the same input V_{CCO}, output V_{CCO}, and V_{REF} can be placed within the same bank.

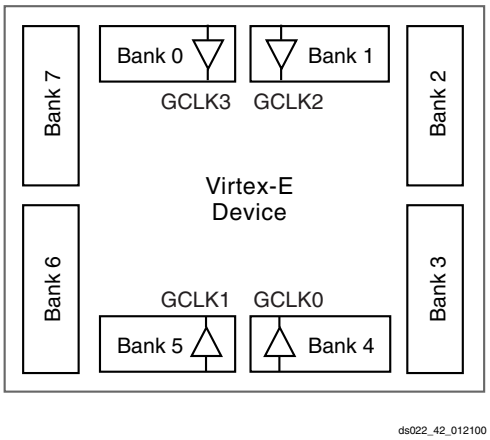


Figure 38: **Virtex-E I/O Banks**

IBUFG

Signals used as high fanout clock inputs to the Virtex-E device should drive a global clock input buffer (IBUFG) via an external input port in order to take advantage of one of the four dedicated global clock distribution networks. The output of the IBUFG symbol can drive only a CLKDLL, CLKDLLHF, or BUFG symbol. The generic Virtex-E IBUFG symbol appears in Figure 39.

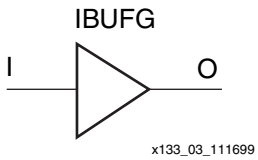


Figure 39: **Virtex-E Global Clock Input Buffer (IBUFG) Symbol**

The extension to the base name determines which I/O standard is used by the IBUFG. With no extension specified for the generic IBUFG symbol, the assumed standard is LVTTL.

The following list details variations of the IBUFG symbol.

- IBUFG
- IBUFG_LVCMOS2
- IBUFG_PCI33_3
- IBUFG_PCI66_3
- IBUFG_GTL
- IBUFG_GTLP
- IBUFG_HSTL_I
- IBUFG_HSTL_III
- IBUFG_HSTL_IV
- IBUFG_SSTL3_I
- IBUFG_SSTL3_II
- IBUFG_SSTL2_I
- IBUFG_SSTL2_II
- IBUFG_CTT
- IBUFG_AGP
- IBUFG_LVCMOS18
- IBUFG_LVDS
- IBUFG_LVPECL

When the IBUFG symbol supports an I/O standard that requires a differential amplifier input, the IBUFG automatically configures as a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}.

The voltage reference signal is "banked" within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IBUFG placement restrictions require any differential amplifier input signals within a bank be of the same standard. The LOC property can specify a location for the IBUFG.

As an added convenience, the BUFGP can be used to instantiate a high fanout clock input. The BUFGP symbol represents a combination of the LVTTL IBUFG and BUFG symbols, such that the output of the BUFGP can connect directly to the clock pins throughout the design.

Unlike previous architectures, the Virtex-E BUFGP symbol can only be placed in a global clock pad location. The LOC property can specify a location for the BUFGP.

OBUF

An OBUF must drive outputs through an external output port. The generic output buffer (OBUF) symbol appears in Figure 40.

The extension to the base name defines which I/O standard the OBUF uses. With no extension specified for the generic OBUF symbol, the assumed standard is slew rate limited LVTTL with 12 mA drive strength.

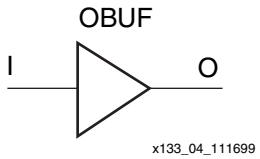


Figure 40: **Virtex-E Output Buffer (OBUF) Symbol**

The LVTTL OBUF additionally can support one of two slew rate modes to minimize bus transients. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals.

LVTTL output buffers have selectable drive strengths.

The format for LVTTL OBUF symbol names is as follows:

OBUF_<slew_rate>_<drive_strength>

where <slew_rate> is either F (Fast) or S (Slow), and <drive_strength> is specified in milliamps (2, 4, 6, 8, 12, 16, or 24).

The following list details variations of the OBUF symbol.

- OBUF
- OBUF_S_2
- OBUF_S_4
- OBUF_S_6
- OBUF_S_8
- OBUF_S_12
- OBUF_S_16
- OBUF_S_24
- OBUF_F_2
- OBUF_F_4
- OBUF_F_6
- OBUF_F_8
- OBUF_F_12
- OBUF_F_16
- OBUF_F_24
- OBUF_LVCMOS2
- OBUF_PCI33_3
- OBUF_PCI66_3
- OBUF_GTL
- OBUF_GTLP
- OBUF_HSTL_I
- OBUF_HSTL_III
- OBUF_HSTL_IV
- OBUF_SSTL3_I
- OBUF_SSTL3_II
- OBUF_SSTL2_I
- OBUF_SSTL2_II
- OBUF_CTT
- OBUF_AGP
- OBUF_LVCMOS18
- OBUF_LVDS
- OBUF_LVPECL

The Virtex-E series supports eight banks for the HQ packages. The CB packages support one V_{CCO} banks.

OBUF placement restrictions require that within a given V_{CCO} bank each OBUF share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within any V_{CCO} bank. Table 20 summarizes the Virtex-E output compatibility requirements. The LOC property can specify a location for the OBUF.

Table 20: **Output Standards Compatibility Requirements**

Rule 1	Only outputs with standards that share compatible V_{CCO} can be used within the same bank.
Rule 2	There are no placement restrictions for outputs with standards that do not require a V_{CCO}.
V_{CCO}	Compatible Standards
3.3	LVTTL, SSTL3_I, SSTL3_II, CTT, AGP, GTL, GTL+, PCI33_3, PCI66_3
2.5	SSTL2_I, SSTL2_II, LVCMOS2, GTL, GTL+
1.5	HSTL_I, HSTL_III, HSTL_IV, GTL, GTL+

OBUFT

The generic 3-state output buffer OBUFT (see Figure 41) typically implements 3-state outputs or bidirectional I/O.

The extension to the base name defines which I/O standard OBUFT uses. With no extension specified for the generic OBUFT symbol, the assumed standard is slew rate limited LVTTL with 12 mA drive strength.

The LVTTL OBUFT additionally can support one of two slew rate modes to minimize bus transients. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals.

LVTTL 3-state output buffers have selectable drive strengths.

The format for LVTTL OBUFT symbol names is as follows:

OBUFT_<*slew_rate*>_<*drive_strength*>

where <*slew_rate*> is either F (Fast) or S (Slow), and <*drive_strength*> is specified in mA (2, 4, 6, 8, 12, 16, 24).

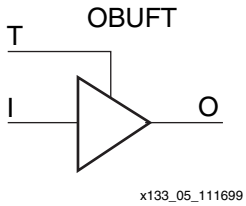


Figure 41: **3-State Output Buffer Symbol (OBUFT)**

The following list details variations of the OBUFT symbol.

- OBUFT
- OBUFT_S_2
- OBUFT_S_4
- OBUFT_S_6
- OBUFT_S_8
- OBUFT_S_12
- OBUFT_S_16
- OBUFT_S_24
- OBUFT_F_2
- OBUFT_F_4
- OBUFT_F_6
- OBUFT_F_8
- OBUFT_F_12
- OBUFT_F_16
- OBUFT_F_24
- OBUFT_LVCMOS2
- OBUFT_PCI33_3
- OBUFT_PCI66_3
- OBUFT_GTL
- OBUFT_GTLP
- OBUFT_HSTL_I
- OBUFT_HSTL_III
- OBUFT_HSTL_IV
- OBUFT_SSTL3_I
- OBUFT_SSTL3_II
- OBUFT_SSTL2_I
- OBUFT_SSTL2_II
- OBUFT_CTT
- OBUFT_AGP
- OBUFT_LVCMOS18
- OBUFT_LVDS
- OBUFT_LVPECL

The Virtex-E series supports eight banks for the HQ package. The CB package supports one V_{CCO} bank.

The SelectIO OBUFT placement restrictions require that within a given V_{CCO} bank each OBUFT share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within the same V_{CCO} bank.

The LOC property can specify a location for the OBUFT.

3-state output buffers and bidirectional buffers can have either a weak pull-up resistor, a weak pull-down resistor, or a weak "keeper" circuit. Control this feature by adding the appropriate symbol to the output net of the OBUFT (PULLUP, PULLDOWN, or KEEPER).

The weak "keeper" circuit requires the input buffer within the IOB to sample the I/O signal. So, OBUFTs programmed for an I/O standard that requires a V_{REF} have automatic placement of a V_{REF} in the bank with an OBUFT configured with a weak "keeper" circuit. This restriction does not affect most circuit design as applications using an OBUFT configured with a weak "keeper" typically implement a bidirectional I/O. In this case the IBUF (and the corresponding V_{REF}) are explicitly placed.

The LOC property can specify a location for the OBUFT.

IOBUF

Use the IOBUF symbol for bidirectional signals that require both an input buffer and a 3-state output buffer with an active high 3-state pin. The generic input/output buffer IOBUF appears in Figure 42.

The extension to the base name defines which I/O standard the IOBUF uses. With no extension specified for the generic IOBUF symbol, the assumed standard is LVTTL input buffer and slew rate limited LVTTL with 12 mA drive strength for the output buffer.

The LVTTL IOBUF additionally can support one of two slew rate modes to minimize bus transients. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals.

LVTTL bidirectional buffers have selectable output drive strengths.

The format for LVTTL IOBUF symbol names is as follows:

IOBUF_<*slew_rate*>_<*drive_strength*>

where <*slew_rate*> is either F (Fast) or S (Slow), and <*drive_strength*> is specified in mA (2, 4, 6, 8, 12, 16, 24).

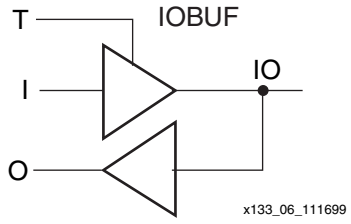


Figure 42: **Input/Output Buffer Symbol (IOBUF)**

The following list details variations of the IOBUF symbol.

- IOBUF
- IOBUF_S_2
- IOBUF_S_4
- IOBUF_S_6
- IOBUF_S_8
- IOBUF_S_12
- IOBUF_S_16
- IOBUF_S_24
- IOBUF_F_2
- IOBUF_F_4
- IOBUF_F_6
- IOBUF_F_8
- IOBUF_F_12
- IOBUF_F_16
- IOBUF_F_24
- IOBUF_LVCMOS2
- IOBUF_PCI33_3
- IOBUF_PCI66_3
- IOBUF_GTL
- IOBUF_GTLP
- IOBUF_HSTL_I
- IOBUF_HSTL_III
- IOBUF_HSTL_IV
- IOBUF_SSTL3_I
- IOBUF_SSTL3_II
- IOBUF_SSTL2_I
- IOBUF_SSTL2_II
- IOBUF_CTT
- IOBUF_AGP
- IOBUF_LVCMOS18
- IOBUF_LVDS
- IOBUF_LVPECL

When the IOBUF symbol used supports an I/O standard that requires a differential amplifier input, the IOBUF automatically configures with a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}.

The voltage reference signal is "banked" within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38, page 33 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IOBUF placement restrictions require any differential amplifier input signals within a bank be of the same standard.

The Virtex-E series supports eight banks for the HQ package. The CB package supports one V_{CCO} bank.

Additional restrictions on the Virtex-E SelectIO IOBUF placement require that within a given V_{CCO} bank each IOBUF must share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within the same V_{CCO} bank. The LOC property can specify a location for the IOBUF.

An optional delay element is associated with the input path in each IOBUF. When the IOBUF drives an input flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Override this default with the NODELAY=TRUE property.

In the case when the IOBUF does not drive an input flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

3-state output buffers and bidirectional buffers can have either a weak pull-up resistor, a weak pull-down resistor, or a weak "keeper" circuit. Control this feature by adding the appropriate symbol to the output net of the IOBUF (PULLUP, PULLDOWN, or KEEPER).

SelectIO Properties

Access to some of the SelectIO features (for example, location constraints, input delay, output drive strength, and slew rate) is available through properties associated with these features.

Input Delay Properties

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Use the NODELAY=TRUE property to override this default.

In the case when the IBUF does not drive a flip-flop within the IOB, the delay element by default de-activates to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

IOB Flip-Flop/Latch Property

The Virtex-E series I/O Block (IOB) includes an optional register on the input path, an optional register on the output path, and an optional register on the 3-state control pin. The design implementation software automatically takes advantage of these registers when the following option for the Map program is specified.

map –pr b <filename>

Alternatively, the IOB = TRUE property can be placed on a register to force the mapper to place the register in an IOB.

Location Constraints

Specify the location of each SelectIO symbol with the location constraint LOC attached to the SelectIO symbol. The

external port identifier indicates the value of the location constrain. The format of the port identifier depends on the package chosen for the specific design.

The LOC properties use the following form:

LOC=A42

LOC=P37

Output Slew Rate Property

As mentioned above, a variety of symbol names provide the option of choosing the desired slew rate for the output buffers. In the case of the LVTTL output buffers (OBUF, OBUFT, and IOBUF), slew rate control can be alternatively programed with the SLEW= property. By default, the slew rate for each output buffer is reduced to minimize power bus transients when switching non-critical signals. The SLEW= property has one of the two following values.

SLEW=SLOW

SLEW=FAST

Output Drive Strength Property

The desired output drive strength can be additionally specified by choosing the appropriate library symbol. The Xilinx library also provides an alternative method for specifying this feature. For the LVTTL output buffers (OBUF, OBUFT, and IOBUF, the desired drive strength can be specified with the DRIVE= property. This property could have one of the following seven values.

DRIVE=2
DRIVE=4
DRIVE=6
DRIVE=8
DRIVE=12 (Default)
DRIVE=16
DRIVE=24

Design Considerations

Reference Voltage (V_{REF}) Pins

Low-voltage I/O standards with a differential amplifier input buffer require an input reference voltage (V_{REF}). Provide the V_{REF} as an external signal to the device.

The voltage reference signal is "banked" within the device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

Within each V_{REF} bank, any input buffers that require a V_{REF} signal must be of the same type. Output buffers of any type and input buffers can be placed without requiring a reference voltage within the same V_{REF} bank.

Output Drive Source Voltage (V_{CCO}) Pins

Many of the low voltage I/O standards supported by SelectIO devices require a different output drive source voltage (V_{CCO}). As a result each device can often have to support multiple output drive source voltages.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Output buffers within a given V_{CCO} bank must share the same output drive source voltage. Input buffers for LVTTL, LVCMOS2, LVCMOS18, PCI33_3, and PCI 66_3 use the V_{CCO} voltage for Input V_{CCO} voltage.

Transmission Line Effects

The delay of an electrical signal along a wire is dominated by the rise and fall times when the signal travels a short distance. Transmission line delays vary with inductance and capacitance, but a well-designed board can experience delays of approximately 180 ps per inch.

Transmission line effects, or reflections, typically start at 1.5" for fast (1.5 ns) rise and fall times. Poor (or non-existent) termination or changes in the transmission line impedance cause these reflections and can cause additional delay in longer traces. As system speeds continue to increase, the effect of I/O delays can become a limiting factor and therefore transmission line termination becomes increasingly more important.

Termination Techniques

A variety of termination techniques reduce the impact of transmission line effects.

The following are output termination techniques:

- None
- Series
- Parallel (Shunt)
- Series and Parallel (Series-Shunt)

Input termination techniques include the following.

- None
- Parallel (Shunt)

These termination techniques can be applied in any combination. A generic example of each combination of termination methods appears in Figure 43.

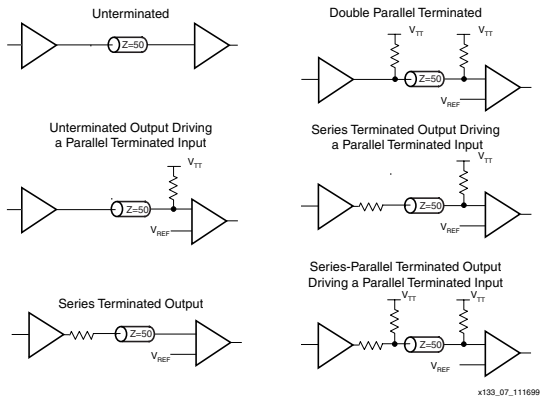


Figure 43: **Overview of Standard Input and Output Termination Methods**

Simultaneous Switching Guidelines

Ground bounce can occur with high-speed digital ICs when multiple outputs change states simultaneously, causing undesired transient behavior on an output, or in the internal logic. This problem is also referred to as the Simultaneous Switching Output (SSO) problem.

Ground bounce is primarily due to current changes in the combined inductance of ground pins, bond wires, and ground metallization. The IC internal ground level deviates from the external system ground level for a short duration (a few nanoseconds) after multiple outputs change state simultaneously.

Ground bounce affects stable Low outputs and all inputs because they interpret the incoming signal by comparing it to the internal ground. If the ground bounce amplitude exceeds the actual instantaneous noise margin, then a non-changing input can be interpreted as a short pulse with a polarity opposite to the ground bounce.

Table 21 provides guidelines for the maximum number of simultaneously switching outputs allowed per output power/ground pair to avoid the effects of ground bounce. See Table 22 for the number of effective output power/ground pairs for each Virtex-E device and package combination.

Table 21: **Guidelines for Max Number of Simultaneously Switching Outputs per Power/Ground Pair**

Standard	Outputs
LVTTL Slow Slew Rate, 2 mA drive	68
LVTTL Slow Slew Rate, 4 mA drive	41
LVTTL Slow Slew Rate, 6 mA drive	29
LVTTL Slow Slew Rate, 8 mA drive	22

Table 21: **Guidelines for Max Number of Simultaneously Switching Outputs per Power/Ground Pair *(Continued)***

Standard	Outputs
LVTTL Slow Slew Rate, 12 mA drive	17
LVTTL Slow Slew Rate, 16 mA drive	14
LVTTL Slow Slew Rate, 24 mA drive	9
LVTTL Fast Slew Rate, 2 mA drive	40
LVTTL Fast Slew Rate, 4 mA drive	24
LVTTL Fast Slew Rate, 6 mA drive	17
LVTTL Fast Slew Rate, 8 mA drive	13
LVTTL Fast Slew Rate, 12 mA drive	10
LVTTL Fast Slew Rate, 16 mA drive	8
LVTTL Fast Slew Rate, 24 mA drive	5
LVCMOS2	10
PCI	8
GTL	4
GTL+	4
HSTL Class I	18
HSTL Class III	9
HSTL Class IV	5
SSTL2 Class I	15
SSTL2 Class II	10
SSTL3 Class I	11
SSTL3 Class II	7
CTT	14
AGP	9

Notes:
1. This analysis assumes a 35 pF load for each output.

Table 22: **Virtex-E Equivalent Power/Ground Pairs**

Pkg/Part	XQV600E	XQV1000E	XQV2000E
CB228	27	-	-
BG432	40	-	-
BG560	-	56	60
CG560	-	56	-
FG1156	-	-	120

Application Examples

Creating a design with the SelectIO features requires the instantiation of the desired library symbol within the design code. At the board level, designers need to know the termination techniques required for each I/O standard.

This section describes some common application examples illustrating the termination techniques recommended by each of the standards supported by the SelectIO features.

Termination Examples

Circuit examples involving typical termination techniques for each of the SelectIO standards follow. For a full range of accepted values for the DC voltage specifications for each standard, refer to the table associated with each figure.

The resistors used in each termination technique example and the transmission lines depicted represent board level components and are not meant to represent components on the device.

GTL

A sample circuit illustrating a valid termination technique for GTL is shown in Figure 44.

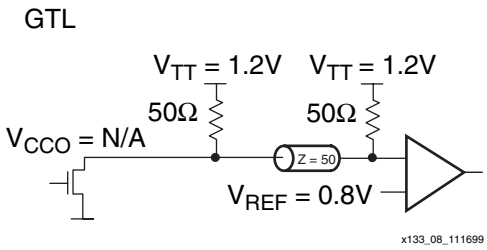


Figure 44: **Terminated GTL**

Table 23 lists DC voltage specifications.

Table 23: **GTL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	-	N/A	-
$V_{REF} = N \times V_{TT}$ (1)	0.74	0.8	0.86
V_{TT}	1.14	1.2	1.26
$V_{IH} = V_{REF} + 0.05$	0.79	0.85	-
$V_{IL} = V_{REF} - 0.05$	-	0.75	0.81
V_{OH}	-	-	-
V_{OL}	-	0.2	0.4
I_{OH} at V_{OH} (mA)	-	-	-
I_{OL} at V_{OL} (mA) at 0.4V	32	-	-
I_{OL} at V_{OL} (mA) at 0.2V	-	-	40

Notes:
1. N must be greater than or equal to 0.653 and less than or equal to 0.68.

GTL+

A sample circuit illustrating a valid termination technique for GTL+ appears in Figure 45. DC voltage specifications appear in Table 24.

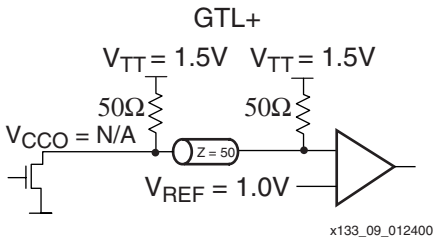


Figure 45: **Terminated GTL+**

Table 24: **GTL+ Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	-	-	-
$V_{REF} = N \times V_{TT}$ (1)	0.88	1.0	1.12
V_{TT}	1.35	1.5	1.65
$V_{IH} = V_{REF} + 0.1$	0.98	1.1	-
$V_{IL} = V_{REF} - 0.1$	-	0.9	1.02
V_{OH}	-	-	-
V_{OL}	0.3	0.45	0.6
I_{OH} at V_{OH} (mA)	-	-	-
I_{OL} at V_{OL} (mA) at 0.6V	36	-	-
I_{OL} at V_{OL} (mA) at 0.3V	-	-	48

Notes:
1. N must be greater than or equal to 0.653 and less than or equal to 0.68.

HSTL

A sample circuit illustrating a valid termination technique for HSTL_I appears in Figure 46. A sample circuit illustrating a valid termination technique for HSTL_III appears in Figure 47.

Table 25: **HSTL Class I Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	0.68	0.75	0.90
V_{TT}	-	$V_{CCO} \times 0.5$	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}			0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	8	-	-

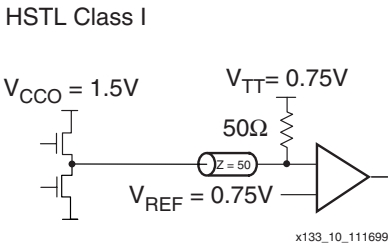


Figure 46: **Terminated HSTL Class I**

Table 26: **HSTL Class III Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF} (1)	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	24	-	-

Notes:
1. Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user."

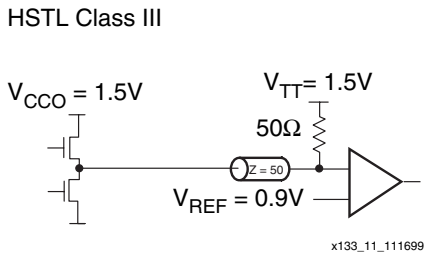


Figure 47: **Terminated HSTL Class III**

A sample circuit illustrating a valid termination technique for HSTL_IV appears in Figure 48.

Table 27: **HSTL Class IV Voltage Specification**

Parameter	Min	Typ	Max
V_{CCO}	1.40	1.50	1.60
V_{REF}	-	0.90	-
V_{TT}	-	V_{CCO}	-
V_{IH}	$V_{REF} + 0.1$	-	-
V_{IL}	-	-	$V_{REF} - 0.1$
V_{OH}	$V_{CCO} - 0.4$	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	48	-	-

Notes:
1. Per EIA/JESD8-6, "The value of V_{REF} is to be selected by the user to provide optimum noise margin in the use conditions specified by the user.

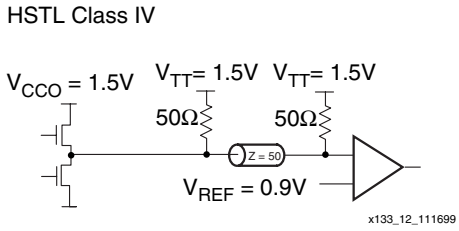


Figure 48: **Terminated HSTL Class IV**

SSTL3_I

A sample circuit illustrating a valid termination technique for SSTL3_I appears in Figure 49. DC voltage specifications appear in Table 28.

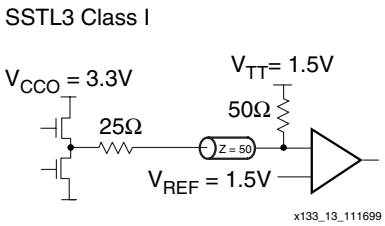


Figure 49: **Terminated SSTL3 Class I**

Table 28: **SSTL3_I Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	**3.0**	**3.3**	**3.6**
$V_{REF} = 0.45 \times V_{CCO}$	1.3	1.5	1.7
$V_{TT} = V_{REF}$	1.3	1.5	1.7
$V_{IH} = V_{REF} + 0.2$	1.5	1.7	3.9(1)
$V_{IL} = V_{REF} - 0.2$	–0.3(2)	1.3	1.5
$V_{OH} = V_{REF} + 0.6$	1.9	-	-
$V_{OL} = V_{REF} - 0.6$	-	-	1.1
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	8	-	-

Notes:
1. V_{IH} maximum is V_{CCO} + 0.3
2. V_{IL} minimum does not conform to the formula

SSTL3_II

A sample circuit illustrating a valid termination technique for SSTL3_II appears in Figure 50. DC voltage specifications appear in Table 29.

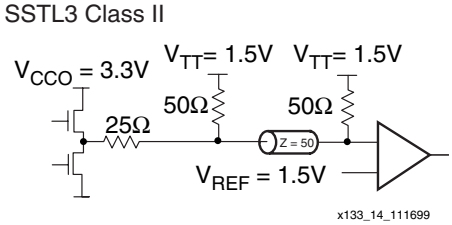


Figure 50: **Terminated SSTL3 Class II**

Table 29: **SSTL3_II Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
$V_{REF} = 0.45 \times V_{CCO}$	1.3	1.5	1.7
$V_{TT} = V_{REF}$	1.3	1.5	1.7
$V_{IH} = V_{REF} + 0.2$	1.5	1.7	3.9(1)
$V_{IL} = V_{REF} - 0.2$	–0.3(2)	1.3	1.5
$V_{OH} = V_{REF} + 0.8$	2.1	-	-
$V_{OL} = V_{REF} - 0.8$	-	-	0.9
I_{OH} at V_{OH} (mA)	–16	-	-
I_{OL}at V_{OL} (mA)	16	-	-

Notes:
1. V_{IH} maximum is V_{CCO} + 0.3
2. V_{IL} minimum does not conform to the formula

SSTL2_I

A sample circuit illustrating a valid termination technique for SSTL2_I appears in Figure 51. DC voltage specifications appear in Table 30.

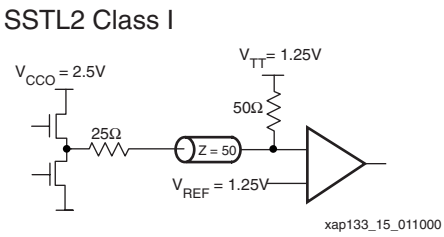


Figure 51: **Terminated SSTL2 Class I**

Table 30: **SSTL2_I Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
$V_{REF} = 0.5 \times V_{CCO}$	1.15	1.25	1.35
$V_{TT} = V_{REF} + N$(1)	1.11	1.25	1.39
$V_{IH} = V_{REF} + 0.18$	1.33	1.43	3.0(2)
$V_{IL} = V_{REF} - 0.18$	–0.3(3)	1.07	1.17
$V_{OH} = V_{REF} + 0.61$	1.76	-	-
$V_{OL} = V_{REF} - 0.61$	-	-	0.74

Table 30: **SSTL2_I Voltage Specifications**

Parameter	Min	Typ	Max
I_{OH} at V_{OH} (mA)	–7.6	-	-
I_{OL}at V_{OL} (mA)	7.6	-	-

Notes:
1. N must be greater than or equal to –0.04 and less than or equal to 0.04.
2. V_{IH} maximum is V_{CCO} + 0.3.
3. V_{IL} minimum does not conform to the formula.

SSTL2_II

A sample circuit illustrating a valid termination technique for SSTL2_II appears in Figure 52. DC voltage specifications appear in Table 31.

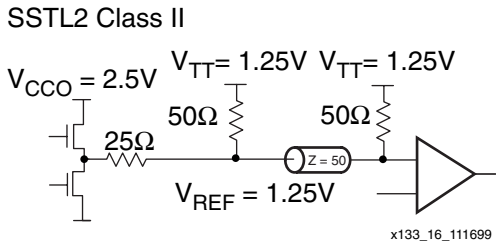


Figure 52: **Terminated SSTL2 Class II**

Table 31: **SSTL2_II Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
$V_{REF} = 0.5 \times V_{CCO}$	1.15	1.25	1.35
$V_{TT} = V_{REF} + N^{(1)}$	1.11	1.25	1.39
$V_{IH} = V_{REF} + 0.18$	1.33	1.43	3.0(2)
$V_{IL} = V_{REF} – 0.18$	–0.3(3)	1.07	1.17
$V_{OH} = V_{REF} + 0.8$	1.95	-	-
$V_{OL} = V_{REF} – 0.8$	-	-	0.55
I_{OH} at V_{OH} (mA)	–15.2	-	-
I_{OL}at V_{OL} (mA)	15.2	-	-

Notes:
1. N must be greater than or equal to -0.04 and less than or equal to 0.04.
2. V_{IH} maximum is V_{CCO} + 0.3.
3. V_{IL} minimum does not conform to the formula.

CTT

A sample circuit illustrating a valid termination technique for CTT appear in Figure 53. DC voltage specifications appear in Table 32.

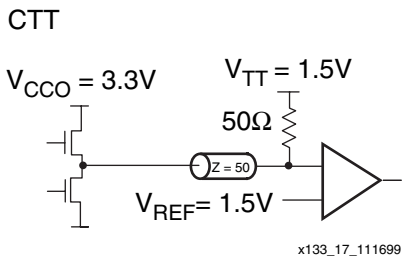


Figure 53: **Terminated CTT**

Table 32: **CTT Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.05(1)	3.3	3.6
V_{REF}	1.35	1.5	1.65
V_{TT}	1.35	1.5	1.65
$V_{IH} = V_{REF} + 0.2$	1.55	1.7	-
$V_{IL} = V_{REF} – 0.2$	-	1.3	1.45
$V_{OH} = V_{REF} + 0.4$	1.75	1.9	-
$V_{OL} = V_{REF} – 0.4$	-	1.1	1.25
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL}at V_{OL} (mA)	8	-	-

Notes:
1. Timing delays are calculated based on V_{CCO} min of 3.0V.

PCI33_3 & PCI66_3

PCI33_3 or PCI66_3 require no termination. DC voltage specifications appear in Table 33.

Table 33: **PCI33_3 and PCI66_3 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
$V_{IH} = 0.5 \times V_{CCO}$	1.5	1.65	V_{CCO} + 0.5
$V_{IL} = 0.3 \times V_{CCO}$	–0.5	0.99	1.08
$V_{OH} = 0.9 \times V_{CCO}$	2.7	-	-
$V_{OL} = 0.1 \times V_{CCO}$	-	-	0.36
I_{OH} at V_{OH} (mA)	Note 1	-	-
I_{OL}at V_{OL} (mA)	Note 1	-	-

Notes:
1. Tested according to the relevant specification.

LVTTL

LVTTL requires no termination. DC voltage specifications appears in Table 34.

Table 34: **LVTTL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	2.0	-	3.6
V_{IL}	–0.5	-	0.8
V_{OH}	2.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–24	-	-
I_{OL} at V_{OL} (mA)	24	-	-

Notes:
1. Note: V_{OL} and V_{OH} for lower drive currents sample tested.

LVCMOS2

LVCMOS2 requires no termination. DC voltage specifications appear in Table 35.

Table 35: **LVCMOS2 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.3	2.5	2.7
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	1.7	-	3.6
V_{IL}	–0.5	-	0.7
V_{OH}	1.9	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–12	-	-
I_{OL} at V_{OL} (mA)	12	-	-

LVCMOS18

LVCMOS18 does not require termination. Table 36 lists DC voltage specifications.

Table 36: **LVCMOS18 Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	1.70	1.80	1.90
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	0.65 x V_{CCO}	-	1.95
V_{IL}	– 0.5	-	0.2 x V_{CCO}
V_{OH}	V_{CCO} – 0.4	-	-
V_{OL}	-	-	0.4
I_{OH} at V_{OH} (mA)	–8	-	-
I_{OL} at V_{OL} (mA)	8	-	-

AGP-2X

The specification for the AGP-2X standard does not document a recommended termination technique. DC voltage specifications appear in Table 37.

Table 37: **AGP-2X Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
$V_{REF} = N \times V_{CCO}$ (1)	1.17	1.32	1.48
V_{TT}	-	-	-
$V_{IH} = V_{REF} + 0.2$	1.37	1.52	-
$V_{IL} = V_{REF} – 0.2$	-	1.12	1.28
$V_{OH} = 0.9 \times V_{CCO}$	2.7	3.0	-
$V_{OL} = 0.1 \times V_{CCO}$	-	0.33	0.36
I_{OH} at V_{OH} (mA)	Note 2	-	-
I_{OL} at V_{OL} (mA)	Note 2	-	-

Notes:
1. N must be greater than or equal to 0.39 and less than or equal to 0.41.
2. Tested according to the relevant specification.

LVDS

Depending on whether the device is transmitting an LVDS signal or receiving an LVDS signal, there are two different circuits used for LVDS termination. A sample circuit illustrating a valid termination technique for transmitting LVDS signals appears in Figure 54. A sample circuit illustrating a valid termination for receiving LVDS signals appears in Figure 55. Table 38 lists DC voltage specifications. Further information on the specific termination resistor packs shown can be found on Table 40.

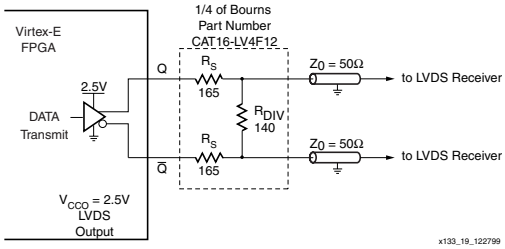


Figure 54: **Transmitting LVDS Signal Circuit**

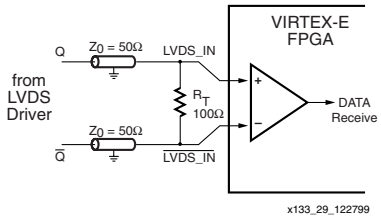


Figure 55: **Receiving LVDS Signal Circuit**

Table 38: **LVDS Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	2.375	2.5	2.625
V_{ICM}(2)	0.2	1.25	2.2
V_{OCM}(1)	1.125	1.25	1.375
V_{IDIFF} (1)	0.1	0.35	-
V_{ODIFF} (1)	0.25	0.35	0.45
V_{OH}(1)	1.25	-	-
V_{OL}(1)	-	-	1.25

Notes:
1. Measured with a 100Ω resistor across Q and $\overline{Q}$.
2. Measured with a differential input voltage = ± 350 mV.

LVPECL

Depending on whether the device is transmitting or receiving an LVPECL signal, two different circuits are used for LVPECL termination. A sample circuit illustrating a valid termination technique for transmitting LVPECL signals appears in Figure 56. A sample circuit illustrating a valid termination for receiving LVPECL signals appears in Figure 57. Table 39 lists DC voltage specifications. Further information on the specific termination resistor packs shown can be found on Table 40.

Table 39: **LVPECL Voltage Specifications**

Parameter	Min	Typ	Max
V_{CCO}	3.0	3.3	3.6
V_{REF}	-	-	-
V_{TT}	-	-	-
V_{IH}	1.49	-	2.72
V_{IL}	0.86	-	2.125
V_{OH}	1.8	-	-
V_{OL}	-	-	1.57

Notes:
1. For more detailed information, see **LVPECL DC Specifications** (Module 2).

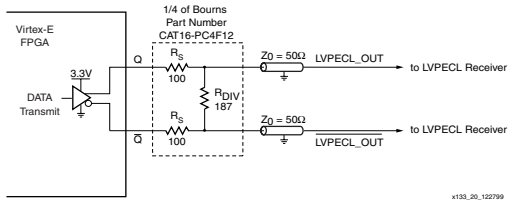


Figure 56: **Transmitting LVPECL Signal Circuit**

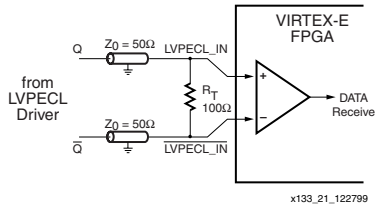


Figure 57: **Receiving LVPECL Signal Circuit**

Termination Resistor Packs

Resistor packs are available with the values and the configuration required for LVDS and LVPECL termination from Bourns, Inc., as listed in Table. For pricing and availability, please contact Bourns directly at http://www.bourns.com.

Table 40: **Bourns LVDS/LVPECL Resistor Packs**

Part Number	I/O Standard	Term. for:	Pairs/ Pack	Pins
CAT16–LV2F6	LVDS	Driver	2	8
CAT16–LV4F12	LVDS	Driver	4	16
CAT16–PC2F6	LVPECL	Driver	2	8
CAT16–PC4F12	LVPECL	Driver	4	16
CAT16–PT2F2	LVDS/LVPECL	Receiver	2	8
CAT16–PT4F4	LVDS/LVPECL	Receiver	4	16

LVDS Design Guide

The SelectIO library elements have been expanded for Virtex-E devices to include new LVDS variants. At this time all of the cells might not be included in the Synthesis libraries. The 2.1i-Service Pack 2 update for Alliance and Foundation software includes these cells in the VHDL and Verilog libraries. It is necessary to combine these cells to create the P-side (positive) and N-side (negative) as described in the input, output, 3-state and bidirectional sections.

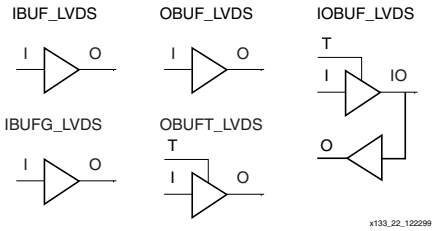


Figure 58: **LVDS elements**

Creating LVDS Global Clock Input Buffers

Global clock input buffers can be combined with adjacent IOBs to form LVDS clock input buffers. P-side is the GCLKPAD location; N-side is the adjacent IO_LVDS_DLL site.

Table 41: **Global Clock Input Buffer Pair Locations**

	GCLK 3		GCLK 2		GCLK 1		GCLK 0	
Pkg	P	N	P	N	P	N	P	N
CB228	-	-	199	198	-	-	87	88
BG432	D17	C17	A16	B16	AK16	AL17	AL16	AH15
BG560	A17	C18	D17	E17	AJ17	AM18	AL17	AM17
CG560	A17	C18	D17	E17	AJ17	AM18	AL17	AM17
FG1156	E17	C17	D17	J18	Al19	AL17	AH18	AM18

HDL Instantiation

Only one global clock input buffer is required to be instantiated in the design and placed on the correct GCLKPAD location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location.

In the physical device, a configuration option is enabled that routes the pad wire to the differential input buffer located in the GCLKIOB. The output of this buffer then drives the output of the GCLKIOB cell. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_external),
.O(clk_internal));
```

Location constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_external LOC = GCLKPAD3;
```

GCLKPAD3 can also be replaced with the package pin name such as D17 for the BG432 package.

Optional N-side

Some designers might prefer to also instantiate the N-side buffer for the global clock buffer. This allows the top-level net list to include net connections for both PCB layout and system-level integration. In this case, only the output P-side IBUFG connection has a net connected to it. Since the N-side IBUFG does not have a connection in the EDIF net list, it is trimmed from the design in MAP.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_p_external, O=>clk_internal);

gclk0_n : IBUFG_LVDS port map
(I=>clk_n_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_p_external),
.O(clk_internal));

IBUFG_LVDS gclk0_n (.I(clk_n_external),
.O(clk_internal));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_p_external LOC = GCLKPAD3;

NET clk_n_external LOC = C17;
```

GCLKPAD3 can also be replaced with the package pin name, such as D17 for the BG432 package.

Creating LVDS Input Buffers

An LVDS input buffer can be placed in a wide number of IOB locations. The exact location is dependent on the package that is used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side where # is the pair number.

HDL Instantiation

Only one input buffer is required to be instantiated in the design and placed on the correct IO_L#P location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location. In the physical device, a configuration option is enabled that routes the pad wire from the IO_L#N IOB to the differential input buffer located in the IO_L#P IOB. The output of this buffer then drives the output of the IO_L#P cell or the input register in the IO_L#P IOB. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
data0_p : IBUF_LVDS port map (I=>data(0),
O=>data_int(0));
```

Verilog Instantiation

```
IBUF_LVDS data0_p (.I(data[0]),
.O(data_int[0]));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data<0> LOC = D28; # IO_L0P
```

Optional N-side

Some designers might prefer to also instantiate the N-side buffer for the input buffer. This allows the top-level net list to include net connections for both PCB layout and system-level integration. In this case, only the output P-side IBUF connection has a net connected to it. Since the N-side IBUF does not have a connection in the EDIF net list, it is trimmed from the design in MAP.

VHDL Instantiation

```
data0_p : IBUF_LVDS port map
(I=>data_p(0), O=>data_int(0));

data0_n : IBUF_LVDS port map
(I=>data_n(0), O=>open);
```

Verilog Instantiation

```
IBUF_LVDS data0_p (.I(data_p[0]),
.O(data_int[0]));

IBUF_LVDS data0_n (.I(data_n[0]), .O());
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Adding an Input Register

All LVDS buffers can have an input register in the IOB. The input register is in the P-side IOB only. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the "map -pr [i|o|b]" where "i" is inputs only, "o" is outputs only and "b" is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries available to explicitly create these structures. The input library macros are listed in Table 42. The I and IB inputs to the macros are the external net connections.

Table 42: **Input Library Macros**

Name	Inputs	Outputs
IBUFDS_FD_LVDS	I, IB, C	Q
IBUFDS_FDE_LVDS	I, IB, CE, C	Q
IBUFDS_FDC_LVDS	I, IB, C, CLR	Q
IBUFDS_FDCE_LVDS	I, IB, CE, C, CLR	Q
IBUFDS_FDP_LVDS	I, IB, C, PRE	Q
IBUFDS_FDPE_LVDS	I, IB, CE, C, PRE	Q
IBUFDS_FDR_LVDS	I, IB, C, R	Q
IBUFDS_FDRE_LVDS	I, IB, CE, C, R	Q
IBUFDS_FDS_LVDS	I, IB, C, S	Q
IBUFDS_FDSE_LVDS	I, IB, CE, C, S	Q
IBUFDS_LD_LVDS	I, IB, G	Q
IBUFDS_LDE_LVDS	I, IB, GE, G	Q
IBUFDS_LDC_LVDS	I, IB, G, CLR	Q
IBUFDS_LDCE_LVDS	I, IB, GE, G, CLR	Q
IBUFDS_LDP_LVDS	I, IB, G, PRE	Q
IBUFDS_LDPE_LVDS	I, IB, GE, G, PRE	Q

Creating LVDS Output Buffers

LVDS output buffers can be placed in a wide number of IOB locations. The exact locations are dependent on the package used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side, where # is the pair number.

HDL Instantiation

Both output buffers are required to be instantiated in the design and placed on the correct IO_L#P and IO_L#N locations. The IOB must have the same net source the following pins, clock (C), set/reset (SR), output (O), output clock enable (OCE). In addition, the output (O) pins must be inverted with respect to each other, and if output registers are used, the INIT states must be opposite values (one HIGH and one LOW). Failure to follow these rules leads to DRC errors in software.

VHDL Instantiation

```
data0_p  : OBUF_LVDS port map
(I=>data_int(0),   O=>data_p(0));

data0_inv: INV       port map
(I=>data_int(0),   O=>data_n_int(0));

data0_n  : OBUF_LVDS port map
(I=>data_n_int(0), O=>data_n(0));
```

Verilog Instantiation

```
OBUF_LVDS data0_p   (.I(data_int[0]),
.O(data_p[0]));

INV       data0_inv (.I(data_int[0],
.O(data_n_int[0]);

OBUF_LVDS data0_n   (.I(data_n_int[0]),
.O(data_n[0]));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the output buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Synchronous vs. Asynchronous Outputs

If the outputs are synchronous (registered in the IOB) then any IO_L#P|N pair can be used. If the outputs are asynchronous (no output register), then they must use one of the pairs that are part of the same IOB group at the end of a ROW or COLUMN in the device.

The LVDS pairs that can be used as asynchronous outputs are listed in the Virtex-E pinout tables. Some pairs are marked as asynchronous-capable for all devices in that package, and others are marked as available only for that device in the package. If the device size might change at some point in the product lifetime, then only the common pairs for all packages should be used.

Adding an Output Register

All LVDS buffers can have an output register in the IOB. The output registers must be in both the P-side and N-side IOBs. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code.

Special care must be taken to insure that the D pins of the registers are inverted and that the INIT states of the registers are opposite. The clock pin (C), clock enable (CE) and set/reset (CLR/PRE or S/R) pins must connect to the same source. Failure to do this leads to a DRC error in the software.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the "map -pr [i|o|b]" where "i" is inputs only, "o" is outputs only and "b" is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries have been developed to explicitly create these structures. The output library macros are listed in Table 43. The O and OB inputs to the macros are the external net connections.

Table 43: **Output Library Macros**

Name	Inputs	Outputs
OBUFDS_FD_LVDS	D, C	O, OB
OBUFDS_FDE_LVDS	DD, CE, C	O, OB
OBUFDS_FDC_LVDS	D, C, CLR	O, OB
OBUFDS_FDCE_LVDS	D, CE, C, CLR	O, OB
OBUFDS_FDP_LVDS	D, C, PRE	O, OB
OBUFDS_FDPE_LVDS	D, CE, C, PRE	O, OB
OBUFDS_FDR_LVDS	D, C, R	O, OB
OBUFDS_FDRE_LVDS	D, CE, C, R	O, OB
OBUFDS_FDS_LVDS	D, C, S	O, OB
OBUFDS_FDSE_LVDS	D, CE, C, S	O, OB
OBUFDS_LD_LVDS	D, G	O, OB
OBUFDS_LDE_LVDS	D, GE, G	O, OB
OBUFDS_LDC_LVDS	D, G, CLR	O, OB
OBUFDS_LDCE_LVDS	D, GE, G, CLR	O, OB
OBUFDS_LDP_LVDS	D, G, PRE	O, OB
OBUFDS_LDPE_LVDS	D, GE, G, PRE	O, OB

Creating LVDS Output 3-State Buffers

LVDS output 3-state buffers can be placed in a wide number of IOB locations. The exact locations are dependent on the package used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side, where # is the pair number.

HDL Instantiation

Both output 3-state buffers are required to be instantiated in the design and placed on the correct IO_L#P and IO_L#N locations. The IOB must have the same net source the following pins, clock (C), set/reset (SR), 3-state (T), 3-state clock enable (TCE), output (O), output clock enable (OCE). In addition, the output (O) pins must be inverted with respect to each other, and if output registers are used, the INIT states must be opposite values (one High and one Low). If 3-state registers are used, they must be initialized to the same state. Failure to follow these rules leads to DRC errors in the software.

VHDL Instantiation

```
data0_p:   OBUFT_LVDS port map
(I=>data_int(0), T=>data_tri,
O=>data_p(0));

data0_inv: INV port map
(I=>data_int(0), O=>data_n_int(0));

data0_n:    OBUFT_LVDS port map
(I=>data_n_int(0), T=>data_tri,
O=>data_n(0));
```

Verilog Instantiation

```
OBUFT_LVDS data0_p   (.I(data_int[0]),
.T(data_tri), .O(data_p[0]));

INV        data0_inv (.I(data_int[0],
.O(data_n_int[0]);

OBUFT_LVDS data0_n   (.I(data_n_int[0]),
.T(data_tri), .O(data_n[0]));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the output buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Synchronous vs. Asynchronous 3-State Outputs

If the outputs are synchronous (registered in the IOB), then any IO_L#PIN pair can be used. If the outputs are asynchronous (no output register), then they must use one of the pairs that are part of the same IOB group at the end of a ROW or COLUMN in the device. This applies for either the 3-state pin or the data out pin.

LVDS pairs that can be used as asynchronous outputs are listed in the Virtex-E pinout tables. Some pairs are marked as "asynchronous capable" for all devices in that package, and others are marked as available only for that device in the package. If the device size might be changed at some point in the product lifetime, then only the common pairs for all packages should be used.

Adding Output and 3-State Registers

All LVDS buffers can have an output register in the IOB. The output registers must be in both the P-side and N-side IOBs. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code.

Special care must be taken to insure that the D pins of the registers are inverted and that the INIT states of the registers are opposite. The 3-state (T), 3-state clock enable (CE), clock pin (C), output clock enable (CE) and set/reset (CLR/PRE or S/R) pins must connect to the same source. Failure to do this leads to a DRC error in the software.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the "map -pr [i|o|b]" where "i" is inputs only, "o" is outputs only and "b" is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries have been developed to explicitly create these structures. The input library macros are listed below. The 3-state is configured to be 3-stated at GSR and when the PRE,CLR,S or R is asserted and shares its clock enable with the output register. If this is not desirable then the library can be updated by the user for the desired functionality. The O and OB inputs to the macros are the external net connections.

Creating a LVDS Bidirectional Buffer

LVDS bidirectional buffers can be placed in a wide number of IOB locations. The exact locations are dependent on the package used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side, where # is the pair number.

HDL Instantiation

Both bidirectional buffers are required to be instantiated in the design and placed on the correct IO_L#P and IO_L#N locations. The IOB must have the same net source the following pins, clock (C), set/reset (SR), 3-state (T), 3-state clock enable (TCE), output (O), output clock enable (OCE). In addition, the output (O) pins must be inverted with respect to each other, and if output registers are used, the INIT states must be opposite values (one HIGH and one LOW). If 3-state registers are used, they must be initialized to the same state. Failure to follow these rules leads to DRC errors in the software.

VHDL Instantiation

```
data0_p:   IOBUF_LVDS port map
(I=>data_out(0), T=>data_tri,
IO=>data_p(0), O=>data_int(0));

data0_inv: INV        port map
(I=>data_out(0),   O=>data_n_out(0));

data0_n  : IOBUF_LVDS port map
(I=>data_n_out(0), T=>data_tri,
IO=>data_n(0), O=>open);
```

Verilog Instantiation

```
IOBUF_LVDS data0_p(.I(data_out[0]),
.T(data_tri), .IO(data_p[0]),
.O(data_int[0]);

INV        data0_inv (.I(data_out[0],
.O(data_n_out[0]);

IOBUF_LVDS
data0_n(.I(data_n_out[0]),.T(data_tri),.
IO(data_n[0]).O());
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the output buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Synchronous vs. Asynchronous Bidirectional Buffers

If the output side of the bidirectional buffers are synchronous (registered in the IOB), then any IO_L#P|N pair can be used. If the output side of the bidirectional buffers are asynchronous (no output register), then they must use one of the pairs that is a part of the asynchronous LVDS IOB group. This applies for either the 3-state pin or the data out pin.

The LVDS pairs that can be used as asynchronous bidirectional buffers are listed in the Virtex-E pinout tables. Some pairs are marked as asynchronous capable for all devices in that package, and others are marked as available only for that device in the package. If the device size might change at some point in the product's lifetime, then only the common pairs for all packages should be used.

Adding Output and 3-State Registers

All LVDS buffers can have an output and input registers in the IOB. The output registers must be in both the P-side and N-side IOBs, the input register is only in the P-side. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code. Special care must be taken to insure that the D pins of the registers are inverted and that the INIT states of the registers are opposite. The 3-state (T), 3-state clock enable (CE), clock pin (C), output clock enable (CE), and set/reset (CLR/PRE or S/R) pins must connect to the same source. Failure to do this leads to a DRC error in the software.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the "map -pr [i|o|b]" where "i" is inputs only, "o" is outputs only and "b" is both inputs and outputs. To improve design coding times VHDL and Verilog synthesis macro libraries have been developed to explicitly create these structures. The bidirectional I/O library macros are listed in Table 44. The 3-state is configured to be 3-stated at GSR and when the PRE,CLR,S or R is asserted and shares its clock enable with the output and input register. If this is not desirable then the library can be updated be the user for the desired functionality. The I/O and IOB inputs to the macros are the external net connections.

Table 44: **Bidirectional I/O Library Macros**

Name	Inputs	Bidirectional	Outputs
IOBUFDS_FD_LVDS	D, T, C	IO, IOB	Q
IOBUFDS_FDE_LVDS	D, T, CE, C	IO, IOB	Q
IOBUFDS_FDC_LVDS	D, T, C, CLR	IO, IOB	Q
IOBUFDS_FDCE_LVDS	D, T, CE, C, CLR	IO, IOB	Q
IOBUFDS_FDP_LVDS	D, T, C, PRE	IO, IOB	Q
IOBUFDS_FDPE_LVDS	D, T, CE, C, PRE	IO, IOB	Q
IOBUFDS_FDR_LVDS	D, T, C, R	IO, IOB	Q
IOBUFDS_FDRE_LVDS	D, T, CE, C, R	IO, IOB	Q
IOBUFDS_FDS_LVDS	D, T, C, S	IO, IOB	Q
IOBUFDS_FDSE_LVDS	D, T, CE, C, S	IO, IOB	Q
IOBUFDS_LD_LVDS	D, T, G	IO, IOB	Q
IOBUFDS_LDE_LVDS	D, T, GE, G	IO, IOB	Q
IOBUFDS_LDC_LVDS	D, T, G, CLR	IO, IOB	Q
IOBUFDS_LDCE_LVDS	D, T, GE, G, CLR	IO, IOB	Q
IOBUFDS_LDP_LVDS	D, T, G, PRE	IO, IOB	Q
IOBUFDS_LDPE_LVDS	D, T, GE, G, PRE	IO, IOB	Q

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
05/19/03	1.0	Initial Xilinx release.
07/29/04	1.1	• Section **Input/Output Block, page 1**: Last paragraph, excepted certain I/O standards from automatic addition of clamping diodes at the inputs. • Section **Input Path, page 2**: Last paragraph, qualified the presence of optional pull-up/pull-down resistors on all inputs to "all *user I/O* inputs." • Section **Block SelectRAM, page 5**: Last paragraph, added reference to XAPP130. • Section **Configuration, page 11**: Added updated information regarding the optional special use of certain pins. • Section **Configuration Modes**: On page 12 (two places), added recommendation to actively drive configuration mode pins rather than leave tem floating. • Figure 18, page 16: Updated flowchart. • Section **Boundary-Scan Mode, page 17**: Added information about required control of $\overline{\text{PROGRAM}}$ pin, and added a reference to XAPP139. • Section **Duty Cycle Correction Property, page 21**: Removed the statement that when duty-cycle correction deactivates, the output clock has the same duty cycle as the source clock. • Table 36, page 43: Correct V_{IH} Min from 0.7 x V_{CCO} to 0.65 x V_{CCO}.

QPro Virtex-E Electrical Characteristics

Based on preliminary characterization. Further changes are not expected.

All guaranteed specifications are representative of worst-case supply voltage and junction temperature conditions. Some specifications also include best-case timing predictions. Best-case timing specifications are for design guidance and are not guaranteed.

DC Characteristics

Absolute Maximum Ratings

Symbol	Description(1)			Units
V_{CCINT}	Internal Supply voltage relative to GND		–0.5 to 2.0	V
V_{CCO}	Supply voltage relative to GND		–0.5 to 4.0	V
V_{REF}	Input Reference Voltage		–0.5 to 4.0	V
V_{IN}(3)	Input voltage relative to GND		–0.5 to V_{CCO} + 0.5	V
V_{TS}	Voltage applied to 3-state output		–0.5 to 4.0	V
V_{CC}	Longest Supply Voltage Rise Time from 0 V - 1.71 V		50	ms
T_{STG}	Storage temperature (ambient)		–65 to +150	°C
T_J	Junction temperature(2)	Plastic packages	+125	°C
		Ceramic packages	+150	°C

Notes:

1. Stresses beyond those listed under Absolute Maximum Ratings can cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time can affect device reliability.
2. For soldering guidelines and thermal considerations, see the Device Packaging infomation on the Xilinx website.
3. Inputs configured as PCI are fully PCI compliant. This statement takes precedence over any specification that would imply that the device is not PCI compliant.

Recommended Operating Conditions

Symbol	Description		Min	Max	Units
V_{CCINT}	Internal Supply voltage relative to GND, T_J = –55°C to +125°C	Military	1.71	1.89	V
V_{CCO}	Supply voltage relative to GND, T_J = –55°C to +125°C	Military	1.2	3.6	V
T_{IN}	Input signal transition time		-	250	ns
T_C	Operating Temperature Range	XQV600E	–55	+125	°C
		XQV1000E	–55	+125	°C
		XQV2000E	–40	+125	°C

DC Characteristics Over Recommended Operating Conditions

Symbol	Description	Device	Min	Max	Units
V_{DRINT}	Data Retention V_{CCINT} Voltage (below which configuration data might be lost)	All	1.5	-	V
V_{DRIO}	Data Retention V_{CCO} Voltage (below which configuration data might be lost)	All	1.2	-	V
I_{CCINTQ}	Quiescent V_{CCINT} supply current(1)	XQV600E	-	400	mA
		XQV1000E	-	500	mA
		XQV2000E	-	1100	mA
I_{CCOQ}	Quiescent V_{CCO} supply current(1)	All	-	2	mA
I_L	Input or output leakage current	All	–10	+10	µA
C_{IN}	Input capacitance (sample tested)	All	-	8	pF
I_{RPU}	Pad pull-up (when selected) @ V_{in} = 0V, V_{CCO} = 3.3V (sample tested)	All	Note 2	0.25	mA
I_{RPD}	Pad pull-down (when selected) @ V_{in} = 3.6V (sample tested)	-	Note 2	0.25	mA

Notes:
1. With no output current loads, no active input pull-up resistors, all I/O pins 3-stated and floating.
2. Internal pull-up and pull-down resistors guarantee valid logic levels at unconnected input pins. These pull-up and pull-down resistors do not guarantee valid logic levels when input pins are connected to other circuits.

Power-On Power Supply Requirements

Xilinx FPGAs require a certain amount of supply current during power-on to insure proper device operation. The actual current consumed depends on the power-on ramp rate of the power supply. This is the time required to reach the nominal power supply voltage of the device[1] from 0 V. The fastest ramp rate is 0V to nominal voltage in 2 ms, and the slowest allowed ramp rate is 0V to nominal voltage in 50 ms. For more details on power supply requirements, see **XAPP158**.

Description[2]	Temperature	Min[3]	Units
Minimum required current supply	T_J = 0°C to +125 °C	1	A
	T_J = –40°C to 0°C	2	A
	T_J = –55°C to –40°C	2.5	A

Notes:
1. Ramp rate used for this specification is from 0-1.8V DC. Peak current occurs on or near the internal power-on reset threshold and lasts for less than 3 ms.
2. Devices are guaranteed to initialize properly with the minimum current available from the power supply as noted above.
3. Larger currents might result if ramp rates are forced to be faster.

DC Input and Output Levels

Values for V_{IL} and V_{IH} are recommended input voltages. Values for I_{OL} and I_{OH} are guaranteed over the recommended operating conditions at the V_{OL} and V_{OH} test points. Only selected standards are tested. These are chosen to ensure that all standards meet their specifications. The selected standards are tested at minimum V_{CCO} with the respective V_{OL} and V_{OH} voltage levels shown. Other standards are sample tested.

Input/Output Standard	V_{IL}		V_{IH}		V_{OL}	V_{OH}	I_{OL}	I_{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
LVTTL(1)	– 0.5	0.8	2.0	3.6	0.4	2.4	24	– 24
LVCMOS2	– 0.5	0.7	1.7	2.7	0.4	1.9	12	– 12
LVCMOS18	– 0.5	35% V_{CCO}	65% V_{CCO}	1.95	0.4	V_{CCO} – 0.4	8	– 8
PCI, 3.3V	– 0.5	30% V_{CCO}	50% V_{CCO}	V_{CCO} + 0.5	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2
GTL	– 0.5	V_{REF} – 0.05	V_{REF} + 0.05	3.6	0.4	n/a	40	n/a
GTL+	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.6	n/a	36	n/a
HSTL I	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	8	–8
HSTL III	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	24	–8
HSTL IV	– 0.5	V_{REF} – 0.1	V_{REF} + 0.1	3.6	0.4	V_{CCO} – 0.4	48	–8
SSTL3 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.6	V_{REF} + 0.6	8	–8
SSTL3 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.8	V_{REF} + 0.8	16	–16
SSTL2 I	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.61	V_{REF} + 0.61	7.6	–7.6
SSTL2 II	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.80	V_{REF} + 0.80	15.2	–15.2
CTT	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	V_{REF} – 0.4	V_{REF} + 0.4	8	–8
AGP	– 0.5	V_{REF} – 0.2	V_{REF} + 0.2	3.6	10% V_{CCO}	90% V_{CCO}	Note 2	Note 2

Notes:
1. V_{OL} and V_{OH} for lower drive currents are sample tested.
2. Tested according to the relevant specifications.

LVDS DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
V_{CCO}	Supply Voltage		2.375	2.5	2.625	V
V_{OH}	Output High Voltage for Q and $\overline{Q}$	R_T = 100Ω across Q and $\overline{Q}$ signals	1.25	1.425	1.6	V
V_{OL}	Output Low Voltage for Q and $\overline{Q}$	R_T = 100Ω across Q and $\overline{Q}$ signals	0.9	1.075	1.25	V
V_{ODIFF}	Differential Output Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	R_T = 100Ω across Q and $\overline{Q}$ signals	250	350	450	mV
V_{OCM}	Output Common-Mode Voltage	R_T = 100Ω across Q and $\overline{Q}$ signals	1.125	1.25	1.375	V
V_{IDIFF}	Differential Input Voltage (Q – $\overline{Q}$), Q = High ($\overline{Q}$ – Q), $\overline{Q}$ = High	Common-mode input voltage = 1.25V	100	350	NA	mV
V_{ICM}	Input Common-Mode Voltage	Differential input voltage = ±350 mV	0.2	1.25	2.2	V

Notes:
1. Refer to the Design Consideration section for termination schematics.

LVPECL DC Specifications

These values are valid at the output of the source termination pack shown under **LVPECL** (Module 2), with a 100Ω differential load only. The V_{OH} levels are 200 mV below standard LVPECL levels and are compatible with devices tolerant of lower common-mode ranges. The following table summarizes the DC output specifications of LVPECL.

DC Parameter	Min	Max	Min	Max	Min	Max	Units
V_{CCO}	**3.0**		**3.3**		**3.6**		**V**
V_{OH}	1.8	2.11	1.92	2.28	2.13	2.41	V
V_{OL}	0.96	1.27	1.06	1.43	1.30	1.57	V
V_{IH}	1.49	2.72	1.49	2.72	1.49	2.72	V
V_{IL}	0.86	2.125	0.86	2.125	0.86	2.125	V
Differential Input Voltage	0.3	-	0.3	-	0.3	-	V

Virtex-E Switching Characteristics

Testing of switching parameters is modeled after testing methods specified by MIL-M-38510/605. All devices are 100% functionally tested. Internal timing parameters are derived from measuring internal test patterns. Listed below are representative values. For more specific, more precise, and worst-case guaranteed data, use the values reported by the static timing analyzer (TRCE in the Xilinx Development System) and back-annotated to the simulation net list. All timing parameters assume worst-case operating conditions (supply voltage and junction temperature). Values apply to all Virtex-E devices unless otherwise noted.

IOB Input Switching Characteristics

Input delays associated with the pad are specified below for LVTTL levels. For other standards, adjust the delays with the values shown in **IOB Input Switching Characteristics Standard Adjustments**, page 6.

Symbol	Description[2]	Device	Best Case[3]		Worst Case		Units
			Min	Max	Min	Max	
Propagation Delays							
T_{IOPI}	Pad to I output, no delay	All	0.43	-	-	0.8	ns
T_{IOPID}	Pad to I output, with delay	XQV600E	0.51	-	-	1.0	ns
		XQV1000E	0.55	-	-	1.1	ns
		XQV2000E	0.55	-	-	1.1	ns
T_{IOPLI}	Pad to output IQ via transparent latch, no delay	All	0.8	-	-	1.6	ns
T_{IOPLID}	Pad to output IQ via transparent latch, with delay	XQV600E	1.55	-	-	3.7	ns
		XQV1000E	1.55	-	-	3.7	ns
		XQV2000E	1.59	-	-	3.8	ns
Sequential Delays, Clock CLK							
T_{CH}	Minimum Pulse Width, High	All	0.56			1.4	ns
T_{CL}	Minimum Pulse Width, Low		0.56			1.4	ns
T_{IOCKIQ}	Clock CLK to output IQ		0.18	-	-	0.7	ns
Setup and Hold Times with respect to Clock at IOB Input Register							
T_{IOPICK}/ T_{IOICKP}	Pad, no delay	All	0.69 / 0	-	1.5 / 0	-	ns
$T_{IOPICKD}$/ $T_{IOICKPD}$	Pad, with delay	XQV600E	1.49 / 0	-	3.5 / 0	-	ns
		XQV1000E	1.49 / 0	-	3.5 / 0	-	ns
		XQV2000E	1.53 / 0	-	3.6 / 0	-	ns
$T_{IOICECK}$/ $T_{IOCKICE}$	ICE input	All	0.28 / 0.01	-	0.7 / 0.01	-	ns
$T_{IOSRCKI}$	SR input (IFF, synchronous)	All	0.38	-	1.0	-	ns
Set/Reset Delays							
T_{IOSRIQ}	SR input to IQ (asynchronous)	All	0.54	-	-	1.4	ns
T_{GSRQ}	GSR to output IQ	All	3.88	-	-	9.7	ns

Notes:
1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.
2. Input timing i for LVTTL is measured at 1.4V. For other I/O standards, see Table 2.
3. Best Case numbers are **Advance** specification numbers. See **DC Characteristics**, page 1 for a description.

IOB Input Switching Characteristics Standard Adjustments

Symbol	Description	Standard(1)	Min(2)	Max	Units
Data Input Delay Adjustments					
T_{ILVTTL}	Standard-specific data input delay adjustments	LVTTL	0.0	0.0	ns
$T_{ILVCMOS2}$		LVCMOS2	–0.02	0.0	ns
$T_{ILVCMOS18}$		LVCMOS18	0.12	+0.20	ns
T_{ILVDS}		LVDS	0.00	+0.15	ns
$T_{ILVPECL}$		LVPECL	0.00	+0.15	ns
T_{IPCI33_3}		PCI, 33 MHz, 3.3V	–0.05	+0.08	ns
T_{IPCI66_3}		PCI, 66 MHz, 3.3V	–0.05	–0.11	ns
T_{IGTL}		GTL	+0.10	+0.14	ns
$T_{IGTLPLUS}$		GTL+	+0.06	+0.14	ns
T_{IHSTL}		HSTL	+0.02	+0.04	ns
T_{ISSTL2}		SSTL2	–0.04	+0.04	ns
T_{ISSTL3}		SSTL3	–0.02	+0.04	ns
T_{ICTT}		CTT	+0.01	+0.10	ns
T_{IAGP}		AGP	–0.03	+0.04	ns

Notes:
1. Input timing i for LVTTL is measured at 1.4V. For other I/O standards, see Table 2.
2. Best Case Numbers are **Advance** product specification numbers. See **DC Characteristics, page 1** for a description.

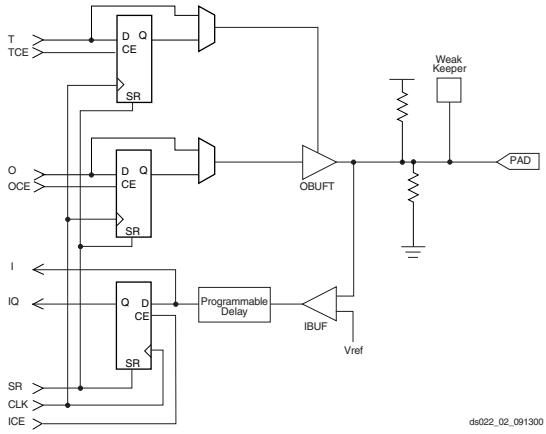


Figure 1: **Virtex-E Input/Output Block (IOB)**

IOB Output Switching Characteristics, Figure 1

Output delays terminating at a pad are specified for LVTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays with the values shown in **IOB Output Switching Characteristics Standard Adjustments**, page 8.

Symbol	Description (2)	Best Case		Worst Case (1)		Units
		Min (3)	Max	Min	Max	
Propagation Delays						
T_{IOOP}	O input to Pad	1.04	-	-	2.9	ns
T_{IOOLP}	O input to Pad via transparent latch	1.24	-	-	3.4	ns
3-State Delays						
T_{IOTHZ}	T input to Pad high-impedance(2)	0.73	-	-	1.9	ns
T_{IOTON}	T input to valid data on Pad	1.13	-	-	3.1	ns
$T_{IOTLPHZ}$	T input to Pad high-impedance via transparent latch (2)	0.86	-	-	2.2	ns
$T_{IOTLPON}$	T input to valid data on Pad via transparent latch	1.26	-	-	3.4	ns
T_{GTS}	GTS to Pad high impedance(2)	1.94	-	-	4.9	ns
Sequential Delays, Clock CLK						
T_{CH}	Minimum Pulse Width, High	0.56			1.4	ns
T_{CL}	Minimum Pulse Width, Low	0.56			1.4	ns
T_{IOCKP}	Clock CLK to Pad	0.97	-	-	2.9	ns
T_{IOCKHZ}	Clock CLK to Pad high-impedance (synchronous)(2)	0.77	-	-	2.2	ns
T_{IOCKON}	Clock CLK to valid data on Pad (synchronous)	1.17	-	-	3.4	ns
Setup and Hold Times before/after Clock CLK						
T_{IOOCK} / T_{IOCKO}	O input	0.43 / 0	-	1.1 / 0	-	ns
$T_{IOOCECK}$ / $T_{IOCKOCE}$	OCE input	0.28 / 0	-	0.7 / 0	-	ns
$T_{IOSRCKO}$ / $T_{IOCKOSR}$	SR input (OFF)	0.40 / 0	-	1.0 / 0	-	ns
T_{IOTCK} / T_{IOCKT}	3-State Setup Times, T input	0.26 / 0	-	0.7 / 0	-	ns
$T_{IOTCECK}$ / $T_{IOCKTCE}$	3-State Setup Times, T_{CE} input	0.30 / 0	-	0.8 / 0	-	ns
$T_{IOSRCKT}$ / $T_{IOCKTSR}$	3-State Setup Times, SR input (T_{FF})	0.38 / 0	-	1.0 / 0	-	ns
Set/Reset Delays						
T_{IOSRP}	SR input to Pad (asynchronous)	1.30	-	-	3.5	ns
T_{IOSRHZ}	SR input to Pad high-impedance (asynchronous)(2)	1.08	-	-	2.7	ns
T_{IOSRON}	SR input to valid data on Pad (asynchronous)	1.48	-	-	3.9	ns
T_{IOGSRQ}	GSR to Pad	3.88	-	-	9.7	ns

Notes:
1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.
2. 3-state turn-off delays should not be adjusted.
3. Best Case Numbers are Advance product specification numbers. See **DC Characteristics**, page 1 for a description.

IOB Output Switching Characteristics Standard Adjustments

Output delays terminating at a pad are specified for LVTTL with 12 mA drive and fast slew rate. For other standards, adjust the delays by the values shown.

Symbol	Description	Standard	Min(1)	Max	Units
Output Delay Adjustments					
T_{OLVTTL_S2}	Standard-specific adjustments for output delays terminating at pads (based on standard capacitive load, Csl)	LVTTL, Slow, 2 mA	4.2	+14.7	ns
T_{OLVTTL_S4}		4 mA	2.5	+7.5	ns
T_{OLVTTL_S6}		6 mA	1.8	+4.8	ns
T_{OLVTTL_S8}		8 mA	1.2	+3.0	ns
T_{OLVTTL_S12}		12 mA	1.0	+1.9	ns
T_{OLVTTL_S16}		16 mA	0.9	+1.7	ns
T_{OLVTTL_S24}		24 mA	0.8	+1.3	ns
T_{OLVTTL_F2}		LVTTL, Fast, 2 mA	1.9	+13.1	ns
T_{OLVTTL_F4}		4 mA	0.7	+5.3	ns
T_{OLVTTL_F6}		6 mA	0.20	+3.1	ns
T_{OLVTTL_F8}		8 mA	0.10	+1.0	ns
T_{OLVTTL_F12}		12 mA	0.0	0.0	ns
T_{OLVTTL_F16}		16 mA	–0.10	–0.05	ns
T_{OLVTTL_F24}		24 mA	–0.10	–0.20	ns
$T_{OLVCMOS\_2}$		LVCMOS2	0.10	+0.09	ns
$T_{OLVCMOS\_18}$		LVCMOS18	0.10	+0.7	ns
T_{OLVDS}		LVDS	–0.39	–1.2	ns
$T_{OLVPECL}$		LVPECL	–0.20	–0.41	ns
T_{OPCI33_3}		PCI, 33 MHz, 3.3V	0.50	+2.3	ns
T_{OPCI66_3}		PCI, 66 MHz, 3.3V	0.10	–0.41	ns
T_{OGTL}		GTL	0.6	+0.49	ns
T_{OGTLP}		GTL+	0.7	+0.8	ns
T_{OHSTL_I}		HSTL I	0.10	–0.51	ns
T_{OHSTL_III}		HSTL III	–0.10	–0.91	ns
T_{OHSTL_IV}		HSTL IV	–0.20	–1.01	ns
T_{OSSTL2_I}		SSTL2 I	–0.10	–0.51	ns
T_{OSSTL2_II}		SSTL2 II	–0.20	–0.91	ns
T_{OSSTL3_I}		SSTL3 I	–0.20	–0.51	ns
T_{OSSTL3_II}		SSTL3 II	–0.30	–1.01	ns
T_{OCTT}		CTT	0.0	–0.61	ns
T_{OAGP}		AGP	–0.1	–0.91	ns

Notes:
1. The numbers for Min are Best Case Advance product specification numbers. See **DC Characteristics**, page 1 for a description.

Calculation of T_{ioop} as a Function of Capacitance

T_{ioop} is the propagation delay from the O Input of the IOB to the pad. The values for T_{ioop} are based on the standard capacitive load (C_{sl}) for each I/O standard as listed in Table 1.

Table 1: **Constants for Use in Calculation of T_{ioop}**

Standard	C_{sl} (pF)	fl (ns/pF)
LVTTL Fast Slew Rate, 2 mA drive	35	0.41
LVTTL Fast Slew Rate, 4 mA drive	35	0.20
LVTTL Fast Slew Rate, 6 mA drive	35	0.13
LVTTL Fast Slew Rate, 8 mA drive	35	0.079
LVTTL Fast Slew Rate, 12 mA drive	35	0.044
LVTTL Fast Slew Rate, 16 mA drive	35	0.043
LVTTL Fast Slew Rate, 24 mA drive	35	0.033
LVTTL Slow Slew Rate, 2 mA drive	35	0.41
LVTTL Slow Slew Rate, 4 mA drive	35	0.20
LVTTL Slow Slew Rate, 6 mA drive	35	0.10
LVTTL Slow Slew Rate, 8 mA drive	35	0.086
LVTTL Slow Slew Rate, 12 mA drive	35	0.058
LVTTL Slow Slew Rate, 16 mA drive	35	0.050
LVTTL Slow Slew Rate, 24 mA drive	35	0.048
LVCMOS2	35	0.041
LVCMOS18	35	0.050
PCI 33 MHZ 3.3V	10	0.050
PCI 66 MHz 3.3V	10	0.033
GTL	0	0.014
GTL+	0	0.017
HSTL Class I	20	0.022
HSTL Class III	20	0.016
HSTL Class IV	20	0.014
SSTL2 Class I	30	0.028
SSTL2 Class II	30	0.016
SSTL3 Class I	30	0.029
SSTL3 Class II	30	0.016
CTT	20	0.035
AGP	10	0.037

Notes:
1. I/O parameter measurements are made with the capacitance values shown above. See the **Application Examples** (Module 2) for appropriate terminations.
2. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

For other capacitive loads, use the formulas below to calculate the corresponding T_{ioop}:

$$T_{ioop} = T_{ioop} + T_{opadjust} + (C_{load} - C_{sl}) * fl$$

where:

$T_{opadjust}$ is reported above in the Output Delay Adjustment section.

C_{load} is the capacitive load for the design.

Table 2: **Delay Measurement Methodology**

Standard	V_L[1]	V_H[1]	Meas. Point	V_{REF} (Typ)[2]
LVTTL	0	3	1.4	-
LVCMOS2	0	2.5	1.125	-
PCI33_3	Per PCI Spec			-
PCI66_3	Per PCI Spec			-
GTL	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	0.80
GTL+	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	1.0
HSTL Class I	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.75
HSTL Class III	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
HSTL Class IV	$V_{REF} - 0.5$	$V_{REF} + 0.5$	V_{REF}	0.90
SSTL3 I & II	$V_{REF} - 1.0$	$V_{REF} + 1.0$	V_{REF}	1.5
SSTL2 I & II	$V_{REF} - 0.75$	$V_{REF} + 0.75$	V_{REF}	1.25
CTT	$V_{REF} - 0.2$	$V_{REF} + 0.2$	V_{REF}	1.5
AGP	$V_{REF} - (0.2xV_{CCO})$	$V_{REF} + (0.2xV_{CCO})$	V_{REF}	Per AGP Spec
LVDS	1.2 – 0.125	1.2 + 0.125	1.2	
LVPECL	1.6 – 0.3	1.6 + 0.3	1.6	

Notes:
1. Input waveform switches between V_L and V_H.
2. Measurements are made at V_{REF} (Typ), Maximum, and Minimum. Worst-case values are reported.

   I/O parameter measurements are made with the capacitance values shown in Table 14. See the **Application Examples** (Module 2) for appropriate terminations.

   I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

Clock Distribution Switching Characteristics

Symbol	Description	Min(1)	Max	Units
GCLK IOB and Buffer				
T_{GPIO}	Global Clock PAD to output.	0.38	0.7	ns
T_{GIO}	Global Clock Buffer I input to O output	0.11	0.50	ns

Notes:
1. The numbers for Min are Best Case **Advance** product specification numbers. See **DC Characteristics, page 1** for a description.

I/O Standard Global Clock Input Adjustments

Symbol(1)	Description	Standard	Min(2)	Max	Units
Data Input Delay Adjustments					
$T_{GPLVTTL}$	Standard-specific global clock input delay adjustments	LVTTL	0.0	0.0	ns
$T_{GPLVCMOS2}$		LVCMOS2	–0.02	0.0	ns
$T_{GPLVCMOS18}$		LVCMOS18	0.12	0.20	ns
T_{GLVDS}		LVDS	0.23	0.38	ns
$T_{GLVPECL}$		LVPECL	0.23	0.38	ns
$T_{GPPCI33\_3}$		PCI, 33 MHz, 3.3V	–0.05	0.08	ns
$T_{GPPCI66\_3}$		PCI, 66 MHz, 3.3V	–0.05	–0.11	ns
T_{GPGTL}		GTL	0.20	0.37	ns
T_{GPGTLP}		GTL+	0.20	0.37	ns
T_{GPHSTL}		HSTL	0.18	0.27	ns
$T_{GPSSTL2}$		SSTL2	0.21	0.27	ns
$T_{GPSSTL3}$		SSTL3	0.18	0.27	ns
T_{GPCTT}		CTT	0.22	0.33	ns
T_{GPAGP}		AGP	0.21	0.27	ns

Notes:
1. Input timing for GPLVTTL is measured at 1.4V. For other I/O standards, see Table 2.
2. The numbers for Min are Best Case **Advance** product specification numbers. See **DC Characteristics, page 1** for a description.

CLB Switching Characteristics

Delays originating at F/G inputs vary slightly according to the input used, see Figure 2. The values listed below are worst-case. Precise values are provided by the timing analyzer.

Symbol	Description	Best Case(1)		Worst Case(2)		Units
		Min	Max	Min	Max	
Combinatorial Delays						
T_{ILO}	4-input function: F/G inputs to X/Y outputs	0.19	-	-	0.47	ns
T_{IF5}	5-input function: F/G inputs to F5 output	0.36	-	-	0.9	ns
T_{IF5X}	5-input function: F/G inputs to X output	0.35	-	-	0.9	ns
T_{IF6Y}	6-input function: F/G inputs to Y output via F6 MUX	0.35	-	-	1.0	ns
T_{F5INY}	6-input function: F5IN input to Y output	0.04	-	-	0.22	ns
T_{IFNCTL}	Incremental delay routing through transparent latch to XQ/YQ outputs	0.27	-	-	0.8	ns
T_{BYYB}	BY input to YB output	0.19	-	-	0.51	ns
Sequential Delays						
T_{CKO}	FF Clock CLK to XQ/YQ outputs	0.34	-	-	1.0	ns
T_{CKLO}	Latch Clock CLK to XQ/YQ outputs	0.40	-	-	1.0	ns
Setup and Hold Times before/after Clock CLK						
T_{ICK} / T_{CKI}	4-input function: F/G Inputs	0.39 / 0	-	1.1 / 0	-	ns
T_{IF5CK} / T_{CKIF5}	5-input function: F/G inputs	0.55 / 0	-	1.5 / 0	-	ns
T_{F5INCK} / T_{CKF5IN}	6-input function: F5IN input	0.27 / 0	-	0.8 / 0	-	ns
T_{IF6CK} / T_{CKIF6}	6-input function: F/G inputs via F6 MUX	0.58 / 0	-	1.6 / 0	-	ns
T_{DICK} / T_{CKDI}	BX/BY inputs	0.25 / 0	-	0.8 / 0	-	ns
T_{CECK} / T_{CKCE}	CE input	0.28 / 0	-	0.7 / 0	-	ns
T_{RCK} / T_{CKR}	SR/BY inputs (synchronous)	0.24 / 0	-	0.6 / 0	-	ns
Clock CLK						
T_{CH}	Minimum Pulse Width, High	1.4	-	1.4	-	ns
T_{CL}	Minimum Pulse Width, Low	1.4	-	1.4	-	ns
Set/Reset						
T_{RPW}	Minimum Pulse Width, SR/BY inputs	0.94	-	2.4	-	ns
T_{RQ}	Delay from SR/BY inputs to XQ/YQ outputs (asynchronous)	0.39	-	-	1.0	ns
F_{TOG}	Toggle Frequency (MHz) (for export control)	-	-	-	357.2	MHz

Notes:
1. Best Case Numbers are **Advance** product specification numbers. See **DC Characteristics**, page 1 for a description.
2. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

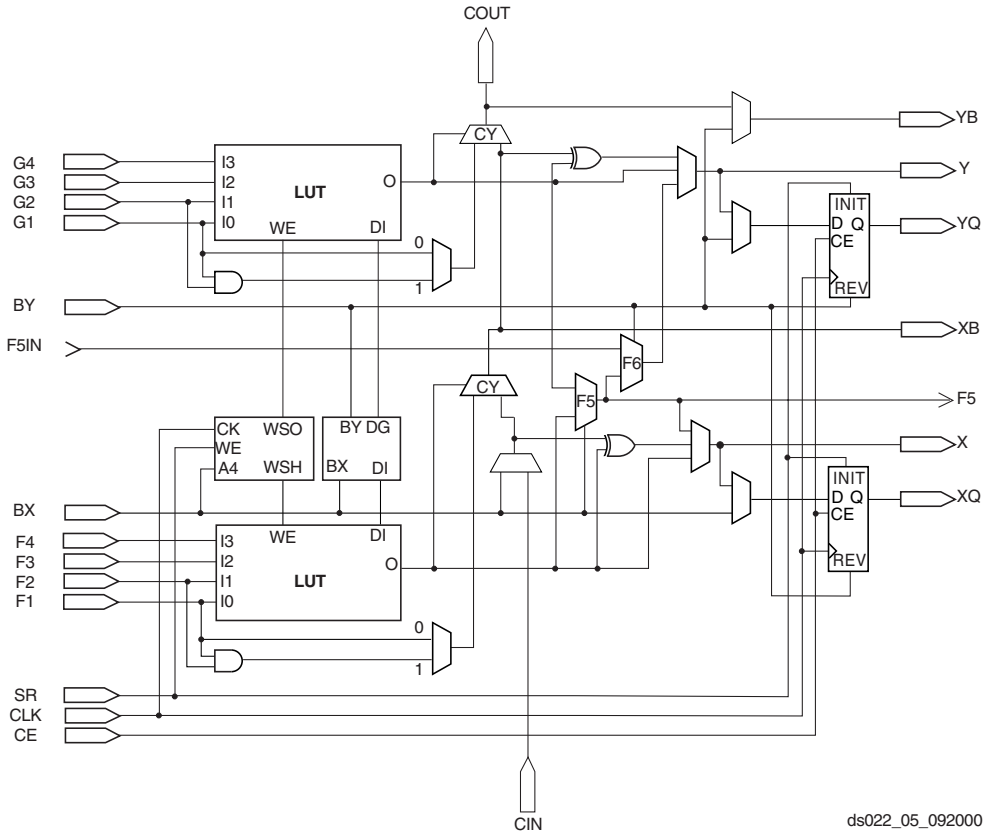


Figure 2: **Detailed View of Virtex-E Slice**

CLB Arithmetic Switching Characteristics

Setup times not listed explicitly can be approximated by decreasing the combinatorial delays by the setup time adjustment listed. Precise values are provided by the timing analyzer.

Symbol	Description	Best Case(1)		Worst Case(2)		Units
		Min	Max	Min	Max	
Combinatorial Delays						
T_{OPX}	F operand inputs to X via XOR	0.32	-	-	0.8	ns
T_{OPXB}	F operand input to XB output	0.35	-	-	0.9	ns
T_{OPY}	F operand input to Y via XOR	0.59	-	-	1.5	ns
T_{OPYB}	F operand input to YB output	0.48	-	-	1.3	ns
T_{OPCYF}	F operand input to COUT output	0.37	-	-	1.0	ns
T_{OPGY}	G operand inputs to Y via XOR	0.34	-	-	0.9	ns
T_{OPGYB}	G operand input to YB output	0.47	-	-	1.3	ns
T_{OPCYG}	G operand input to COUT output	0.36	-	-	1.0	ns
T_{BXCY}	BX initialization input to COUT	0.19	-	-	0.57	ns
T_{CINX}	CIN input to X output via XOR	0.27	-	-	0.7	ns
T_{CINXB}	CIN input to XB	0.02	-	-	0.08	ns
T_{CINY}	CIN input to Y via XOR	0.26	-	-	0.7	ns
T_{CINYB}	CIN input to YB	0.16	-	-	0.43	ns
T_{BYP}	CIN input to COUT output	0.05	-	-	0.15	ns
Multiplier Operation						
T_{FANDXB}	F1/2 operand inputs to XB output via AND	0.10	-	-	0.39	ns
T_{FANDYB}	F1/2 operand inputs to YB output via AND	0.28	-	-	0.8	ns
T_{FANDCY}	F1/2 operand inputs to COUT output via AND	0.17	-	-	0.51	ns
T_{GANDYB}	G1/2 operand inputs to YB output via AND	0.20	-	-	0.7	ns
T_{GANDCY}	G1/2 operand inputs to COUT output via AND	0.09	-	-	0.34	ns
Setup and Hold Times before/after Clock CLK						
T_{CCKX}/T_{CKCX}	CIN input to FFX	0.47 / 0	-	1.3 / 0	-	ns
T_{CCKY}/T_{CKCY}	CIN input to FFY	0.49 / 0	-	1.3 / 0	-	ns

Notes:
1. Best Case Numbers are **Advance** product specification numbers. See **DC Characteristics**, page 1 for a description.
2. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.

CLB Distributed RAM Switching Characteristics

Symbol	Description	Best Case		Worst Case(1)		Units
		Min(2)	Max	Min	Max	
Sequential Delays						
$T_{SHCKO16}$	Clock CLK to X/Y outputs (WE active) 16 x 1 mode	0.67	-	-	1.7	ns
$T_{SHCKO32}$	Clock CLK to X/Y outputs (WE active) 32 x 1 mode	0.84	-	-	2.1	ns
Shift-Register Mode						
T_{REG}	Clock CLK to X/Y outputs	1.25	-	-	3.2	ns
Setup and Hold Times before/after Clock CLK						
T_{AS}/T_{AH}	F/G address inputs	0.19 / 0	-	0.47 / 0	-	ns
T_{DS}/T_{DH}	BX/BY data inputs (DIN)	0.24 / 0	-	0.6 / 0	-	ns
T_{WS}/T_{WH}	CE input (WE)	0.29 / 0	-	0.8 / 0	-	ns
Shift-Register Mode						
T_{SHDICK}	BX/BY data inputs (DIN)	0.24 / 0	-	0.6 / 0	-	ns
T_{SHCECK}	CE input (WS)	0.29 / 0	-	0.8 / 0	-	ns
Clock CLK						
T_{WPH}	Minimum Pulse Width, High	0.96	-	2.4	-	ns
T_{WPL}	Minimum Pulse Width, Low	0.96	-	2.4	-	ns
T_{WC}	Minimum clock period to meet address write cycle time	1.92	-	4.8	-	ns
Shift-Register Mode						
T_{SRPH}	Minimum Pulse Width, High	1.0	-	2.4	-	ns
T_{SRPL}	Minimum Pulse Width, Low	1.0	-	2.4	-	ns

Notes:
1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.
2. The numbers for Min are **Advance** product specification numbers. See **DC Characteristics**, page 1 for a description.

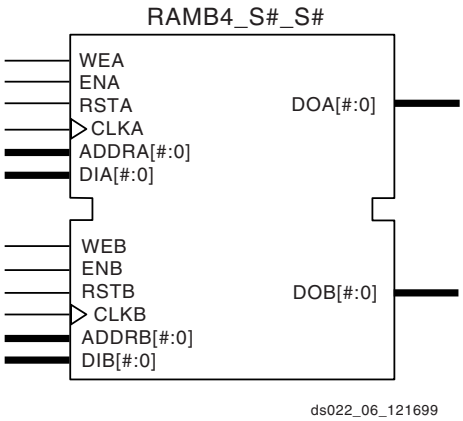


Figure 3: **Dual-Port Block SelectRAM**

Block RAM Switching Characteristics

Symbol	Description	Best Case		Worst Case(1)		Units
		Min(2)	Max	Min	Max	
Sequential Delays						
T_{BCKO}	Clock CLK to DOUT output	0.63	-	-	3.5	ns
Setup and Hold Times before Clock CLK						
T_{BACK}/T_{BCKA}	ADDR inputs	0.42 / 0	-	1.1 / 0	-	ns
T_{BDCK}/T_{BCKD}	DIN inputs	0.42 / 0	-	1.1 / 0	-	ns
T_{BECK}/T_{BCKE}	EN input	0.97 / 0	-	2.5 / 0	-	ns
T_{BRCK}/T_{BCKR}	RST input	0.9 / 0	-	2.3 / 0	-	ns
T_{BWCK}/T_{BCKW}	WEN input	0.86 / 0	-	2.2 / 0	-	ns
Clock CLK						
T_{BPWH}	Minimum Pulse Width, High	0.6	-	1.5	-	ns
T_{BPWL}	Minimum Pulse Width, Low	0.6	-	1.5	-	ns
T_{BCCS}	CLKA -> CLKB setup time for different ports	1.2	-	3.0	-	ns

Notes:
1. A Zero "0" Hold Time listing indicates no hold time or a negative hold time. Negative values can not be guaranteed "best-case", but if a "0" is listed, there is no positive hold time.
2. The numbers for Min are **Advance** product specification numbers. See **DC Characteristics**, page 1 for a description.

TBUF Switching Characteristics

Symbol	Description	Best Case		Worst Case		Units
		Min(1)	Max	Min	Max	
Combinatorial Delays						
T_{IO}	IN input to OUT output	0.0	-	-	0 .0	ns
T_{OFF}	TRI input to OUT output high-impedance	0.05	-	-	0.11	ns
T_{ON}	TRI input to valid data on OUT output	0.05	-	-	0.11	ns

Notes:
1. The numbers for Min are **Advance** product specification numbers. See **DC Characteristics**, page 1 for a description.

JTAG Test Access Port Switching Characteristics

Symbol	Description	Min	Max	Units
T_{TAPTK}	TMS and TDI Setup times before TCK	4.0	-	ns
T_{TCKTAP}	TMS and TDI Hold times after TCK	2.0	-	ns
T_{TCKTDO}	Output delay from clock TCK to output TDO	-	11.0	ns
F_{TCK}	Maximum TCK clock frequency	-	33	MHz

Virtex-E Pin-to-Pin Output Parameter Guidelines

Testing of switching parameters is modeled after testing methods specified by MIL-M-38510/605. All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted.

Global Clock Input to Output Delay for LVTTL, 12 mA, Fast Slew Rate, *with* DLL

Symbol	Description[1]	Device	Best Case		Worst Case		Units
			Min[4]	Max	Min	Max	
$T_{ICKOFDLL}$	LVTTL Global Clock Input to Output Delay using Output Flip-flop, 12 mA, Fast Slew Rate, *with* DLL. For data *output* with different standards, adjust the delays with the values shown in **IOB Output Switching Characteristics Standard Adjustments**, page 8.	XQV600E	1.0	-	-	3.1	ns
		XQV1000E	1.0	-	-	3.1	ns
		XQV2000E	1.0	-	-	3.1	ns

Notes:
1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with 35 pF external capacitive load. For other I/O standards and different loads, see Table 1 and Table 2.
3. DLL output jitter is already included in the timing calculation.
4. The numbers for Min are **Advance** product specification numbers. See **DC Characteristics**, page 1 for a description.

Global Clock Input to Output Delay for LVTTL, 12 mA, Fast Slew Rate, *without* DLL

Symbol	Description[1]	Device	Best Case		Worst Case		Units
			Min[4]	Max	Min	Max	
T_{ICKOF}	LVTTL Global Clock Input to Output Delay using Output Flip-flop, 12 mA, Fast Slew Rate, *without* DLL. For data *output* with different standards, adjust the delays with the values shown in **IOB Output Switching Characteristics Standard Adjustments**, page 8.	XQV600E	1.6	-	-	4.9	ns
		XQV1000E	1.7	-	-	5.0	ns
		XQV2000E	1.8	-	-	5.2	ns

Notes:
1. Listed above are representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible IOB and CLB flip-flops are clocked by the global clock net.
2. Output timing is measured at 50% V_{CC} threshold with 35 pF external capacitive load. For other I/O standards and different loads, see Table 1 and Table 2.
3. The numbers for Min are **Advance** product specification numbers. See **DC Characteristics**, page 1 for a description.

Virtex-E Pin-to-Pin Input Parameter Guidelines

Testing of switching parameters is modeled after testing methods specified by MIL-M-38510/605. All devices are 100% functionally tested. Listed below are representative values for typical pin locations and normal clock loading. Values are expressed in nanoseconds unless otherwise noted.

Global Clock Set-Up and Hold for LVTTL Standard, *with* DLL

Symbol	Description(1)	Device	Best Case		Worst Case		Units
			Min(4)	Max	Min	Max	
T_{PSDLL}/T_{PHDLL}	No Delay. Global Clock and IFF, with DLL. Input Setup and Hold Time Relative to Global Clock Input Signal for LVTTL Standard. For data input with different standards, adjust the setup time delay by the values shown in **IOB Input Switching Characteristics Standard Adjustments**, page 6.	XQV600E	1.5 / –0.4	-	-	1.7 / –0.4	ns
		XQV1000E	1.5 / –0.4	-	-	1.7 / –0.4	ns
		XQV2000E	1.5 / –0.4	-	-	1.7 / –0.4	ns

Notes:
1. IFF = Input Flip-Flop or Latch.
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. DLL output jitter is already included in the timing calculation.
4. The numbers for Min are **Advance** product specification numbers. See **DC Characteristics**, page 1 for a description.

Global Clock Set-Up and Hold for LVTTL Standard, *without* DLL

Symbol	Description(1)	Device	Best Case		Worst Case		Units
			Min(4)	Max	Min	Max	
T_{PSFD}/T_{PHFD}	Full Delay Global Clock and IFF, without DLL Input Setup and Hold Time Relative to Global Clock Input Signal for LVTTL Standard. For data input with different standards, adjust the setup time delay by the values shown in **IOB Input Switching Characteristics Standard Adjustments**, page 6.	XQV600E	2.1 / 0	-	-	2.1 / 0	ns
		XQV1000E	2.3 / 0	-	-	2.3 / 0	ns
		XQV2000E	2.5 / 0	-	-	2.5 / 0	ns

Notes:
1. IFF = Input Flip-Flop or Latch.
2. Setup time is measured relative to the Global Clock input signal with the fastest route and the lightest load. Hold time is measured relative to the Global Clock input signal with the slowest route and heaviest load.
3. DLL output jitter is already included in the timing calculation.
4. The numbers for Min are **Advance** product specification numbers. See **DC Characteristics**, page 1 for a description.

DLL Timing Parameters

Switching parameters testing is modeled after testing methods specified by MIL-M-38510/605; all devices are 100 percent functionally tested. Because of the difficulty in directly measuring many internal timing parameters, those parameters are derived from benchmark timing patterns. The following guidelines reflect worst-case values across the recommended operating conditions.

Description	Symbol	F_{CLKIN}	Min	Max	Units
Input Clock Frequency (CLKDLLHF)	FCLKINHF		60	275	MHz
Input Clock Frequency (CLKDLL)	FCLKINLF		25	135	MHz
Input Clock Low/High Pulse Width	T_{DLLPW}	≥ 25 MHz	5.0	-	ns
		≥ 50 MHz	3.0	-	ns
		≥100 MHz	2.4	-	ns
		≥ 150 MHz	2.0	-	ns
		≥ 200 MHz	1.8	-	ns
		≥ 250 MHz	1.5	-	ns
		≥ 300 MHz	NA	-	ns

Notes:
1. All specifications correspond to Military Operating Temperatures (-55°C to +125°C).

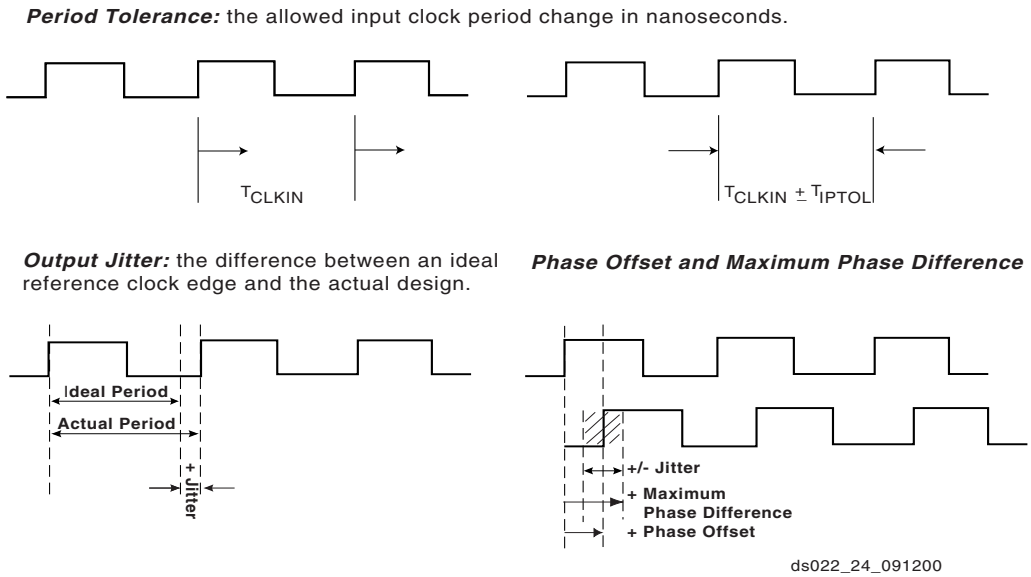


Figure 4: **DLL Timing Waveforms**

DLL Clock Tolerance, Jitter, and Phase Information

All DLL output jitter and phase specifications determined through statistical measurement at the package pins using a clock mirror configuration and matched drivers.

Symbol	Description	F_{CLKIN}	CLKDLLHF		CLKDLL		Units
			Min	Max	Min	Max	
T_{IPTOL}	Input Clock Period Tolerance		-	1.0	-	1.0	ns
T_{IJITCC}	Input Clock Jitter Tolerance (Cycle to Cycle)		-	± 150	-	± 300	ps
T_{LOCK}	Time Required for DLL to Acquire Lock	> 60 MHz	-	20	-	20	µs
		50 - 60 MHz	-	-	-	25	µs
		40 - 50 MHz	-	-	-	50	µs
		30 - 40 MHz	-	-	-	90	µs
		25 - 30 MHz	-	-	-	120	µs
T_{OJITCC}	Output Jitter (cycle-to-cycle) for any DLL Clock Output(1)		-	± 60	-	± 60	ps
T_{PHIO}	Phase Offset between CLKIN and CLKO(2)		-	± 100	-	± 100	ps
T_{PHOO}	Phase Offset between Clock Outputs on the DLL(3)		-	± 140	-	± 140	ps
T_{PHIOM}	Maximum Phase Difference between CLKIN and CLKO(4)		-	± 160	-	± 160	ps
T_{PHOOM}	Maximum Phase Difference between Clock Outputs on the DLL(5)		-	± 200	-	± 200	ps

Notes:
1. **Output Jitter** is cycle-to-cycle jitter measured on the DLL output clock, *excluding* input clock jitter.
2. **Phase Offset between CLKIN and CLKO** is the worst-case fixed time difference between rising edges of CLKIN and CLKO, *excluding* Output Jitter and input clock jitter.
3. **Phase Offset between Clock Outputs on the DLL** is the worst-case fixed time difference between rising edges of any two DLL outputs, *excluding* Output Jitter and input clock jitter.
4. **Maximum Phase Difference between CLKIN an CLKO** is the sum of Output Jitter and Phase Offset between CLKIN and CLKO, or the greatest difference between CLKIN and CLKO rising edges due to DLL alone (*excluding* input clock jitter).
5. **Maximum Phase DIfference between Clock Outputs on the DLL** is the sum of Output JItter and Phase Offset between any DLL clock outputs, or the greatest difference between any two DLL output rising edges sue to DLL alone (*excluding* input clock jitter).
6. All specifications correspond to Military Operating Temperatures (-55°C to +125°C).

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
05/19/03	1.0	Initial Xilinx release.
07/29/04	1.1	• Table **Absolute Maximum Ratings**, page 1: - Revised V_{IN} from "–0.5 to 4.0" to "–0.5 to V_{CCO} + 0.5". - Removed Footnote (2) regarding power-up sequencing. Former Footnote (3) is now Footnote (2). - Added new Footnote (3) regarding PCI standard compliance. • Table **DC Characteristics Over Recommended Operating Conditions**, page 2: Revised I_{CCINTQ} for XQV2000E device from 500 mA to 1100 mA. • Section **Power-On Power Supply Requirements**, page 2: Added reference to XAPP158 regarding power supply requirements. • Table **IOB Input Switching Characteristics**, page 5, and **IOB Output Switching Characteristics, Figure 1**, page 7: Added T_{CH} and T_{CL} pulse width parameters for clock CLK.

Virtex-E Pin Definitions

Pin Name	Dedicated Pin	Direction	Description
GCK0, GCK1, GCK2, GCK3	Yes	Input	Clock input pins that connect to Global Clock Buffers.
M0, M1, M2	Yes	Input	Mode pins are used to specify the configuration mode.
CCLK	Yes	Input or Output	The configuration Clock I/O pin: it is an input for SelectMAP and slave-serial modes, and output in master-serial mode. After configuration, it is input only, logic level = Don't Care.
PROGRAM	Yes	Input	Initiates a configuration sequence when asserted Low.
DONE	Yes	Bidirectional	Indicates that configuration loading is complete, and that the start-up sequence is in progress. The output can be open drain.
INIT	No	Bidirectional (Open-drain)	When Low, indicates that the configuration memory is being cleared. The pin becomes a user I/O after configuration.
BUSY/DOUT	No	Output	In SelectMAP mode, BUSY controls the rate at which configuration data is loaded. The pin becomes a user I/O after configuration unless the SelectMAP port is retained. In bit-serial modes, DOUT provides preamble and configuration data to downstream devices in a daisy-chain. The pin becomes a user I/O after configuration.
D0/DIN, D1, D2, D3, D4, D5, D6, D7	No	Input or Output	In SelectMAP mode, D0-D7 are configuration data pins. These pins become user I/Os after configuration unless the SelectMAP port is retained. In bit-serial modes, DIN is the single data input. This pin becomes a user I/O after configuration.
WRITE	No	Input	In SelectMAP mode, the active-low Write Enable signal. The pin becomes a user I/O after configuration unless the SelectMAP port is retained.
CS	No	Input	In SelectMAP mode, the active-low Chip Select signal. The pin becomes a user I/O after configuration unless the SelectMAP port is retained.
TDI, TDO, TMS, TCK	Yes	Mixed	Boundary-scan Test-Access-Port pins, as defined in IEEE1149.1.
DXN, DXP	Yes	N/A	Temperature-sensing diode pins. (Anode: DXP, cathode: DXN)
V_{CCINT}	Yes	Input	Power-supply pins for the internal core logic.
V_{CCO}	Yes	Input	Power-supply pins for the output drivers (subject to banking rules)
V_{REF}	No	Input	Input threshold voltage pins. Become user I/Os when an external threshold voltage is not needed (subject to banking rules).
GND	Yes	Input	Ground

Low Voltage Differential Signals

The Virtex-E family incorporates low-voltage signalling (LVDS and LVPECL). Two pins are utilized for these signals to be connected to a Virtex-E device. These are known as differential pin pairs. Each differential pin pair has a Positive (P) and a Negative (N) pin. These pairs are labeled in the following manner.

IO_L#[P/N]

where

L = LVDS or LVPECL pin
# = Pin Pair Number
P = Positive
N = Negative

I/O pins for differential signals can either be synchronous or asynchronous, input or output. The pin pairs can be used for synchronous input and output signals as well as asynchronous input signals. However, only some of the low-voltage pairs can be used for asynchronous output signals.

DIfferential signals require the pins of a pair to switch almost simultaneously. If the signals driving the pins are from IOB flip-flops, they are synchronous. If the signals driving the pins are from internal logic, they are asynchronous. Table 1 defines the names and function of the different types of low-voltage pin pairs in the Virtex-E family.

Virtex-E Package Pinouts

The QPro Virtex-E family of FPGAs is available in three popular packages, including plastic ball grid, fine-pitch plastic ball grid, and hermetic ceramic column grid arrays. Family members have footprint compatibility across devices provided in the same package. The pinout tables in this section indicate function, pin, and bank information for each package/device combination. Following each pinout table is an additional table summarizing information specific to differential pin pairs for all devices provided in that package.

Table 1: **LVDS Pin Pairs**

Pin Name	Description
IO_L#[P/N] Example: IO_L22N	Represents a general IO or a synchronous input/output differential signal. When used as a differential signal, N means Negative I/O and P means Positive I/O.
IO_L#[P/N]_Y Example: IO_L22N_Y	Represents a general IO or a synchronous input/output differential signal, or a part-dependent asynchronous output differential signal.
IO_L#[P/N]_YY Example: O_L22N_YY	Represents a general IO or a synchronous input/output differential signal, or an asynchronous output differential signal.
IO_LVDS_DLL_L#[P/N] Example: IO_LVDS_DLL_L16N	Represents a general IO or a synchronous input/output differential signal, a differential clock input signal, or a DLL input. When used as a differential clock input, this pin is paired with the adjacent GCK pin. The GCK pin is always the positive input in the differential clock input configuration.

BG432 Ball Grid Array Packages

XQV600E devices are available in the BG432 Ball Grid Array package and supports output banking. See Table 2 for pinout information. Immediately following Table 2, see Table 3 for Differential Pair information.

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
0	GCK3	D17
0	IO	A22
0	IO	A26
0	IO	B20
0	IO	C23
0	IO	C28
0	IO_L0N_Y	B29
0	IO_L0P_Y	D27
0	IO_L1N_YY	B28
0	IO_L1P_YY	C27
0	IO_VREF_L2N_YY	D26
0	IO_L2P_YY	A28
0	IO_L3N_Y	B27
0	IO_L3P_Y	C26
0	IO_L4N_YY	D25
0	IO_L4P_YY	A27
0	IO_VREF_L5N_YY	D24
0	IO_L5P_YY	C25
0	IO_L6N_Y	B25
0	IO_L6P_Y	D23
0	IO_VREF_L7N_Y	C24
0	IO_L7P_Y	B24
0	IO_VREF_L8N_YY	D22
0	IO_L8P_YY	A24
0	IO_L9N_YY	C22
0	IO_L9P_YY	B22
0	IO_L10N_YY	C21
0	IO_L10P_YY	D20
0	IO_L11N_YY	B21
0	IO_L11P_YY	C20
0	IO_L12N_YY	A20
0	IO_L12P_YY	D19
0	IO_VREF_L13N_YY	B19
0	IO_L13P_YY	A19
0	IO_L14N_Y	B18
0	IO_L14P_Y	D18
0	IO_VREF_L15N_Y	C18
0	IO_L15P_Y	B17
0	IO_LVDS_DLL_L16N	C17
1	GCK2	A16
1	IO	A12
1	IO	B9
1	IO	B11
1	IO	C16
1	IO	D9
1	IO_LVDS_DLL_L16P	B16
1	IO_L17N_Y	A15
1	IO_VREF_L17P_Y	B15
1	IO_L18N_Y	C15
1	IO_L18P_Y	D15
1	IO_L19N_YY	B14
1	IO_VREF_L19P_YY	A13
1	IO_L20N_YY	B13
1	IO_L20P_YY	D14
1	IO_L21N_YY	C13
1	IO_L21P_YY	B12
1	IO_L22N_YY	D13
1	IO_L22P_YY	C12
1	IO_L23N_YY	D12
1	IO_L23P_YY	C11
1	IO_L24N_YY	B10
1	IO_VREF_L24P_YY	C10
1	IO_L25N_Y	C9
1	IO_VREF_L25P_Y	D10
1	IO_L26N_Y	A8
1	IO_L26P_Y	B8
1	IO_L27N_YY	C8

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
1	IO_VREF_L27P_YY	B7
1	IO_L28N_YY	D8
1	IO_L28P_YY	A6
1	IO_L29N_Y	B6
1	IO_L29P_Y	D7
1	IO_L30N_YY	A5
1	IO_VREF_L30P_YY	C6
1	IO_L31N_YY	B5
1	IO_L31P_YY	D6
1	IO_L32N_Y	A4
1	IO_L32P_Y	C5
1	IO_WRITE_L33N_YY	B4
1	IO_CS_L33P_YY	D5
2	IO	H4
2	IO	J3
2	IO	L3
2	IO	M1
2	IO	R2
2	IO_DOUT_BUSY_L34P_YY	D3
2	IO_DIN_D0_L34N_YY	C2
2	IO_L35P	D2
2	IO_L35N	E4
2	IO_L36P_Y	D1
2	IO_L36N_Y	E3
2	IO_VREF_L37P_Y	E2
2	IO_L37N_Y	F4
2	IO_L38P	E1
2	IO_L38N	F3
2	IO_L39P_Y	F2
2	IO_L39N_Y	G4
2	IO_VREF_L40P_YY	G3
2	IO_L40N_YY	G2
2	IO_L41P_Y	H3
2	IO_L41N_Y	H2
2	IO_VREF_L42P_Y	H1

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
2	IO_L42N_Y	J4
2	IO_VREF_L43P_YY	J2
2	IO_D1_L43N_YY	K4
2	IO_D2_L44P_YY	K2
2	IO_L44N_YY	K1
2	IO_L45P_Y	L2
2	IO_L45N_Y	M4
2	IO_L46P_Y	M3
2	IO_L46N_Y	M2
2	IO_L47P_Y	N4
2	IO_L47N_Y	N3
2	IO_VREF_L48P_YY	N1
2	IO_D3_L48N_YY	P4
2	IO_L49P_Y	P3
2	IO_L49N_Y	P2
2	IO_VREF_L50P_Y	R3
2	IO_L50N_Y	R4
2	IO_L51P_YY	R1
2	IO_L51N_YY	T3
3	IO	AA2
3	IO	AC2
3	IO	AE2
3	IO	U3
3	IO	W1
3	IO_L52P_Y	U4
3	IO_VREF_L52N_Y	U2[2]
3	IO_L53P_Y	U1
3	IO_L53N_Y	V3
3	IO_D4_L54P_YY	V4
3	IO_VREF_L54N_YY	V2
3	IO_L55P_Y	W3
3	IO_L55N_Y	W4
3	IO_L56P_Y	Y1
3	IO_L56N_Y	Y3
3	IO_L57P_Y	Y4

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
3	IO_L57N_Y	Y2
3	IO_L58P_YY	AA3
3	IO_D5_L58N_YY	AB1
3	IO_D6_L59P_YY	AB3
3	IO_VREF_L59N_YY	AB4
3	IO_L60P_Y	AD1
3	IO_VREF_L60N_Y	AC3
3	IO_L61P_Y	AC4
3	IO_L61N_Y	AD2
3	IO_L62P_YY	AD3
3	IO_VREF_L62N_YY	AD4
3	IO_L63P_Y	AF2
3	IO_L63N_Y	AE3
3	IO_L64P	AE4
3	IO_L64N	AG1
3	IO_L65P_Y	AG2
3	IO_VREF_L65N_Y	AF3
3	IO_L66P_Y	AF4
3	IO_L66N_Y	AH1
3	IO_L67P	AH2
3	IO_L67N	AG3
3	IO_D7_L68P_YY	AG4
3	IO_INIT_L68N_YY	AJ2
3	IO	T2
4	GCK0	AL16
4	IO	AH10
4	IO	AJ11
4	IO	AK7
4	IO	AL12
4	IO	AL15
4	IO_L69P_YY	AJ4
4	IO_L69N_YY	AK3
4	IO_L70P_Y	AH5
4	IO_L70N_Y	AK4
4	IO_L71P_YY	AJ5

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
4	IO_L71N_YY	AH6
4	IO_VREF_L72P_YY	AL4
4	IO_L72N_YY	AK5
4	IO_L73P_Y	AJ6
4	IO_L73N_Y	AH7
4	IO_L74P_YY	AL5
4	IO_L74N_YY	AK6
4	IO_VREF_L75P_YY	AJ7
4	IO_L75N_YY	AL6
4	IO_L76P_Y	AH9
4	IO_L76N_Y	AJ8
4	IO_VREF_L77P_Y	AK8[1]
4	IO_L77N_Y	AJ9
4	IO_VREF_L78P_YY	AL8
4	IO_L78N_YY	AK9
4	IO_L79P_YY	AK10
4	IO_L79N_YY	AL10
4	IO_L80P_YY	AH12
4	IO_L80N_YY	AK11
4	IO_L81P_YY	AJ12
4	IO_L81N_YY	AK12
4	IO_L82P_YY	AH13
4	IO_L82N_YY	AJ13
4	IO_VREF_L83P_YY	AL13
4	IO_L83N_YY	AK14
4	IO_L84P_Y	AH14
4	IO_L84N_Y	AJ14
4	IO_VREF_L85P_Y	AK15[2]
4	IO_L85N_Y	AJ15
4	IO_LVDS_DLL_L86P	AH15
5	GCK1	AK16
5	IO	AH20
5	IO	AJ19
5	IO	AJ23
5	IO	AJ24

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
5	IO_LVDS_DLL_L86N	AL17
5	IO_L87P_Y	AK17
5	IO_VREF_L87N_Y	AJ17[2]
5	IO_L88P_Y	AH17
5	IO_L88N_Y	AK18
5	IO_L89P_YY	AL19
5	IO_VREF_L89N_YY	AJ18
5	IO_L90P_YY	AH18
5	IO_L90N_YY	AL20
5	IO_L91P_YY	AK20
5	IO_L91N_YY	AH19
5	IO_L92P_YY	AJ20
5	IO_L92N_YY	AK21
5	IO_L93P_YY	AJ21
5	IO_L93N_YY	AL22
5	IO_L94P_YY	AJ22
5	IO_VREF_L94N_YY	AK23
5	IO_L95P_Y	AH22
5	IO_VREF_L95N_Y	AL24[1]
5	IO_L96P_Y	AK24
5	IO_L96N_Y	AH23
5	IO_L97P_YY	AK25
5	IO_VREF_L97N_YY	AJ25
5	IO_L98P_YY	AL26
5	IO_L98N_YY	AK26
5	IO_L99P_Y	AH25
5	IO_L99N_Y	AL27
5	IO_L100P_YY	AJ26
5	IO_VREF_L100N_YY	AK27
5	IO_L101P_YY	AH26
5	IO_L101N_YY	AL28
5	IO_L102P_Y	AJ27
5	IO_L102N_Y	AK28
6	IO	AA30
6	IO	AC30

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
6	IO	AD29
6	IO	U31
6	IO	W28
6	IO_L103N_YY	AJ30
6	IO_L103P_YY	AH30
6	IO_L104N	AG28
6	IO_L104P	AH31
6	IO_L105N_Y	AG29
6	IO_L105P_Y	AG30
6	IO_VREF_L106N_Y	AF28
6	IO_L106P_Y	AG31
6	IO_L107N	AF29
6	IO_L107P	AF30
6	IO_L108N_Y	AE28
6	IO_L108P_Y	AF31
6	IO_VREF_L109N_YY	AE30
6	IO_L109P_YY	AD28
6	IO_L110N_Y	AD30
6	IO_L110P_Y	AD31
6	IO_VREF_L111N_Y	AC28[1]
6	IO_L111P_Y	AC29
6	IO_VREF_L112N_YY	AB28
6	IO_L112P_YY	AB29
6	IO_L113N_YY	AB31
6	IO_L113P_YY	AA29
6	IO_L114N_Y	Y28
6	IO_L114P_Y	Y29
6	IO_L115N_Y	Y30
6	IO_L115P_Y	Y31
6	IO_L116N_Y	W29
6	IO_L116P_Y	W30
6	IO_VREF_L117N_YY	V28
6	IO_L117P_YY	V29
6	IO_L118N_Y	V30
6	IO_L118P_Y	U29
6	IO_VREF_L119N_Y	U28

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
6	IO_L119P_Y	U30
6	IO	T30
7	IO	C30
7	IO	H29
7	IO	H31
7	IO	L29
7	IO	M31
7	IO	R28
7	IO_L120N_YY	T31
7	IO_L120P_YY	R29
7	IO_L121N_Y	R30
7	IO_VREF_L121P_Y	R31
7	IO_L122N_Y	P29
7	IO_L122P_Y	P28
7	IO_L123N_YY	P30
7	IO_VREF_L123P_YY	N30
7	IO_L124N_Y	N28
7	IO_L124P_Y	N31
7	IO_L125N_Y	M29
7	IO_L125P_Y	M28
7	IO_L126N_Y	M30
7	IO_L126P_Y	L30
7	IO_L127N_YY	K31
7	IO_L127P_YY	K30
7	IO_L128N_YY	K28
7	IO_VREF_L128P_YY	J30
7	IO_L129N_Y	J29
7	IO_VREF_L129P_Y	J28[1]
7	IO_L130N_Y	H30
7	IO_L130P_Y	G30
7	IO_L131N_YY	H28
7	IO_VREF_L131P_YY	F31
7	IO_L132N_Y	G29
7	IO_L132P_Y	G28
7	IO_L133N	E31

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
7	IO_L133P	E30
7	IO_L134N_Y	F29
7	IO_VREF_L134P_Y	F28
7	IO_L135N_Y	D31
7	IO_L135P_Y	D30
7	IO_L136N	E29
7	IO_L136P	E28
2	CCLK	D4
3	DONE	AH4
NA	DXN	AH27
NA	DXP	AK29
NA	M0	AH28
NA	M1	AH29
NA	M2	AJ28
NA	PROGRAM	AH3
NA	TCK	D28
NA	TDI	B3
2	TDO	C4
NA	TMS	D29
NA	VCCINT	A10
NA	VCCINT	A17
NA	VCCINT	B23
NA	VCCINT	B26
NA	VCCINT	C7
NA	VCCINT	C14
NA	VCCINT	C19
NA	VCCINT	F1
NA	VCCINT	F30
NA	VCCINT	K3
NA	VCCINT	K29
NA	VCCINT	N2
NA	VCCINT	N29
NA	VCCINT	T1
NA	VCCINT	T29

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
NA	VCCINT	W2
NA	VCCINT	W31
NA	VCCINT	AB2
NA	VCCINT	AB30
NA	VCCINT	AE29
NA	VCCINT	AF1
NA	VCCINT	AH8
NA	VCCINT	AH24
NA	VCCINT	AJ10
NA	VCCINT	AJ16
NA	VCCINT	AK22
NA	VCCINT	AK13
NA	VCCINT	AK19
0	VCCO	A21
0	VCCO	C29
0	VCCO	D21
1	VCCO	A1
1	VCCO	A11
1	VCCO	D11
2	VCCO	C3
2	VCCO	L4
2	VCCO	L1
3	VCCO	AA1
3	VCCO	AA4
3	VCCO	AJ3
4	VCCO	AH11
4	VCCO	AL1
4	VCCO	AL11
5	VCCO	AH21
5	VCCO	AL21
5	VCCO	AJ29
6	VCCO	AA28
6	VCCO	AA31
6	VCCO	AL31
7	VCCO	A31

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
7	VCCO	L28
7	VCCO	L31
NA	GND	A2
NA	GND	A3
NA	GND	A7
NA	GND	A9
NA	GND	A14
NA	GND	A18
NA	GND	A23
NA	GND	A25
NA	GND	A29
NA	GND	A30
NA	GND	B1
NA	GND	B2
NA	GND	B30
NA	GND	B31
NA	GND	C1
NA	GND	C31
NA	GND	D16
NA	GND	G1
NA	GND	G31
NA	GND	J1
NA	GND	J31
NA	GND	P1
NA	GND	P31
NA	GND	T4
NA	GND	T28
NA	GND	V1
NA	GND	V31
NA	GND	AC1
NA	GND	AC31
NA	GND	AE1
NA	GND	AE31
NA	GND	AH16
NA	GND	AJ1

Table 2: **BG432 — XQV600E**

Bank	Pin Description	Pin #
NA	GND	AJ31
NA	GND	AK1
NA	GND	AK2
NA	GND	AK30
NA	GND	AK31
NA	GND	AL2
NA	GND	AL3
NA	GND	AL7
NA	GND	AL9
NA	GND	AL14
NA	GND	AL18
NA	GND	AL23
NA	GND	AL25
NA	GND	AL29
NA	GND	AL30

BG432 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 3: **BG432 Differential Pin Pair Summary XQV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	AL16	AH15	NA	IO_DLL_L86P
1	5	AK16	AL17	NA	IO_DLL_L86N
2	1	A16	B16	NA	IO_DLL_L16P
3	0	D17	C17	NA	IO_DLL_L16N
IO LVDS Total Outputs: 137, Asynchronous Output Pairs: 63					
0	0	D27	B29	√	-
1	0	C27	B28	√	-
2	0	A28	D26	√	VREF

Table 3: **BG432 Differential Pin Pair Summary XQV600E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
3	0	C26	B27	NA	-
4	0	A27	D25	√	-
5	0	C25	D24	√	VREF
6	0	D23	B25	√	-
7	0	B24	C24	√	VREF
8	0	A24	D22	√	VREF
9	0	B22	C22	√	-
10	0	D20	C21	√	-
11	0	C20	B21	√	-
12	0	D19	A20	√	-
13	0	A19	B19	√	VREF
14	0	D18	B18	√	-
15	0	B17	C18	√	VREF
16	1	B16	C17	NA	IO_LVDS_DLL
17	1	B15	A15	√	VREF
18	1	D15	C15	√	-
19	1	A13	B14	√	VREF
20	1	D14	B13	√	-
21	1	B12	C13	√	-
22	1	C12	D13	√	-
23	1	C11	D12	√	-
24	1	C10	B10	√	VREF
25	1	D10	C9	√	VREF
26	1	B8	A8	√	-
27	1	B7	C8	√	VREF
28	1	A6	D8	√	-
29	1	D7	B6	NA	-
30	1	C6	A5	√	VREF
31	1	D6	B5	√	-
32	1	C5	A4	√	-
33	1	D5	B4	√	CS, WRITE
34	2	D3	C2	√	DIN, D0, BUSY

Table 3: **BG432 Differential Pin Pair Summary**
XQV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
35	2	D2	E4	√	-
36	2	D1	E3	NA	-
37	2	E2	F4	√	VREF
38	2	E1	F3	√	-
39	2	F2	G4	√	-
40	2	G3	G2	√	VREF
41	2	H3	H2	NA	-
42	2	H1	J4	√	VREF
43	2	J2	K4	√	D1
44	2	K2	K1	√	D2
45	2	L2	M4	4	-
46	2	M3	M2	√	-
47	2	N4	N3	√	-
48	2	N1	P4	√	D3
49	2	P3	P2	NA	-
50	2	R3	R4	√	VREF
51	2	R1	T3	√	-
52	3	U4	U2	√	VREF
53	3	U1	V3	NA	-
54	3	V4	V2	√	VREF
55	3	W3	W4	√	-
56	3	Y1	Y3	√	-
57	3	Y4	Y2	NA	-
58	3	AA3	AB1	√	D5
59	3	AB3	AB4	√	VREF
60	3	AD1	AC3	√	VREF
61	3	AC4	AD2	NA	-
62	3	AD3	AD4	√	VREF
63	3	AF2	AE3	√	-
64	3	AE4	AG1	√	-
65	3	AG2	AF3	√	VREF
66	3	AF4	AH1	NA	-

Table 3: **BG432 Differential Pin Pair Summary**
XQV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
67	3	AH2	AG3	√	-
68	3	AG4	AJ2	√	INIT
69	4	AJ4	AK3	√	-
70	4	AH5	AK4	√	-
71	4	AJ5	AH6	√	-
72	4	AL4	AK5	√	VREF
73	4	AJ6	AH7	NA	-
74	4	AL5	AK6	√	-
75	4	AJ7	AL6	√	VREF
76	4	AH9	AJ8	√	-
77	4	AK8	AJ9	√	VREF
78	4	AL8	AK9	√	VREF
79	4	AK10	AL10	√	-
80	4	AH12	AK11	√	-
81	4	AJ12	AK12	√	-
82	4	AH13	AJ13	√	-
83	4	AL13	AK14	√	VREF
84	4	AH14	AJ14	√	-
85	4	AK15	AJ15	√	VREF
86	5	AH15	AL17	NA	IO_LVDS_DLL
87	5	AK17	AJ17	√	VREF
88	5	AH17	AK18	√	-
89	5	AL19	AJ18	√	VREF
90	5	AH18	AL20	√	-
91	5	AK20	AH19	√	-
92	5	AJ20	AK21	√	-
93	5	AJ21	AL22	√	-
94	5	AJ22	AK23	√	VREF
95	5	AH22	AL24	√	VREF
96	5	AK24	AH23	√	-
97	5	AK25	AJ25	√	VREF
98	5	AL26	AK26	√	-

Table 3: **BG432 Differential Pin Pair Summary**
XQV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
99	5	AH25	AL27	NA	-
100	5	AJ26	AK27	√	VREF
101	5	AH26	AL28	√	-
102	5	AJ27	AK28	√	-
103	6	AH30	AJ30	√	-
104	6	AH31	AG28	√	-
105	6	AG30	AG29	NA	-
106	6	AG31	AF28	√	VREF
107	6	AF30	AF29	√	-
108	6	AF31	AE28	√	-
109	6	AD28	AE30	√	VREF
110	6	AD31	AD30	NA	-
111	6	AC29	AC28	√	VREF
112	6	AB29	AB28	√	VREF
113	6	AA29	AB31	√	-
114	6	Y29	Y28	NA	-
115	6	Y31	Y30	√	-
116	6	W30	W29	√	-
117	6	V29	V28	√	VREF
118	6	U29	V30	NA	-
119	6	U30	U28	√	VREF
120	7	R29	T31	√	-
121	7	R31	R30	√	VREF
122	7	P28	P29	NA	-
123	7	N30	P30	√	VREF
124	7	N31	N28	√	-
125	7	M28	M29	√	-
126	7	L30	M30	NA	-
127	7	K30	K31	√	-
128	7	J30	K28	√	VREF
129	7	J28	J29	√	VREF
130	7	G30	H30	NA	-

Table 3: **BG432 Differential Pin Pair Summary**
XQV600E

Pair	Bank	P Pin	N Pin	AO	Other Functions
131	7	F31	H28	√	VREF
132	7	G28	G29	√	-
133	7	E30	E31	√	-
134	7	F28	F29	√	VREF
135	7	D30	D31	NA	-
136	7	E28	E29	√	-

BG560 Plastic Ball Grid and CG560 Ceramic Column Grid Array Packages

XQV1000E is the only Virtex-E device available in the CG560 Hermetic Ceramic Column Grid Array package. XQV1000E and XQV2000E devices are both available in BG560 Ball Grid Array packages and have footprint compatibility. Pins labeled I0_VREF can be used as either in all parts unless device-dependent as indicated in the footnotes. If the pin is not used as V_{REF}, it can be used as general I/O. Immediately following Table 4, see Table 5 for Differential Pair information.

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
0	GCK3	A17	
0	IO	A27	
0	IO	B25	
0	IO	C28	
0	IO	C30	
0	IO	D30	
0	IO_L0N	E28	
0	IO_VREF_L0P	D29	
0	IO_L1N_YY	D28	
0	IO_L1P_YY	A31	
0	IO_VREF_L2N_YY	E27	
0	IO_L2P_YY	C29	
0	IO_L3N_Y	B30	
0	IO_L3P_Y	D27	
0	IO_L4N_YY	E26	
0	IO_L4P_YY	B29	
0	IO_VREF_L5N_YY	D26	
0	IO_L5P_YY	C27	
0	IO_L6N_Y	E25	
0	IO_VREF_L6P_Y	A28	1
0	IO_L7N_Y	D25	
0	IO_L7P_Y	C26	
0	IO_VREF_L8N_Y	E24	
0	IO_L8P_Y	B26	
0	IO_L9N_Y	C25	
0	IO_L9P_Y	D24	
0	IO_VREF_L10N_YY	E23	
0	IO_L10P_YY	A25	
0	IO_L11N_YY	D23	
0	IO_L11P_YY	B24	
0	IO_L12N_Y	E22	
0	IO_L12P_Y	C23	
0	IO_L13N_YY	A23	
0	IO_L13P_YY	D22	
0	IO_VREF_L14N_YY	E21	
0	IO_L14P_YY	B22	
0	IO_L15N_Y	D21	
0	IO_L15P_Y	C21	
0	IO_L16N_YY	B21	
0	IO_L16P_YY	E20	
0	IO_VREF_L17N_YY	D20	
0	IO_L17P_YY	C20	
0	IO_L18N_Y	B20	
0	IO_L18P_Y	E19	
0	IO_L19N_Y	D19	
0	IO_L19P_Y	C19	
0	IO_VREF_L20N_Y	A19	
0	IO_L20P_Y	D18	
0	IO_LVDS_DLL_L21N	C18	
0	IO_VREF	E18	1
1	GCK2	D17	
1	IO	A3	
1	IO	D9	
1	IO	E8	
1	IO	E11	
1	IO_LVDS_DLL_L21P	E17	
1	IO_VREF_L22N_Y	C17	1
1	IO_L22P_Y	B17	
1	IO_L23N_Y	B16	
1	IO_VREF_L23P_Y	D16	
1	IO_L24N_Y	E16	
1	IO_L24P_Y	C16	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
1	IO_L25N_Y	A15	
1	IO_L25P_Y	C15	
1	IO_L26N_YY	D15	
1	IO_VREF_L26P_YY	E15	
1	IO_L27N_YY	C14	
1	IO_L27P_YY	D14	
1	IO_L28N_Y	A13	
1	IO_L28P_Y	E14	
1	IO_L29N_YY	C13	
1	IO_VREF_L29P_YY	D13	
1	IO_L30N_YY	C12	
1	IO_L30P_YY	E13	
1	IO_L31N_Y	A11	
1	IO_L31P_Y	D12	
1	IO_L32N_YY	B11	
1	IO_L32P_YY	C11	
1	IO_L33N_YY	B10	
1	IO_VREF_L33P_YY	D11	
1	IO_L34N_Y	C10	
1	IO_L34P_Y	A9	
1	IO_L35N_Y	C9	
1	IO_VREF_L35P_Y	D10	
1	IO_L36N_Y	A8	
1	IO_L36P_Y	B8	
1	IO_L37N_Y	E10	
1	IO_VREF_L37P_Y	C8	1
1	IO_L38N_YY	B7	
1	IO_VREF_L38P_YY	A6	
1	IO_L39N_YY	C7	
1	IO_L39P_YY	D8	
1	IO_L40N_Y	A5	
1	IO_L40P_Y	B5	
1	IO_L41N_YY	C6	
1	IO_VREF_L41P_YY	D7	
1	IO_L42N_YY	A4	
1	IO_L42P_YY	B4	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
1	IO_L43N_Y	C5	
1	IO_VREF_L43P_Y	E7	
1	IO_WRITE_L44N_YY	D6	
1	IO_CS_L44P_YY	A2	
2	IO	D3	
2	IO	F3	
2	IO	G1	
2	IO	J2	
2	IO_DOUT_BUSY_L45P_YY	D4	
2	IO_DIN_D0_L45N_YY	E4	
2	IO_L46P_Y	F5	
2	IO_VREF_L46N_Y	B3	
2	IO_L47P_Y	F4	
2	IO_L47N_Y	C1	
2	IO_VREF_L48P_Y	G5	
2	IO_L48N_Y	E3	
2	IO_L49P_Y	D2	
2	IO_L49N_Y	G4	
2	IO_L50P_Y	H5	
2	IO_L50N_Y	E2	
2	IO_VREF_L51P_YY	H4	
2	IO_L51N_YY	G3	
2	IO_L52P_Y	J5	
2	IO_VREF_L52N_Y	F1	1
2	IO_L53P_Y	J4	
2	IO_L53N_Y	H3	
2	IO_VREF_L54P_Y	K5	
2	IO_L54N_Y	H2	
2	IO_L55P_Y	J3	
2	IO_L55N_Y	K4	
2	IO_VREF_L56P_YY	L5	
2	IO_D1_L56N_YY	K3	
2	IO_D2_L57P_YY	L4	
2	IO_L57N_YY	K2	
2	IO_L58P_Y	M5	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
2	IO_L58N_Y	L3	
2	IO_L59P_Y	L1	
2	IO_L59N_Y	M4	
2	IO_VREF_L60P_Y	N5	
2	IO_L60N_Y	M2	
2	IO_L61P_Y	N4	
2	IO_L61N_Y	N3	
2	IO_L62P_Y	N2	
2	IO_L62N_Y	P5	
2	IO_VREF_L63P_YY	P4	
2	IO_D3_L63N_YY	P3	
2	IO_L64P_Y	P2	
2	IO_L64N_Y	R5	
2	IO_L65P_Y	R4	
2	IO_L65N_Y	R3	
2	IO_VREF_L66P_Y	R1	
2	IO_L66N_Y	T4	
2	IO_L67P_Y	T5	
2	IO_VREF_L67N_Y	T3	1
2	IO_L68P_YY	T2	
2	IO_L68N_YY	U3	
3	IO	AE3	
3	IO	AF3	
3	IO	AH3	
3	IO	AK3	
3	IO_VREF_L69P_Y	U1	1
3	IO_L69N_Y	U2	
3	IO_L70P_Y	V2	
3	IO_VREF_L70N_Y	V4	
3	IO_L71P_Y	V5	
3	IO_L71N_Y	V3	
3	IO_L72P_Y	W1	
3	IO_L72N_Y	W3	
3	IO_D4_L73P_YY	W4	
3	IO_VREF_L73N_YY	W5	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
3	IO_L74P_Y	Y3	
3	IO_L74N_Y	Y4	
3	IO_L75P_Y	AA1	
3	IO_L75N_Y	Y5	
3	IO_L76P_Y	AA3	
3	IO_VREF_L76N_Y	AA4	
3	IO_L77P_Y	AB3	
3	IO_L77N_Y	AA5	
3	IO_L78P_Y	AC1	
3	IO_L78N_Y	AB4	
3	IO_L79P_YY	AC3	
3	IO_D5_L79N_YY	AB5	
3	IO_D6_L80P_YY	AC4	
3	IO_VREF_L80N_YY	AD3	
3	IO_L81P_Y	AE1	
3	IO_L81N_Y	AC5	
3	IO_L82P_Y	AD4	
3	IO_VREF_L82N_Y	AF1	
3	IO_L83P_Y	AF2	
3	IO_L83N_Y	AD5	
3	IO_L84P_Y	AG2	
3	IO_VREF_L84N_Y	AE4	1
3	IO_L85P_YY	AH1	
3	IO_VREF_L85N_YY	AE5	
3	IO_L86P_Y	AF4	
3	IO_L86N_Y	AJ1	
3	IO_L87P_Y	AJ2	
3	IO_L87N_Y	AF5	
3	IO_L88P_Y	AG4	
3	IO_VREF_L88N_Y	AK2	
3	IO_L89P_Y	AJ3	
3	IO_L89N_Y	AG5	
3	IO_L90P_Y	AL1	
3	IO_VREF_L90N_Y	AH4	
3	IO_D7_L91P_YY	AJ4	
3	IO_INIT_L91N_YY	AH5	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
3	IO	U4	
4	GCK0	AL17	
4	IO	AJ8	
4	IO	AJ11	
4	IO	AK6	
4	IO	AK9	
4	IO_L92P_YY	AL4	
4	IO_L92N_YY	AJ6	
4	IO_L93P_Y	AK5	
4	IO_VREF_L93N_Y	AN3	
4	IO_L94P_YY	AL5	
4	IO_L94N_YY	AJ7	
4	IO_VREF_L95P_YY	AM4	
4	IO_L95N_YY	AM5	
4	IO_L96P_Y	AK7	
4	IO_L96N_Y	AL6	
4	IO_L97P_YY	AM6	
4	IO_L97N_YY	AN6	
4	IO_VREF_L98P_YY	AL7	
4	IO_L98N_YY	AJ9	
4	IO_L99P_Y	AN7	
4	IO_VREF_L99N_Y	AL8	1
4	IO_L100P_Y	AM8	
4	IO_L100N_Y	AJ10	
4	IO_VREF_L101P_Y	AL9	
4	IO_L101N_Y	AM9	
4	IO_L102P_Y	AK10	
4	IO_L102N_Y	AN9	
4	IO_VREF_L103P_YY	AL10	
4	IO_L103N_YY	AM10	
4	IO_L104P_YY	AL11	
4	IO_L104N_YY	AJ12	
4	IO_L105P_Y	AN11	
4	IO_L105N_Y	AK12	
4	IO_L106P_YY	AL12	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
4	IO_L106N_YY	AM12	
4	IO_VREF_L107P_YY	AK13	
4	IO_L107N_YY	AL13	
4	IO_L108P_Y	AM13	
4	IO_L108N_Y	AN13	
4	IO_L109P_YY	AJ14	
4	IO_L109N_YY	AK14	
4	IO_VREF_L110P_YY	AM14	
4	IO_L110N_YY	AN15	
4	IO_L111P_Y	AJ15	
4	IO_L111N_Y	AK15	
4	IO_L112P_Y	AL15	
4	IO_L112N_Y	AM16	
4	IO_VREF_L113P_Y	AL16	
4	IO_L113N_Y	AJ16	
4	IO_L114P_Y	AK16	
4	IO_VREF_L114N_Y	AN17	1
4	IO_LVDS_DLL_L115P	AM17	
5	GCK1	AJ17	
5	IO	AL25	
5	IO	AL28	
5	IO	AL30	
5	IO	AN28	
5	IO_LVDS_DLL_L115N	AM18	
5	IO_VREF	AL18	1
5	IO_L116P_Y	AK18	
5	IO_VREF_L116N_Y	AJ18	
5	IO_L117P_Y	AN19	
5	IO_L117N_Y	AL19	
5	IO_L118P_Y	AK19	
5	IO_L118N_Y	AM20	
5	IO_L119P_YY	AJ19	
5	IO_VREF_L119N_YY	AL20	
5	IO_L120P_YY	AN21	
5	IO_L120N_YY	AL21	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
5	IO_L121P_Y	AJ20	
5	IO_L121N_Y	AM22	
5	IO_L122P_YY	AK21	
5	IO_VREF_L122N_YY	AN23	
5	IO_L123P_YY	AJ21	
5	IO_L123N_YY	AM23	
5	IO_L124P_Y	AK22	
5	IO_L124N_Y	AM24	
5	IO_L125P_YY	AL23	
5	IO_L125N_YY	AJ22	
5	IO_L126P_YY	AK23	
5	IO_VREF_L126N_YY	AL24	
5	IO_L127P_Y	AN26	
5	IO_L127N_Y	AJ23	
5	IO_L128P_Y	AK24	
5	IO_VREF_L128N_Y	AM26	
5	IO_L129P_Y	AM27	
5	IO_L129N_Y	AJ24	
5	IO_L130P_Y	AL26	
5	IO_VREF_L130N_Y	AK25	1
5	IO_L131P_YY	AN29	
5	IO_VREF_L131N_YY	AJ25	
5	IO_L132P_YY	AK26	
5	IO_L132N_YY	AM29	
5	IO_L133P_Y	AM30	
5	IO_L133N_Y	AJ26	
5	IO_L134P_YY	AK27	
5	IO_VREF_L134N_YY	AL29	
5	IO_L135P_YY	AN31	
5	IO_L135N_YY	AJ27	
5	IO_L136P_Y	AM31	
5	IO_VREF_L136N_Y	AK28	
6	IO	AE33	
6	IO	AF31	
6	IO	AJ32	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
6	IO	AL33	
6	IO_L137N_YY	AH29	
6	IO_L137P_YY	AJ30	
6	IO_L138N_Y	AK31	
6	IO_VREF_L138P_Y	AH30	
6	IO_L139N_Y	AG29	
6	IO_L139P_Y	AJ31	
6	IO_VREF_L140N_Y	AK32	
6	IO_L140P_Y	AG30	
6	IO_L141N_Y	AH31	
6	IO_L141P_Y	AF29	
6	IO_L142N_Y	AH32	
6	IO_L142P_Y	AF30	
6	IO_VREF_L143N_YY	AE29	
6	IO_L143P_YY	AH33	
6	IO_L144N_Y	AG33	
6	IO_VREF_L144P_Y	AE30	1
6	IO_L145N_Y	AD29	
6	IO_L145P_Y	AF32	
6	IO_VREF_L146N_Y	AE31	
6	IO_L146P_Y	AD30	
6	IO_L147N_Y	AE32	
6	IO_L147P_Y	AC29	
6	IO_VREF_L148N_YY	AD31	
6	IO_L148P_YY	AC30	
6	IO_L149N_YY	AB29	
6	IO_L149P_YY	AC31	
6	IO_L150N_Y	AC33	
6	IO_L150P_Y	AB30	
6	IO_L151N_Y	AB31	
6	IO_L151P_Y	AA29	
6	IO_VREF_L152N_Y	AA30	
6	IO_L152P_Y	AA31	
6	IO_L153N_Y	AA32	
6	IO_L153P_Y	Y29	
6	IO_L154N_Y	AA33	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
6	IO_L154P_Y	Y30	
6	IO_VREF_L155N_YY	Y32	
6	IO_L155P_YY	W29	
6	IO_L156N_Y	W30	
6	IO_L156P_Y	W31	
6	IO_L157N_Y	W33	
6	IO_L157P_Y	V30	
6	IO_VREF_L158N_Y	V29	
6	IO_L158P_Y	V31	
6	IO_L159N_Y	V32	
6	IO_VREF_L159P_Y	U33	1
6	IO	U29	
7	IO	E30	
7	IO	F29	
7	IO	F33	
7	IO	G30	
7	IO	K30	
7	IO_L160N_YY	U31	
7	IO_L160P_YY	U32	
7	IO_VREF_L161N_Y	T32	1
7	IO_L161P_Y	T30	
7	IO_L162N_Y	T29	
7	IO_VREF_L162P_Y	T31	
7	IO_L163N_Y	R33	
7	IO_L163P_Y	R31	
7	IO_L164N_Y	R30	
7	IO_L164P_Y	R29	
7	IO_L165N_YY	P32	
7	IO_VREF_L165P_YY	P31	
7	IO_L166N_Y	P30	
7	IO_L166P_Y	P29	
7	IO_L167N_Y	M32	
7	IO_L167P_Y	N31	
7	IO_L168N_Y	N30	
7	IO_VREF_L168P_Y	L33	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
7	IO_L169N_Y	M31	
7	IO_L169P_Y	L32	
7	IO_L170N_Y	M30	
7	IO_L170P_Y	L31	
7	IO_L171N_YY	M29	
7	IO_L171P_YY	J33	
7	IO_L172N_YY	L30	
7	IO_VREF_L172P_YY	K31	
7	IO_L173N_Y	L29	
7	IO_L173P_Y	H33	
7	IO_L174N_Y	J31	
7	IO_VREF_L174P_Y	H32	
7	IO_L175N_Y	K29	
7	IO_L175P_Y	H31	
7	IO_L176N_Y	J30	
7	IO_VREF_L176P_Y	G32	1
7	IO_L177N_YY	J29	
7	IO_VREF_L177P_YY	G31	
7	IO_L178N_Y	E33	
7	IO_L178P_Y	E32	
7	IO_L179N_Y	H29	
7	IO_L179P_Y	F31	
7	IO_L180N_Y	D32	
7	IO_VREF_L180P_Y	E31	
7	IO_L181N_Y	G29	
7	IO_L181P_Y	C33	
7	IO_L182N_Y	F30	
7	IO_VREF_L182P_Y	D31	
2	CCLK	C4	
3	DONE	AJ5	
NA	DXN	AK29	
NA	DXP	AJ28	
NA	M0	AJ29	
NA	M1	AK30	
NA	M2	AN32	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
NA	PROGRAM	AM1	
NA	TCK	E29	
NA	TDI	D5	
2	TDO	E6	
NA	TMS	B33	
NA	NC	C31	
NA	NC	AC2	
NA	NC	AK4	
NA	NC	AL3	
NA	VCCINT	A21	
NA	VCCINT	B12	
NA	VCCINT	B14	
NA	VCCINT	B18	
NA	VCCINT	B28	
NA	VCCINT	C22	
NA	VCCINT	C24	
NA	VCCINT	E9	
NA	VCCINT	E12	
NA	VCCINT	F2	
NA	VCCINT	H30	
NA	VCCINT	J1	
NA	VCCINT	K32	
NA	VCCINT	M3	
NA	VCCINT	N1	
NA	VCCINT	N29	
NA	VCCINT	N33	
NA	VCCINT	U5	
NA	VCCINT	U30	
NA	VCCINT	Y2	
NA	VCCINT	Y31	
NA	VCCINT	AB2	
NA	VCCINT	AB32	
NA	VCCINT	AD2	
NA	VCCINT	AD32	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
NA	VCCINT	AG3	
NA	VCCINT	AG31	
NA	VCCINT	AJ13	
NA	VCCINT	AK8	
NA	VCCINT	AK11	
NA	VCCINT	AK17	
NA	VCCINT	AK20	
NA	VCCINT	AL14	
NA	VCCINT	AL22	
NA	VCCINT	AL27	
NA	VCCINT	AN25	
0	VCCO	A22	
0	VCCO	A26	
0	VCCO	A30	
0	VCCO	B19	
0	VCCO	B32	
1	VCCO	A10	
1	VCCO	A16	
1	VCCO	B13	
1	VCCO	C3	
1	VCCO	E5	
2	VCCO	B2	
2	VCCO	D1	
2	VCCO	H1	
2	VCCO	M1	
2	VCCO	R2	
3	VCCO	V1	
3	VCCO	AA2	
3	VCCO	AD1	
3	VCCO	AK1	
3	VCCO	AL2	
4	VCCO	AN4	
4	VCCO	AN8	
4	VCCO	AN12	
4	VCCO	AM2	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
4	VCCO	AM15	
5	VCCO	AL31	
5	VCCO	AM21	
5	VCCO	AN18	
5	VCCO	AN24	
5	VCCO	AN30	
6	VCCO	W32	
6	VCCO	AB33	
6	VCCO	AF33	
6	VCCO	AK33	
6	VCCO	AM32	
7	VCCO	C32	
7	VCCO	D33	
7	VCCO	K33	
7	VCCO	N32	
7	VCCO	T33	
NA	GND	A1	
NA	GND	A7	
NA	GND	A12	
NA	GND	A14	
NA	GND	A18	
NA	GND	A20	
NA	GND	A24	
NA	GND	A29	
NA	GND	A32	
NA	GND	A33	
NA	GND	B1	
NA	GND	B6	
NA	GND	B9	
NA	GND	B15	
NA	GND	B23	
NA	GND	B27	
NA	GND	B31	
NA	GND	C2	
NA	GND	E1	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
NA	GND	F32	
NA	GND	G2	
NA	GND	G33	
NA	GND	J32	
NA	GND	K1	
NA	GND	L2	
NA	GND	M33	
NA	GND	P1	
NA	GND	P33	
NA	GND	R32	
NA	GND	T1	
NA	GND	V33	
NA	GND	W2	
NA	GND	Y1	
NA	GND	Y33	
NA	GND	AB1	
NA	GND	AC32	
NA	GND	AD33	
NA	GND	AE2	
NA	GND	AG1	
NA	GND	AG32	
NA	GND	AH2	
NA	GND	AJ33	
NA	GND	AL32	
NA	GND	AM3	
NA	GND	AM7	
NA	GND	AM11	
NA	GND	AM19	
NA	GND	AM25	
NA	GND	AM28	
NA	GND	AM33	
NA	GND	AN1	
NA	GND	AN2	
NA	GND	AN5	
NA	GND	AN10	
NA	GND	AN14	

Table 4: **BG560/CG560 — XQV1000E, XQV2000E**

Bank	Pin Description	Pin#	See Note
NA	GND	AN16	
NA	GND	AN20	
NA	GND	AN22	
NA	GND	AN27	
NA	GND	AN33	

Notes:
1. V_{REF} or I/O option only in the XQV2000E; otherwise, I/O option only.

BG560 and CG560 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. A √ in the AO column indicates that the pin pair can be used as an asynchronous output for all devices provided in this package. Pairs with a note number in the AO column are device dependent. They can have asynchronous outputs if the pin pair are in the same CLB row and column in the device. Numbers in this column refer to footnotes that indicate which devices have pin pairs than can be asynchronous outputs. The Other Functions column indicates alternative function(s) not available when the pair is used as a differential pair or differential clock.

Table 5: **BG560/CG560 Differential Pin Pair Summary XQV1000E, XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
Global Differential Clock					
0	4	AL17	AM17	NA	IO_DLL_L15P
1	5	AJ17	AM18	NA	IO_DLL_L15N
2	1	D17	E17	NA	IO_DLL_L21P
3	0	A17	C18	NA	IO_DLL_L21N
IO LVDS Total Outputs: 183, Asynchronous Outputs: 87					
0	0	D29	E28	NA	VREF
1	0	A31	D28	√	-
2	0	C29	E27	√	VREF
3	0	D27	B30	2	-
4	0	B29	E26	√	-
5	0	C27	D26	√	VREF
6	0	A28	E25	NA	VREF
7	0	C26	D25	√	-
8	0	B26	E24	√	VREF
9	0	D24	C25	2	-
10	0	A25	E23	√	VREF
11	0	B24	D23	√	-
12	0	C23	E22	NA	-
13	0	D22	A23	√	-
14	0	B22	E21	√	VREF
15	0	C21	D21	2	-
16	0	E20	B21	√	-
17	0	C20	D20	√	VREF
18	0	E19	B20	NA	-
19	0	C19	D19	√	-
20	0	D18	A19	√	VREF
21	1	E17	C18	NA	IO_LVDS_DLL
22	1	B17	C17	2	VREF
23	1	D16	B16	√	VREF
24	1	C16	E16	√	-
25	1	C15	A15	NA	-
26	1	E15	D15	√	VREF
27	1	D14	C14	√	-
28	1	E14	A13	2	-
29	1	D13	C13	√	VREF
30	1	E13	C12	√	-
31	1	D12	A11	NA	-
32	1	C11	B11	√	-
33	1	D11	B10	√	VREF
34	1	A9	C10	√	-
35	1	D10	C9	√	VREF
36	1	B8	A8	√	-
37	1	C8	E10	√	VREF

Table 5: **BG560/CG560 Differential Pin Pair Summary XQV1000E, XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
38	1	A6	B7	√	VREF
39	1	D8	C7	√	-
40	1	B5	A5	1	-
41	1	D7	C6	√	VREF
42	1	B4	A4	√	-
43	1	E7	C5	√	VREF
44	1	A2	D6	√	CS
45	2	D4	E4	√	DIN, D0
46	2	F5	B3	2	VREF
47	2	F4	C1	1	-
48	2	G5	E3	√	VREF
49	2	D2	G4	2	-
50	2	H5	E2	√	-
51	2	H4	G3	√	VREF
52	2	J5	F1	2	VREF
53	2	J4	H3	1	-
54	2	K5	H2	√	VREF
55	2	J3	K4	2	-
56	2	L5	K3	√	D1
57	2	L4	K2	√	D2
58	2	M5	L3	2	-
59	2	L1	M4	1	-
60	2	N5	M2	√	VREF
61	2	N4	N3	2	-
62	2	N2	P5	√	-
63	2	P4	P3	√	D3
64	2	P2	R5	2	-
65	2	R4	R3	1	-
66	2	R1	T4	√	VREF
67	2	T5	T3	2	VREF
68	2	T2	U3	√	-

Table 5: **BG560/CG560 Differential Pin Pair Summary XQV1000E, XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
69	3	U1	U2	2	VREF
70	3	V2	V4	√	VREF
71	3	V5	V3	1	-
72	3	W1	W3	2	-
73	3	W4	W5	√	VREF
74	3	Y3	Y4	√	-
75	3	AA1	Y5	2	-
76	3	AA3	AA4	√	VREF
77	3	AB3	AA5	1	-
78	3	AC1	AB4	2	-
79	3	AC3	AB5	√	D5
80	3	AC4	AD3	√	VREF
81	3	AE1	AC5	1	-
82	3	AD4	AF1	√	VREF
83	3	AF2	AD5	1	-
84	3	AG2	AE4	1	VREF
85	3	AH1	AE5	√	VREF
86	3	AF4	AJ1	√	-
87	3	AJ2	AF5	1	-
88	3	AG4	AK2	√	VREF
89	3	AJ3	AG5	1	-
90	3	AL1	AH4	1	VREF
91	3	AJ4	AH5	√	INIT
92	4	AL4	AJ6	√	-
93	4	AK5	AN3	NA	VREF
94	4	AL5	AJ7	√	-
95	4	AM4	AM5	√	VREF
96	4	AK7	AL6	2	-
97	4	AM6	AN6	√	-
98	4	AL7	AJ9	√	VREF
99	4	AN7	AL8	NA	VREF

Table 5: **BG560/CG560 Differential Pin Pair Summary XQV1000E, XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
100	4	AM8	AJ10	√	-
101	4	AL9	AM9	√	VREF
102	4	AK10	AN9	2	-
103	4	AL10	AM10	√	VREF
104	4	AL11	AJ12	√	-
105	4	AN11	AK12	NA	-
106	4	AL12	AM12	√	-
107	4	AK13	AL13	√	VREF
108	4	AM13	AN13	2	-
109	4	AJ14	AK14	√	-
110	4	AM14	AN15	√	VREF
111	4	AJ15	AK15	NA	-
112	4	AL15	AM16	√	-
113	4	AL16	AJ16	√	VREF
114	4	AK16	AN17	2	VREF
115	5	AM17	AM18	NA	IO_LVDS_DLL
116	5	AK18	AJ18	√	VREF
117	5	AN19	AL19	√	-
118	5	AK19	AM20	NA	-
119	5	AJ19	AL20	√	VREF
120	5	AN21	AL21	√	-
121	5	AJ20	AM22	2	-
122	5	AK21	AN23	√	VREF
123	5	AJ21	AM23	√	-
124	5	AK22	AM24	NA	-
125	5	AL23	AJ22	√	-
126	5	AK23	AL24	√	VREF
127	5	AN26	AJ23	1	-
128	5	AK24	AM26	√	VREF
129	5	AM27	AJ24	√	-
130	5	AL26	AK25	√	VREF

Table 5: **BG560/CG560 Differential Pin Pair Summary XQV1000E, XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
131	5	AN29	AJ25	√	VREF
132	5	AK26	AM29	√	-
133	5	AM30	AJ26	1	-
134	5	AK27	AL29	√	VREF
135	5	AN31	AJ27	√	-
136	5	AM31	AK28	√	VREF
137	6	AJ30	AH29	√	-
138	6	AH30	AK31	2	VREF
139	6	AJ31	AG29	1	-
140	6	AG30	AK32	√	VREF
141	6	AF29	AH31	2	-
142	6	AF30	AH32	√	-
143	6	AH33	AE29	√	VREF
144	6	AE30	AG33	2	VREF
145	6	AF32	AD29	1	-
146	6	AD30	AE31	√	VREF
147	6	AC29	AE32	2	-
148	6	AC30	AD31	√	VREF
149	6	AC31	AB29	√	-
150	6	AB30	AC33	2	-
151	6	AA29	AB31	1	-
152	6	AA31	AA30	√	VREF
153	6	Y29	AA32	2	-
154	6	Y30	AA33	√	-
155	6	W29	Y32	√	VREF
156	6	W31	W30	2	-
157	6	V30	W33	1	-
158	6	V31	V29	√	VREF
159	6	U33	V32	2	VREF
160	7	U32	U31	√	-
161	7	T30	T32	2	VREF

Table 5: **BG560/CG560 Differential Pin Pair Summary**
XQV1000E, XQV2000E

Pair	Bank	P Pin	N Pin	AO	Other Functions
162	7	T31	T29	√	VREF
163	7	R31	R33	1	-
164	7	R29	R30	2	-
165	7	P31	P32	√	VREF
166	7	P29	P30	√	-
167	7	N31	M32	2	-
168	7	L33	N30	√	VREF
169	7	L32	M31	1	-
170	7	L31	M30	2	-
171	7	J33	M29	√	-
172	7	K31	L30	√	VREF
173	7	H33	L29	1	-
174	7	H32	J31	√	VREF
175	7	H31	K29	1	-
176	7	G32	J30	1	VREF
177	7	G31	J29	√	VREF
178	7	E32	E33	√	-
179	7	F31	H29	1	-
180	7	E31	D32	√	VREF
181	7	C33	G29	1	-
182	7	D31	F30	1	VREF

Notes:

1. AO in the XQV1000E.
2. AO in the XQV2000E.

FG1156 Fine-Pitch Ball Grid Array Package

XQV2000E devices only are available in the FG1156 fine-pitch Ball Grid Array package. See Table 6 for pinout information. Immediately following Table 6, see Table 7 for Differential Pair information.

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
0	GCK3	E17
0	IO	B4
0	IO	B9
0	IO	B10
0	IO	D9
0	IO	D16
0	IO	E7
0	IO	E11
0	IO	E13
0	IO	E16
0	IO	F17
0	IO	J12
0	IO	J13
0	IO	J14
0	IO	K11
0	IO_L0N_Y	F7
0	IO_L0P_Y	H9
0	IO_L1N_Y	C5
0	IO_L1P_Y	J10
0	IO_VREF_L2N_Y	E6
0	IO_L2P_Y	D6
0	IO_L3N_Y	A4
0	IO_L3P_Y	G8
0	IO_L4N_YY	C6
0	IO_L4P_YY	J11
0	IO_VREF_L5N_YY	G9
0	IO_L5P_YY	F8
0	IO_L6N_YY	A5
0	IO_L6P_YY	H10
0	IO_L7N_Y	D7
0	IO_L7P_Y	B5

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
0	IO_L8N_Y	K12
0	IO_L8P_Y	E8
0	IO_L9N	B6
0	IO_L9P	F9
0	IO_L10N_YY	G10
0	IO_L10P_YY	C7
0	IO_VREF_L11N_YY	D8
0	IO_L11P_YY	B7
0	IO_L12N	H11
0	IO_L12P	C8[5]
0	IO_L13N_Y	E9
0	IO_L13P_Y	B8
0	IO_VREF_L14N_Y	K13
0	IO_L14P_Y	G11
0	IO_L15N	A8
0	IO_L15P	F10
0	IO_L16N_YY	C9
0	IO_L16P_YY	H12
0	IO_VREF_L17N_YY	D10
0	IO_L17P_YY	A9
0	IO_L18N_Y	F11
0	IO_L18P_Y	A10
0	IO_L19N_Y	K14
0	IO_L19P_Y	C10
0	IO_VREF_L20N_YY	H13
0	IO_L20P_YY	G12
0	IO_L21N_YY	A11
0	IO_L21P_YY	B11
0	IO_L22N_Y	E12
0	IO_L22P_Y	D11
0	IO_L23N_Y	G13
0	IO_L23P_Y	C12
0	IO_L24N_Y	K15
0	IO_L24P_Y	A12
0	IO_L25N_Y	B12

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
0	IO_L25P_Y	H14
0	IO_L26N_YY	D12
0	IO_L26P_YY	F13
0	IO_VREF_L27N_YY	A13
0	IO_L27P_YY	B13
0	IO_L28N_YY	J15
0	IO_L28P_YY	G14
0	IO_L29N_Y	C13
0	IO_L29P_Y	F14
0	IO_L30N_Y	H15
0	IO_L30P_Y	D13
0	IO_L31N	A14
0	IO_L31P	K16
0	IO_L32N_YY	E14
0	IO_L32P_YY	B14
0	IO_VREF_L33N_YY	G15
0	IO_L33P_YY	D14
0	IO_L34N	J16
0	IO_L34P	D15
0	IO_L35N_Y	F15
0	IO_L35P_Y	B15
0	IO_L36N_Y	A15
0	IO_L36P_Y	E15
0	IO_L37N	G16
0	IO_L37P	A16
0	IO_L38N_YY	F16
0	IO_L38P_YY	J17
0	IO_VREF_L39N_YY	C16
0	IO_L39P_YY	B16
0	IO_L40N_Y	H17
0	IO_L40P_Y	A17
0	IO_VREF_L41N_Y	G17
0	IO_L41P_Y	B17
0	IO_LVDS_DLL_L42N	C17

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
1	GCK2	D17
1	IO	A18
1	IO	B18
1	IO	B24
1	IO	B25
1	IO	E22
1	IO	E23
1	IO	D18
1	IO	D19
1	IO	D25
1	IO	D26
1	IO	D28
1	IO	D29
1	IO	G23
1	IO	J23
1	IO_LVDS_DLL_L42P	J18
1	IO_L43N_Y	G18
1	IO_VREF_L43P_Y	C18
1	IO_L44N_Y	H18
1	IO_L44P_Y	F18
1	IO_L45N_YY	B19
1	IO_VREF_L45P_YY	A19
1	IO_L46N_YY	K19
1	IO_L46P_YY	C19
1	IO_L47N	F19
1	IO_L47P	E19
1	IO_L48N_Y	G19
1	IO_L48P_Y	J19
1	IO_L49N_Y	A20
1	IO_L49P_Y	G20
1	IO_L50N	B20
1	IO_L50P	F20
1	IO_L51N_YY	D20
1	IO_VREF_L51P_YY	E20
1	IO_L52N_YY	H20

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
1	IO_L52P_YY	A21
1	IO_L53N	E21
1	IO_L53P	J20
1	IO_L54N_Y	D21
1	IO_L54P_Y	K20
1	IO_L55N_Y	B21
1	IO_L55P_Y	H21
1	IO_L56N_YY	G21
1	IO_L56P_YY	F21
1	IO_L57N_YY	A22
1	IO_VREF_L57P_YY	B22
1	IO_L58N_YY	J21
1	IO_L58P_YY	C22
1	IO_L59N_Y	D22
1	IO_L59P_Y	G22
1	IO_L60N_Y	K21
1	IO_L60P_Y	A23
1	IO_L61N_Y	F22
1	IO_L61P_Y	B23
1	IO_L62N_Y	C23
1	IO_L62P_Y	H22
1	IO_L63N_YY	D23
1	IO_L63P_YY	K22
1	IO_L64N_YY	A24
1	IO_VREF_L64P_YY	J22
1	IO_L65N_Y	H23
1	IO_L65P_Y	D24
1	IO_L66N_Y	A25
1	IO_L66P_Y	E24
1	IO_L67N_YY	A26
1	IO_VREF_L67P_YY	C25
1	IO_L68N_YY	F24
1	IO_L68P_YY	B26
1	IO_L69N	K23
1	IO_L69P	F25
1	IO_L70N_Y	C26
1	IO_VREF_L70P_Y	H24
1	IO_L71N_Y	G24
1	IO_L71P_Y	A27
1	IO_L72N	B27
1	IO_L72P	G25
1	IO_L73N_YY	E26
1	IO_VREF_L73P_YY	C27
1	IO_L74N_YY	J24
1	IO_L74P_YY	B28
1	IO_L75N	K24
1	IO_L75P	H25
1	IO_L76N_Y	D27
1	IO_L76P_Y	F26
1	IO_L77N_Y	G26
1	IO_L77P_Y	C28
1	IO_L78N_YY	E27
1	IO_L78P_YY	J25
1	IO_L79N_YY	A30
1	IO_VREF_L79P_YY	H26
1	IO_L80N_YY	G27
1	IO_L80P_YY	B29
1	IO_L81N_Y	F27
1	IO_L81P_Y	C29
1	IO_L82N_Y	E28
1	IO_VREF_L82P_Y	F28
1	IO_L83N_Y	L25
1	IO_L83P_Y	B30
1	IO_L84N	B31
1	IO_L84P	E29
1	IO_WRITE_L85N_YY	A31
1	IO_CS_L85P_YY	D30
2	IO	F31
2	IO	J32

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
2	IO	K27
2	IO	K31
2	IO	L28
2	IO	L30
2	IO	M32
2	IO	N26
2	IO	N28
2	IO	P25
2	IO	U26
2	IO	U30
2	IO	U32
2	IO	U34
2	IO_D2	M30
2	IO_DOUT_BUSY_L86P_YY	D32
2	IO_DIN_D0_L86N_YY	J27
2	IO_L87P_Y	E31
2	IO_L87N_Y	F30
2	IO_L88P_Y	G29
2	IO_L88N_Y	F32
2	IO_VREF_L89P_Y	E32
2	IO_L89N_Y	G30
2	IO_L90P	M25
2	IO_L90N	G31
2	IO_L91P_Y	L26
2	IO_L91N_Y	D33
2	IO_VREF_L92P_Y	D34
2	IO_L92N_Y	H29
2	IO_L93P_YY	J28
2	IO_L93N_YY	E33
2	IO_L94P_YY	H28
2	IO_L94N_YY	H30
2	IO_L95P_Y	H32
2	IO_L95N_Y	K28
2	IO_L96P_Y	L27
2	IO_L96N_Y	F33

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
2	IO_L97P_Y	M26
2	IO_L97N_Y	E34
2	IO_VREF_L98P_YY	H31
2	IO_L98N_YY	G32
2	IO_L99P_YY	N25
2	IO_L99N_YY	J31
2	IO_L100P_YY	J30
2	IO_L100N_YY	G33
2	IO_VREF_L101P_Y	H34
2	IO_L101N_Y	J29
2	IO_L102P	M27
2	IO_L102N	H33
2	IO_L103P_Y	K29
2	IO_L103N_Y	J34
2	IO_VREF_L104P_YY	L29
2	IO_L104N_YY	J33
2	IO_L105P_YY	M28
2	IO_L105N_YY	K34
2	IO_L106P_Y	N27
2	IO_L106N_Y	L34
2	IO_VREF_L107P_YY	K33
2	IO_D1_L107N_YY	P26
2	IO_L108P_Y	R25
2	IO_L108N_Y	M34
2	IO_L109P_Y	L31
2	IO_L109N_Y	L33
2	IO_L110P_Y	P27
2	IO_L110N_Y	M33
2	IO_L111P	M31
2	IO_L111N	R26
2	IO_L112P_Y	N30
2	IO_L112N_Y	P28
2	IO_VREF_L113P_Y	N29
2	IO_L113N_Y	N33
2	IO_L114P_YY	T25

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
2	IO_L114N_YY	N34
2	IO_L115P_YY	P34
2	IO_L115N_YY	R27
2	IO_L116P_Y	P29
2	IO_L116N_Y	P31
2	IO_L117P_Y	P33
2	IO_L117N_Y	T26
2	IO_L118P_Y	R34
2	IO_L118N_Y	R28
2	IO_VREF_L119P_YY	N31
2	IO_D3_L119N_YY	N32
2	IO_L120P_YY	P30
2	IO_L120N_YY	R33
2	IO_L121P_YY	R29
2	IO_L121N_YY	T34
2	IO_L122P_Y	R30
2	IO_L122N_Y	T30
2	IO_L123P	T28
2	IO_L123N	R31
2	IO_L124P_Y	T29
2	IO_L124N_Y	U27
2	IO_VREF_L125P_YY	T31
2	IO_L125N_YY	T33
2	IO_L126P_YY	U28
2	IO_L126N_YY	T32
2	IO_VREF_L127P_Y	U29
2	IO_L127N_Y	U33
2	IO_L128P_YY	V33
2	IO_L128N_YY	U31
3	IO	V27
3	IO	V31
3	IO	V32
3	IO	W33
3	IO	AB25

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
3	IO	AB26
3	IO	AB31
3	IO	AC31
3	IO	AF34
3	IO	AG31
3	IO	AG33
3	IO	AG34
3	IO	AH29
3	IO	AJ30
3	IO_L129P_Y	V26
3	IO_VREF_L129N_Y	V30
3	IO_L130P_YY	W34
3	IO_L130N_YY	V28
3	IO_L131P_YY	W32
3	IO_VREF_L131N_YY	W30
3	IO_L132P_Y	V29
3	IO_L132N_Y	Y34
3	IO_L133P	W29
3	IO_L133N	Y33
3	IO_L134P_Y	W26
3	IO_L134N_Y	W28
3	IO_L135P_YY	Y31
3	IO_L135N_YY	Y30
3	IO_L136P_YY	AA34
3	IO_L136N_YY	W31
3	IO_D4_L137P_YY	AA33
3	IO_VREF_L137N_YY	Y29
3	IO_L138P_Y	W25
3	IO_L138N_Y	AB34
3	IO_L139P_Y	Y28
3	IO_L139N_Y	AB33
3	IO_L140P_Y	AA30
3	IO_L140N_Y	Y26
3	IO_L141P_YY	Y27
3	IO_L141N_YY	AA31

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
3	IO_L142P_YY	AA27
3	IO_L142N_YY	AA29
3	IO_L143P_Y	AB32
3	IO_VREF_L143N_Y	AB29
3	IO_L144P_Y	AA28
3	IO_L144N_Y	AC34
3	IO_L145P	Y25
3	IO_L145N	AD34
3	IO_L146P_Y	AB30
3	IO_L146N_Y	AC33
3	IO_L147P_Y	AA26
3	IO_L147N_Y	AC32
3	IO_L148P_Y	AD33
3	IO_L148N_Y	AB28
3	IO_L149P_YY	AE34
3	IO_D5_L149N_YY	AB27
3	IO_D6_L150P_YY	AE33
3	IO_VREF_L150N_YY	AC30
3	IO_L151P_Y	AA25
3	IO_L151N_Y	AE32
3	IO_L152P_YY	AE31
3	IO_L152N_YY	AD29
3	IO_L153P_YY	AD31
3	IO_VREF_L153N_YY	AF33
3	IO_L154P_Y	AC28
3	IO_L154N_Y	AF31
3	IO_L155P_Y	AC27
3	IO_L155N_Y	AF32
3	IO_L156P_Y	AE29
3	IO_VREF_L156N_Y	AD28
3	IO_L157P_YY	AD30
3	IO_L157N_YY	AG32
3	IO_L158P_YY	AC26
3	IO_L158N_YY	AH33
3	IO_L159P_YY	AD26

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
3	IO_VREF_L159N_YY	AF30
3	IO_L160P_Y	AC25
3	IO_L160N_Y	AH32
3	IO_L161P_Y	AE28
3	IO_L161N_Y	AL34
3	IO_L162P_Y	AG30
3	IO_L162N_Y	AD27
3	IO_L163P_YY	AF29
3	IO_L163N_YY	AK34
3	IO_L164P_YY	AD25
3	IO_L164N_YY	AE27
3	IO_L165P_Y	AJ33
3	IO_VREF_L165N_Y	AH31
3	IO_L166P_Y	AE26
3	IO_L166N_Y	AL33
3	IO_L167P	AF28
3	IO_L167N	AL32
3	IO_L168P_Y	AJ31
3	IO_VREF_L168N_Y	AF27
3	IO_L169P_Y	AG29
3	IO_L169N_Y	AJ32
3	IO_L170P_Y	AK33
3	IO_L170N_Y	AH30
3	IO_D7_L171P_YY	AK32
3	IO_INIT_L171N_YY	AK31
3	IO	V34
4	GCK0	AH18
4	IO	AE21
4	IO	AG18
4	IO	AG23
4	IO	AH24
4	IO	AH25
4	IO	AJ28
4	IO	AK18

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
4	IO	AK19
4	IO	AL25
4	IO	AL27
4	IO	AL30
4	IO	AN18
4	IO	AN22
4	IO	AN24
4	IO_L172P_YY	AP31
4	IO_L172N_YY	AK29
4	IO_L173P_Y	AP30
4	IO_L173N_Y	AN31
4	IO_L174P_Y	AH27
4	IO_L174N_Y	AN30
4	IO_VREF_L175P_Y	AM30
4	IO_L175N_Y	AK28
4	IO_L176P_Y	AG26
4	IO_L176N_Y	AN29
4	IO_L177P_YY	AF25
4	IO_L177N_YY	AM29
4	IO_VREF_L178P_YY	AL29
4	IO_L178N_YY	AL28
4	IO_L179P_YY	AE24
4	IO_L179N_YY	AN28
4	IO_L180P_Y	AJ27
4	IO_L180N_Y	AH26
4	IO_L181P_Y	AG25
4	IO_L181N_Y	AK27
4	IO_L182P	AM28
4	IO_L182N	AF24
4	IO_L183P_YY	AJ26
4	IO_L183N_YY	AP27
4	IO_VREF_L184P_YY	AK26
4	IO_L184N_YY	AN27
4	IO_L185P	AE23
4	IO_L185N	AM27

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
4	IO_L186P_Y	AL26
4	IO_L186N_Y	AP26
4	IO_VREF_L187P_Y	AN26
4	IO_L187N_Y	AJ25
4	IO_L188P	AG24
4	IO_L188N	AP25
4	IO_L189P_YY	AF23
4	IO_L189N_YY	AM26
4	IO_VREF_L190P_YY	AJ24
4	IO_L190N_YY	AN25
4	IO_L191P_Y	AE22
4	IO_L191N_Y	AM25
4	IO_L192P_Y	AK24
4	IO_L192N_Y	AH23
4	IO_VREF_L193P_YY	AF22
4	IO_L193N_YY	AP24
4	IO_L194P_YY	AL24
4	IO_L194N_YY	AK23
4	IO_L195P_Y	AG22
4	IO_L195N_Y	AN23
4	IO_L196P_Y	AP23
4	IO_L196N_Y	AM23
4	IO_L197P_Y	AH22
4	IO_L197N_Y	AP22
4	IO_L198P_Y	AL23
4	IO_L198N_Y	AF21
4	IO_L199P_YY	AL22
4	IO_L199N_YY	AJ22
4	IO_VREF_L200P_YY	AK22
4	IO_L200N_YY	AM22
4	IO_L201P_YY	AG21
4	IO_L201N_YY	AJ21
4	IO_L202P_Y	AP21
4	IO_L202N_Y	AE20
4	IO_L203P_Y	AH21

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
4	IO_L203N_Y	AL21
4	IO_L204P	AN21
4	IO_L204N	AF20
4	IO_L205P_YY	AK21
4	IO_L205N_YY	AP20
4	IO_VREF_L206P_YY	AE19
4	IO_L206N_YY	AN20
4	IO_L207P_Y	AG20
4	IO_L207N_Y	AL20
4	IO_L208P_Y	AH20
4	IO_L208N_Y	AK20
4	IO_L209P_Y	AN19
4	IO_L209N_Y	AJ20
4	IO_L210P	AF19
4	IO_L210N	AP19
4	IO_L211P_YY	AM19
4	IO_L211N_YY	AH19
4	IO_VREF_L212P_YY	AJ19
4	IO_L212N_YY	AP18
4	IO_L213P_Y	AF18
4	IO_L213N_Y	AP17
4	IO_VREF_L214P_Y	AJ18
4	IO_L214N_Y	AL18
4	IO_LVDS_DLL_L215P	AM18
5	GCK1	AL19
5	IO	AF17
5	IO	AG12
5	IO	AH12
5	IO	AJ10
5	IO	AJ11
5	IO	AK7
5	IO	AK13
5	IO	AL13
5	IO	AM4

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
5	IO	AN9
5	IO	AN10
5	IO	AN16
5	IO	AN17
5	IO_LVDS_DLL_L215N	AL17
5	IO_L216P_Y	AH17
5	IO_VREF_L216N_Y	AM17
5	IO_L217P_Y	AJ17
5	IO_L217N_Y	AG17
5	IO_L218P_YY	AP16
5	IO_VREF_L218N_YY	AL16
5	IO_L219P_YY	AJ16
5	IO_L219N_YY	AM16
5	IO_L220P	AK16
5	IO_L220N	AP15
5	IO_L221P_Y	AL15
5	IO_L221N_Y	AH16
5	IO_L222P_Y	AN15
5	IO_L222N_Y	AF16
5	IO_L223P_Y	AP14
5	IO_L223N_Y	AE16
5	IO_L224P_YY	AK15
5	IO_VREF_L224N_YY	AJ15
5	IO_L225P_YY	AH15
5	IO_L225N_YY	AN14
5	IO_L226P	AK14
5	IO_L226N	AG15
5	IO_L227P_Y	AM13
5	IO_L227N_Y	AF15
5	IO_L228P_Y	AG14
5	IO_L228N_Y	AP13
5	IO_L229P_YY	AE14
5	IO_L229N_YY	AE15
5	IO_L230P_YY	AN13
5	IO_VREF_L230N_YY	AG13

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
5	IO_L231P_YY	AH14
5	IO_L231N_YY	AP12
5	IO_L232P_Y	AJ14
5	IO_L232N_Y	AL14
5	IO_L233P_Y	AF13
5	IO_L233N_Y	AN12
5	IO_L234P_Y	AF14
5	IO_L234N_Y	AP11
5	IO_L235P_Y	AN11
5	IO_L235N_Y	AH13
5	IO_L236P_YY	AM12
5	IO_L236N_YY	AL12
5	IO_L237P_YY	AJ13
5	IO_VREF_L237N_YY	AP10
5	IO_L238P_Y	AK12
5	IO_L238N_Y	AM10
5	IO_L239P_Y	AP9
5	IO_L239N_Y	AK11
5	IO_L240P_YY	AL11
5	IO_VREF_L240N_YY	AL10
5	IO_L241P_YY	AE13
5	IO_L241N_YY	AM9
5	IO_L242P	AF12
5	IO_L242N	AP8
5	IO_L243P_Y	AL9
5	IO_VREF_L243N_Y	AH11
5	IO_L244P_Y	AF11
5	IO_L244N_Y	AN8
5	IO_L245P_Y	AM8
5	IO_L245N_Y	AG11
5	IO_L246P_YY	AL8
5	IO_VREF_L246N_YY	AK9
5	IO_L247P_YY	AH10
5	IO_L247N_YY	AN7
5	IO_L248P	AE12

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
5	IO_L248N	AJ9
5	IO_L249P_Y	AM7
5	IO_L249N_Y	AL7
5	IO_L250P_Y	AG10
5	IO_L250N_Y	AN6
5	IO_L251P_YY	AK8
5	IO_L251N_YY	AH9
5	IO_L252P_YY	AP5
5	IO_VREF_L252N_YY	AJ8
5	IO_L253P_YY	AE11
5	IO_L253N_YY	AN5
5	IO_L254P_Y	AF10
5	IO_L254N_Y	AM6
5	IO_L255P_Y	AL6
5	IO_VREF_L255N_Y	AG9
5	IO_L256P_Y	AH8
5	IO_L256N_Y	AP4
5	IO_L257P_Y	AN4
5	IO_L257N_Y	AJ7
5	IO_L258P_YY	AM5
5	IO_L258N_YY	AK6
6	IO	T1
6	IO	V2
6	IO	V3
6	IO	V5
6	IO	V8
6	IO	AA10
6	IO	AB5
6	IO	AB7
6	IO	AB9
6	IO	AD7
6	IO	AD8
6	IO	AE2
6	IO	AE4

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
6	IO	AJ4
6	IO	AH5
6	IO_L259N_YY	AH6
6	IO_L259P_YY	AF8
6	IO_L260N_Y	AE9
6	IO_L260P_Y	AK3
6	IO_L261N_Y	AD10
6	IO_L261P_Y	AL2
6	IO_VREF_L262N_Y	AL1
6	IO_L262P_Y	AH4
6	IO_L263N	AG6
6	IO_L263P	AK1
6	IO_L264N_Y	AF7
6	IO_L264P_Y	AK2
6	IO_VREF_L265N_Y	AJ3
6	IO_L265P_Y	AG5
6	IO_L266N_YY	AD9
6	IO_L266P_YY	AJ2
6	IO_L267N_YY	AC10
6	IO_L267P_YY	AH2
6	IO_L268N_Y	AH3
6	IO_L268P_Y	AF5
6	IO_L269N_Y	AE8
6	IO_L269P_Y	AG3
6	IO_L270N_Y	AE7
6	IO_L270P_Y	AG2
6	IO_VREF_L271N_YY	AF6
6	IO_L271P_YY	AG1
6	IO_L272N_YY	AC9
6	IO_L272P_YY	AG4
6	IO_L273N_YY	AE6
6	IO_L273P_YY	AF3
6	IO_VREF_L274N_Y	AF1
6	IO_L274P_Y	AF4
6	IO_L275N	AB10

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
6	IO_L275P	AF2
6	IO_L276N_Y	AC8
6	IO_L276P_Y	AE1
6	IO_VREF_L277N_YY	AD5
6	IO_L277P_YY	AE3
6	IO_L278N_YY	AC7
6	IO_L278P_YY	AD1
6	IO_L279N_Y	AD6
6	IO_L279P_Y	AD2
6	IO_VREF_L280N_YY	AB8
6	IO_L280P_YY	AC1
6	IO_L281N_YY	AC5
6	IO_L281P_YY	AC2
6	IO_L282N_Y	AA9
6	IO_L282P_Y	AC3
6	IO_L283N_Y	AC4
6	IO_L283P_Y	AD4
6	IO_L284N_Y	AA8
6	IO_L284P_Y	AB6
6	IO_L285N	AB1
6	IO_L285P	Y10
6	IO_L286N_Y	AB2
6	IO_L286P_Y	AA7
6	IO_VREF_L287N_Y	AA4
6	IO_L287P_Y	AA1
6	IO_L288N_YY	Y9
6	IO_L288P_YY	AB4
6	IO_L289N_YY	AA2
6	IO_L289P_YY	Y8
6	IO_L290N_Y	AA6
6	IO_L290P_Y	AA5
6	IO_L291N_Y	AB3
6	IO_L291P_Y	Y7
6	IO_L292N_Y	Y1
6	IO_L292P_Y	W10

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
6	IO_VREF_L293N_YY	Y5
6	IO_L293P_YY	Y2
6	IO_L294N_YY	W9
6	IO_L294P_YY	W2
6	IO_L295N_YY	W7
6	IO_L295P_YY	Y4
6	IO_L296N_Y	W1
6	IO_L296P_Y	Y6
6	IO_L297N_Y	W6
6	IO_L297P_Y	W3
6	IO_L298N_Y	V9
6	IO_L298P_Y	W4
6	IO_VREF_L299N_YY	W5
6	IO_L299P_YY	V1
6	IO_L300N_YY	V7
6	IO_L300P_YY	U2
6	IO_VREF_L301N_Y	V6
6	IO_L301P_Y	U1
7	IO	F5
7	IO	G6
7	IO	H1
7	IO	H7
7	IO	K2
7	IO	K4
7	IO	L6
7	IO	M5
7	IO	M10
7	IO	N5
7	IO	N10
7	IO	R7
7	IO	T2
7	IO	T7
7	IO	U8
7	IO	V4[3]

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
7	IO_L302N_YY	U9
7	IO_L302P_YY	U4
7	IO_L303N_Y	U7
7	IO_VREF_L303P_Y	U5
7	IO_L304N_YY	U3
7	IO_L304P_YY	U6
7	IO_L305N_YY	T3
7	IO_VREF_L305P_YY	T6
7	IO_L306N_Y	T9
7	IO_L306P_Y	T4
7	IO_L307N_Y	T5
7	IO_L307P_Y	R1
7	IO_L308N_Y	R6
7	IO_L308P_Y	T10
7	IO_L309N_YY	R2
7	IO_L309P_YY	R5
7	IO_L310N_YY	P1
7	IO_VREF_L310P_YY	P5
7	IO_L311N_Y	R8
7	IO_L311P_Y	P2
7	IO_L312N_Y	R9
7	IO_L312P_Y	N1
7	IO_L313N_Y	P4
7	IO_L313P_Y	R10
7	IO_L314N_YY	P8
7	IO_L314P_YY	N2
7	IO_L315N_YY	P6
7	IO_L315P_YY	P7
7	IO_L316N_Y	M1
7	IO_VREF_L316P_Y	N4
7	IO_L317N_Y	N6
7	IO_L317P_Y	N3
7	IO_L318N	P9
7	IO_L318P	M2
7	IO_L319N_Y	N7

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
7	IO_L319P_Y	M3
7	IO_L320N_Y	P10
7	IO_L320P_Y	M4
7	IO_L321N_Y	L1
7	IO_L321P_Y	N8
7	IO_L322N_YY	L2
7	IO_L322P_YY	N9
7	IO_L323N_YY	M7
7	IO_VREF_L323P_YY	K1
7	IO_L324N_Y	M8
7	IO_L324P_Y	L4
7	IO_L325N_YY	J1
7	IO_L325P_YY	L5
7	IO_L326N_YY	J2
7	IO_VREF_L326P_YY	K3
7	IO_L327N_Y	L7
7	IO_L327P_Y	J3
7	IO_L328N_Y	M9
7	IO_L328P_Y	H2[4]
7	IO_L329N_Y	J4
7	IO_VREF_L329P_Y	K6
7	IO_L330N_YY	L8
7	IO_L330P_YY	G2
7	IO_L331N_YY	H3
7	IO_L331P_YY	K7
7	IO_L332N_YY	G3
7	IO_VREF_L332P_YY	J5
7	IO_L333N_Y	L9
7	IO_L333P_Y	H5
7	IO_L334N_Y	J6
7	IO_L334P_Y	H4
7	IO_L335N_Y	G4
7	IO_L335P_Y	K8
7	IO_L336N_YY	J7
7	IO_L336P_YY	F2

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
7	IO_L337N_YY	F3
7	IO_L337P_YY	L10
7	IO_L338N_Y	E1
7	IO_VREF_L338P_Y_Y	H6
7	IO_L339N_Y	G5
7	IO_L339P_Y	E2
7	IO_L340N	K9
7	IO_L340P	D1
7	IO_L341N_Y	E3
7	IO_VREF_L341P_Y	J8
7	IO_L342N_Y	E4
7	IO_L342P_Y	D2
7	IO_L343N_Y	F4
7	IO_L343P_Y	D3
2	CCLK	C31
3	DONE	AM31
NA	DXN	AJ5
NA	DXP	AL5
NA	M0	AK4
NA	M1	AG7
NA	M2	AL3
NA	PROGRAM	AG28
NA	TCK	D5
NA	TDI	C30
2	TDO	K26
NA	TMS	C4
NA	VCCINT	K10
NA	VCCINT	K17
NA	VCCINT	K18
NA	VCCINT	K25
NA	VCCINT	L11
NA	VCCINT	L24
NA	VCCINT	M12

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	VCCINT	M23
NA	VCCINT	N13
NA	VCCINT	N14
NA	VCCINT	N15
NA	VCCINT	N16
NA	VCCINT	N19
NA	VCCINT	N20
NA	VCCINT	N21
NA	VCCINT	N22
NA	VCCINT	P13
NA	VCCINT	P22
NA	VCCINT	R13
NA	VCCINT	R22
NA	VCCINT	T13
NA	VCCINT	T22
NA	VCCINT	U10
NA	VCCINT	U25
NA	VCCINT	V10
NA	VCCINT	V25
NA	VCCINT	W13
NA	VCCINT	W22
NA	VCCINT	Y13
NA	VCCINT	Y22
NA	VCCINT	AA13
NA	VCCINT	AA22
NA	VCCINT	AB13
NA	VCCINT	AB14
NA	VCCINT	AB15
NA	VCCINT	AB16
NA	VCCINT	AB19
NA	VCCINT	AB20
NA	VCCINT	AB21
NA	VCCINT	AB22
NA	VCCINT	AC12
NA	VCCINT	AC23

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	VCCINT	AD24
NA	VCCINT	AD11
NA	VCCINT	AE10
NA	VCCINT	AE17
NA	VCCINT	AE18
NA	VCCINT	AE25
NA	VCCO_0	M17
NA	VCCO_0	L17
NA	VCCO_0	L16
NA	VCCO_0	E10
NA	VCCO_0	C14
NA	VCCO_0	A6
NA	VCCO_0	M13
NA	VCCO_0	M14
NA	VCCO_0	M15
NA	VCCO_0	M16
NA	VCCO_0	L12
NA	VCCO_0	L13
NA	VCCO_0	L14
NA	VCCO_0	L15
NA	VCCO_1	M18
NA	VCCO_1	L18
NA	VCCO_1	L23
NA	VCCO_1	E25
NA	VCCO_1	C21
NA	VCCO_1	A29
NA	VCCO_1	M19
NA	VCCO_1	M20
NA	VCCO_1	M21
NA	VCCO_1	M22
NA	VCCO_1	L19
NA	VCCO_1	L20
NA	VCCO_1	L21
NA	VCCO_1	L22

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	VCCO_2	U24
NA	VCCO_2	U23
NA	VCCO_2	N24
NA	VCCO_2	M24
NA	VCCO_2	K30
NA	VCCO_2	F34
NA	VCCO_2	T23
NA	VCCO_2	T24
NA	VCCO_2	R23
NA	VCCO_2	R24
NA	VCCO_2	P23
NA	VCCO_2	P24
NA	VCCO_2	P32
NA	VCCO_2	N23
NA	VCCO_3	V23
NA	VCCO_3	V24
NA	VCCO_3	Y23
NA	VCCO_3	Y24
NA	VCCO_3	W23
NA	VCCO_3	W24
NA	VCCO_3	AJ34
NA	VCCO_3	AE30
NA	VCCO_3	AC24
NA	VCCO_3	AB23
NA	VCCO_3	AB24
NA	VCCO_3	AA23
NA	VCCO_3	AA24
NA	VCCO_3	AA32
NA	VCCO_4	AD18
NA	VCCO_4	AC18
NA	VCCO_4	AC19
NA	VCCO_4	AC20
NA	VCCO_4	AC21
NA	VCCO_4	AC22
NA	VCCO_4	AP29

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	VCCO_4	AM21
NA	VCCO_4	AK25
NA	VCCO_4	AD19
NA	VCCO_4	AD20
NA	VCCO_4	AD21
NA	VCCO_4	AD22
NA	VCCO_4	AD23
NA	VCCO_5	AC17
NA	VCCO_5	AD17
NA	VCCO_5	AC13
NA	VCCO_5	AC14
NA	VCCO_5	AC15
NA	VCCO_5	AC16
NA	VCCO_5	AP6
NA	VCCO_5	AM14
NA	VCCO_5	AK10
NA	VCCO_5	AD12
NA	VCCO_5	AD13
NA	VCCO_5	AD14
NA	VCCO_5	AD15
NA	VCCO_5	AD16
NA	VCCO_6	V11
NA	VCCO_6	V12
NA	VCCO_6	Y11
NA	VCCO_6	Y12
NA	VCCO_6	W11
NA	VCCO_6	W12
NA	VCCO_6	AJ1
NA	VCCO_6	AE5
NA	VCCO_6	AC11
NA	VCCO_6	AB11
NA	VCCO_6	AB12
NA	VCCO_6	AA3
NA	VCCO_6	AA11
NA	VCCO_6	AA12

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	VCCO_7	U11
NA	VCCO_7	U12
NA	VCCO_7	N12
NA	VCCO_7	M11
NA	VCCO_7	K5
NA	VCCO_7	F1
NA	VCCO_7	T11
NA	VCCO_7	T12
NA	VCCO_7	R11
NA	VCCO_7	R12
NA	VCCO_7	P3
NA	VCCO_7	P11
NA	VCCO_7	P12
NA	VCCO_7	N11
NA	GND	K32
NA	GND	R4
NA	GND	AN1
NA	GND	AM11
NA	GND	AK5
NA	GND	AH28
NA	GND	AD32
NA	GND	AA20
NA	GND	Y20
NA	GND	W19
NA	GND	V19
NA	GND	U20
NA	GND	T20
NA	GND	R19
NA	GND	P19
NA	GND	H8
NA	GND	F12
NA	GND	C2
NA	GND	B1
NA	GND	A7

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	GND	AP1
NA	GND	AN2
NA	GND	AM15
NA	GND	AK17
NA	GND	AH34
NA	GND	AC6
NA	GND	AA21
NA	GND	Y21
NA	GND	W20
NA	GND	V20
NA	GND	U21
NA	GND	T21
NA	GND	R20
NA	GND	P20
NA	GND	H16
NA	GND	F23
NA	GND	C3
NA	GND	B2
NA	GND	A28
NA	GND	AP34
NA	GND	AM3
NA	GND	AL31
NA	GND	AH7
NA	GND	AD3
NA	GND	AA19
NA	GND	Y19
NA	GND	W18
NA	GND	V18
NA	GND	U19
NA	GND	T19
NA	GND	R18
NA	GND	P18
NA	GND	J26
NA	GND	F6
NA	GND	C1

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	GND	C34
NA	GND	A3
NA	GND	AP2
NA	GND	AN3
NA	GND	AM20
NA	GND	AK30
NA	GND	AG8
NA	GND	AC29
NA	GND	Y3
NA	GND	Y32
NA	GND	W21
NA	GND	V21
NA	GND	T8
NA	GND	T27
NA	GND	R21
NA	GND	P21
NA	GND	H19
NA	GND	F29
NA	GND	C11
NA	GND	B3
NA	GND	A32
NA	GND	AP3
NA	GND	AN32
NA	GND	AM24
NA	GND	AJ6
NA	GND	AG16
NA	GND	AA14
NA	GND	Y14
NA	GND	W8
NA	GND	W27
NA	GND	U14
NA	GND	T14
NA	GND	R3
NA	GND	R32
NA	GND	M6

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	GND	H27
NA	GND	E5
NA	GND	C15
NA	GND	B32
NA	GND	A33
NA	GND	AP7
NA	GND	AN33
NA	GND	AM32
NA	GND	AJ12
NA	GND	AG19
NA	GND	AA15
NA	GND	Y15
NA	GND	W14
NA	GND	V14
NA	GND	U15
NA	GND	T15
NA	GND	R14
NA	GND	P14
NA	GND	M29
NA	GND	G1
NA	GND	E18
NA	GND	C20
NA	GND	B33
NA	GND	A34
NA	GND	AP28
NA	GND	AN34
NA	GND	AM33
NA	GND	AJ23
NA	GND	AG27
NA	GND	AA16
NA	GND	Y16
NA	GND	W15
NA	GND	V15
NA	GND	U16
NA	GND	T16

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	GND	R15
NA	GND	P15
NA	GND	L3
NA	GND	G7
NA	GND	E30
NA	GND	C24
NA	GND	B34
NA	GND	AP32
NA	GND	AM1
NA	GND	AM34
NA	GND	AJ29
NA	GND	AF9
NA	GND	AA17
NA	GND	Y17
NA	GND	W16
NA	GND	V16
NA	GND	U17
NA	GND	T17
NA	GND	R16
NA	GND	P16
NA	GND	L32
NA	GND	G28
NA	GND	D4
NA	GND	C32
NA	GND	A1
NA	GND	AP33
NA	GND	AM2
NA	GND	AL4
NA	GND	AH1
NA	GND	AF26
NA	GND	AA18
NA	GND	Y18
NA	GND	W17
NA	GND	V17
NA	GND	U18

Table 6: **FG1156 — XQV2000E**

Bank	Pin Description	Pin #
NA	GND	T18
NA	GND	R17
NA	GND	P17
NA	GND	J9
NA	GND	G34
NA	GND	D31
NA	GND	C33
NA	GND	A2
NA	GND	AB17
NA	GND	AB18
NA	GND	N17
NA	GND	N18
NA	GND	U13
NA	GND	V13
NA	GND	U22
NA	GND	V22

FG1156 Differential Pin Pairs

Virtex-E devices have differential pin pairs that can also provide other functions when not used as a differential pair. The AO column in Table 7 indicates which pin pairs may be used as an asynchronous output with a "√." The "Other Functions" column indicates alternative function(s) that are not available when the pair is used as a differential pair or differential clock.

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
GCLK LVDS					
3	0	E17	C17	NA	IO_DLL_L 42N
2	1	D17	J18	NA	IO_DLL_L 42P
1	5	AL19	AL17	NA	IO_DLL_L 215N
0	4	AH18	AM18	NA	IO_DLL_L 215P
IO LVDS Total Pairs: 344, Asynchronous Output Pairs: 134					
0	0	H9	F7	NA	-
1	0	J10	C5	√	-

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
2	0	D6	E6	√	VREF
3	0	G8	A4	NA	-
4	0	J11	C6	√	-
5	0	F8	G9	√	VREF
6	0	H10	A5	√	-
7	0	B5	D7	NA	-
8	0	E8	K12	NA	-
9	0	F9	B6	NA	-
10	0	C7	G10	√	-
11	0	B7	D8	√	VREF
12	0	C8	H11	NA	-
13	0	B8	E9	√	-
14	0	G11	K13	√	VREF
15	0	F10	A8	NA	-
16	0	H12	C9	√	-
17	0	A9	D10	√	VREF
18	0	A10	F11	NA	-
19	0	C10	K14	NA	-
20	0	G12	H13	√	VREF
21	0	B11	A11	√	-
22	0	D11	E12	NA	-
23	0	C12	G13	√	-
24	0	A12	K15	√	-
25	0	H14	B12	NA	-
26	0	F13	D12	√	-
27	0	B13	A13	√	VREF
28	0	G14	J15	√	-
29	0	F14	C13	NA	-
30	0	D13	H15	NA	-
31	0	K16	A14	NA	-
32	0	B14	E14	√	-
33	0	D14	G15	√	VREF
34	0	D15	J16	NA	-
35	0	B15	F15	√	-

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
36	0	E15	A15	√	-
37	0	A16	G16	NA	-
38	0	J17	F16	√	-
39	0	B16	C16	√	VREF
40	0	A17	H17	NA	-
41	0	B17	G17	NA	VREF
42	1	J18	C17	None	IO_LVDS_DLL
43	1	C18	G18	NA	VREF
44	1	F18	H18	NA	-
45	1	A19	B19	√	VREF
46	1	C19	K19	√	-
47	1	E19	F19	√	-
48	1	J19	G19	√	-
49	1	G20	A20	√	-
50	1	F20	B20	NA	-
51	1	E20	D20	√	VREF
52	1	A21	H20	√	-
53	1	J20	E21	NA	-
54	1	K20	D21	NA	-
55	1	H21	B21	NA	-
56	1	F21	G21	√	-
57	1	B22	A22	√	VREF
58	1	C22	J21	√	-
59	1	G22	D22	NA	-
60	1	A23	K21	√	-
61	1	B23	F22	√	-
62	1	H22	C23	NA	-
63	1	K22	D23	√	-
64	1	J22	A24	√	VREF
65	1	D24	H23	NA	-
66	1	E24	A25	NA	-
67	1	C25	A26	√	VREF
68	1	B26	F24	√	-
69	1	F25	K23	NA	-

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
70	1	H24	C26	√	VREF
71	1	A27	G24	√	-
72	1	G25	B27	NA	-
73	1	C27	E26	√	VREF
74	1	B28	J24	√	-
75	1	H25	K24	NA	-
76	1	F26	D27	NA	-
77	1	C28	G26	NA	-
78	1	J25	E27	√	-
79	1	H26	A30	√	VREF
80	1	B29	G27	√	-
81	1	C29	F27	NA	-
82	1	F28	E28	√	VREF
83	1	B30	L25	√	-
84	1	E29	B31	NA	-
85	1	D30	A31	√	CS
86	2	D32	J27	√	DIN, D0
87	2	E31	F30	√	-
88	2	G29	F32	√	-
89	2	E32	G30	NA	VREF
90	2	M25	G31	NA	-
91	2	L26	D33	NA	-
92	2	D34	H29	√	VREF
93	2	J28	E33	√	-
94	2	H28	H30	√	-
95	2	H32	K28	NA	-
96	2	L27	F33	√	-
97	2	M26	E34	√	-
98	2	H31	G32	√	VREF
99	2	N25	J31	√	-
100	2	J30	G33	√	-
101	2	H34	J29	NA	VREF
102	2	M27	H33	NA	-
103	2	K29	J34	NA	-

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
104	2	L29	J33	√	VREF
105	2	M28	K34	√	-
106	2	N27	L34	NA	-
107	2	K33	P26	√	D1
108	2	R25	M34	√	-
109	2	L31	L33	√	-
110	2	P27	M33	NA	-
111	2	M31	R26	NA	-
112	2	N30	P28	NA	-
113	2	N29	N33	√	VREF
114	2	T25	N34	√	-
115	2	P34	R27	√	-
116	2	P29	P31	NA	-
117	2	P33	T26	√	-
118	2	R34	R28	√	-
119	2	N31	N32	√	D3
120	2	P30	R33	√	-
121	2	R29	T34	√	-
122	2	R30	T30	NA	-
123	2	T28	R31	NA	-
124	2	T29	U27	NA	-
125	2	T31	T33	√	VREF
126	2	U28	T32	√	-
127	2	U29	U33	NA	VREF
128	2	V33	U31	√	-
129	3	V26	V30	NA	VREF
130	3	W34	V28	√	-
131	3	W32	W30	√	VREF
132	3	V29	Y34	NA	-
133	3	W29	Y33	NA	-
134	3	W26	W28	NA	-
135	3	Y31	Y30	√	-
136	3	AA34	W31	√	-
137	3	AA33	Y29	√	VREF

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
138	3	W25	AB34	√	-
139	3	Y28	AB33	√	-
140	3	AA30	Y26	NA	-
141	3	Y27	AA31	√	-
142	3	AA27	AA29	√	-
143	3	AB32	AB29	√	VREF
144	3	AA28	AC34	NA	-
145	3	Y25	AD34	NA	-
146	3	AB30	AC33	NA	-
147	3	AA26	AC32	√	-
148	3	AD33	AB28	√	-
149	3	AE34	AB27	√	D5
150	3	AE33	AC30	√	VREF
151	3	AA25	AE32	NA	-
152	3	AE31	AD29	√	-
153	3	AD31	AF33	√	VREF
154	3	AC28	AF31	NA	-
155	3	AC27	AF32	NA	-
156	3	AE29	AD28	NA	VREF
157	3	AD30	AG32	√	-
158	3	AC26	AH33	√	-
159	3	AD26	AF30	√	VREF
160	3	AC25	AH32	√	-
161	3	AE28	AL34	√	-
162	3	AG30	AD27	NA	-
163	3	AF29	AK34	√	-
164	3	AD25	AE27	√	-
165	3	AJ33	AH31	√	VREF
166	3	AE26	AL33	NA	-
167	3	AF28	AL32	NA	-
168	3	AJ31	AF27	NA	VREF
169	3	AG29	AJ32	√	-
170	3	AK33	AH30	√	-
171	3	AK32	AK31	√	INIT

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
172	4	AP31	AK29	√	-
173	4	AP30	AN31	NA	-
174	4	AH27	AN30	√	-
175	4	AM30	AK28	√	VREF
176	4	AG26	AN29	NA	-
177	4	AF25	AM29	√	-
178	4	AL29	AL28	√	VREF
179	4	AE24	AN28	√	-
180	4	AJ27	AH26	NA	-
181	4	AG25	AK27	NA	-
182	4	AM28	AF24	NA	-
183	4	AJ26	AP27	√	-
184	4	AK26	AN27	√	VREF
185	4	AE23	AM27	NA	-
186	4	AL26	AP26	√	-
187	4	AN26	AJ25	√	VREF
188	4	AG24	AP25	NA	-
189	4	AF23	AM26	√	-
190	4	AJ24	AN25	√	VREF
191	4	AE22	AM25	NA	-
192	4	AK24	AH23	NA	-
193	4	AF22	AP24	√	VREF
194	4	AL24	AK23	√	-
195	4	AG22	AN23	NA	-
196	4	AP23	AM23	√	-
197	4	AH22	AP22	√	-
198	4	AL23	AF21	NA	-
199	4	AL22	AJ22	√	-
200	4	AK22	AM22	√	VREF
201	4	AG21	AJ21	√	-
202	4	AP21	AE20	NA	-
203	4	AH21	AL21	NA	-
204	4	AN21	AF20	NA	-
205	4	AK21	AP20	√	-

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
206	4	AE19	AN20	√	VREF
207	4	AG20	AL20	NA	-
208	4	AH20	AK20	√	-
209	4	AN19	AJ20	√	-
210	4	AF19	AP19	NA	-
211	4	AM19	AH19	√	-
212	4	AJ19	AP18	√	VREF
213	4	AF18	AP17	NA	-
214	4	AJ18	AL18	NA	VREF
215	5	AM18	AL17	None	IO_LVDS_DLL
216	5	AH17	AM17	NA	VREF
217	5	AJ17	AG17	NA	-
218	5	AP16	AL16	√	VREF
219	5	AJ16	AM16	√	-
220	5	AK16	AP15	NA	-
221	5	AL15	AH16	√	-
222	5	AN15	AF16	√	-
223	5	AP14	AE16	NA	-
224	5	AK15	AJ15	√	VREF
225	5	AH15	AN14	√	-
226	5	AK14	AG15	NA	-
227	5	AM13	AF15	NA	-
228	5	AG14	AP13	NA	-
229	5	AE14	AE15	√	-
230	5	AN13	AG13	√	VREF
231	5	AH14	AP12	√	-
232	5	AJ14	AL14	NA	-
233	5	AF13	AN12	√	-
234	5	AF14	AP11	√	-
235	5	AN11	AH13	NA	-
236	5	AM12	AL12	√	-
237	5	AJ13	AP10	√	VREF
238	5	AK12	AM10	NA	-
239	5	AP9	AK11	NA	-

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
240	5	AL11	AL10	√	VREF
241	5	AE13	AM9	√	-
242	5	AF12	AP8	NA	-
243	5	AL9	AH11	√	VREF
244	5	AF11	AN8	√	-
245	5	AM8	AG11	NA	-
246	5	AL8	AK9	√	VREF
247	5	AH10	AN7	√	-
248	5	AE12	AJ9	NA	-
249	5	AM7	AL7	NA	-
250	5	AG10	AN6	NA	-
251	5	AK8	AH9	√	-
252	5	AP5	AJ8	√	VREF
253	5	AE11	AN5	√	-
254	5	AF10	AM6	NA	-
255	5	AL6	AG9	√	VREF
256	5	AH8	AP4	√	-
257	5	AN4	AJ7	NA	-
258	5	AM5	AK6	√	-
259	6	AF8	AH6	√	-
260	6	AK3	AE9	√	-
261	6	AL2	AD10	√	-
262	6	AH4	AL1	NA	VREF
263	6	AK1	AG6	NA	-
264	6	AK2	AF7	NA	-
265	6	AG5	AJ3	√	VREF
266	6	AJ2	AD9	√	-
267	6	AH2	AC10	√	-
268	6	AF5	AH3	NA	-
269	6	AG3	AE8	√	-
270	6	AG2	AE7	√	-
271	6	AG1	AF6	√	VREF
272	6	AG4	AC9	√	-
273	6	AF3	AE6	√	-

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
274	6	AF4	AF1	NA	VREF
275	6	AF2	AB10	NA	-
276	6	AE1	AC8	NA	-
277	6	AE3	AD5	√	VREF
278	6	AD1	AC7	√	-
279	6	AD2	AD6	NA	-
280	6	AC1	AB8	√	VREF
281	6	AC2	AC5	√	-
282	6	AC3	AA9	√	-
283	6	AD4	AC4	√	-
284	6	AB6	AA8	NA	-
285	6	Y10	AB1	NA	-
286	6	AA7	AB2	NA	-
287	6	AA1	AA4	√	VREF
288	6	AB4	Y9	√	-
289	6	Y8	AA2	√	-
290	6	AA5	AA6	NA	-
291	6	Y7	AB3	√	-
292	6	W10	Y1	√	-
293	6	Y2	Y5	√	VREF
294	6	W2	W9	√	-
295	6	Y4	W7	√	-
296	6	Y6	W1	NA	-
297	6	W3	W6	NA	-
298	6	W4	V9	NA	-
299	6	V1	W5	√	VREF
300	6	U2	V7	√	-
301	6	U1	V6	NA	VREF
302	7	U4	U9	√	-
303	7	U5	U7	NA	VREF
304	7	U6	U3	√	-
305	7	T6	T3	√	VREF
306	7	T4	T9	NA	-
307	7	R1	T5	NA	-

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
308	7	T10	R6	NA	-
309	7	R5	R2	√	-
310	7	P5	P1	√	VREF
311	7	P2	R8	√	-
312	7	N1	R9	√	-
313	7	R10	P4	NA	-
314	7	N2	P8	√	-
315	7	P7	P6	√	-
316	7	N4	M1	√	VREF
317	7	N3	N6	NA	-
318	7	M2	P9	NA	-
319	7	M3	N7	NA	-
320	7	M4	P10	√	-
321	7	N8	L1	√	-
322	7	N9	L2	√	-
323	7	K1	M7	√	VREF
324	7	L4	M8	NA	-
325	7	L5	J1	√	-
326	7	K3	J2	√	VREF
327	7	J3	L7	NA	-
328	7	H2	M9	NA	-
329	7	K6	J4	NA	VREF
330	7	G2	L8	√	-
331	7	K7	H3	√	-
332	7	J5	G3	√	VREF
333	7	H5	L9	√	-
334	7	H4	J6	√	-
335	7	K8	G4	NA	-
336	7	F2	J7	√	-
337	7	L10	F3	√	-
338	7	H6	E1	√	VREF
339	7	E2	G5	NA	-
340	7	D1	K9	NA	-

Table 7: **FG1156 Differential Pin Pair Summary: XQV2000E**

Pair	Bank	P Pin	N Pin	AO	Other Functions
341	7	J8	E3	NA	VREF
342	7	D2	E4	√	-
343	7	D3	F4	√	-

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
05/19/03	1.0	Initial Xilinx release.
07/29/04	1.1	• Removed CB228 and HQ240 package pinout information (not offered). • Added “VREF” to pin description of pin B15 in package BG432 (XQV600E).